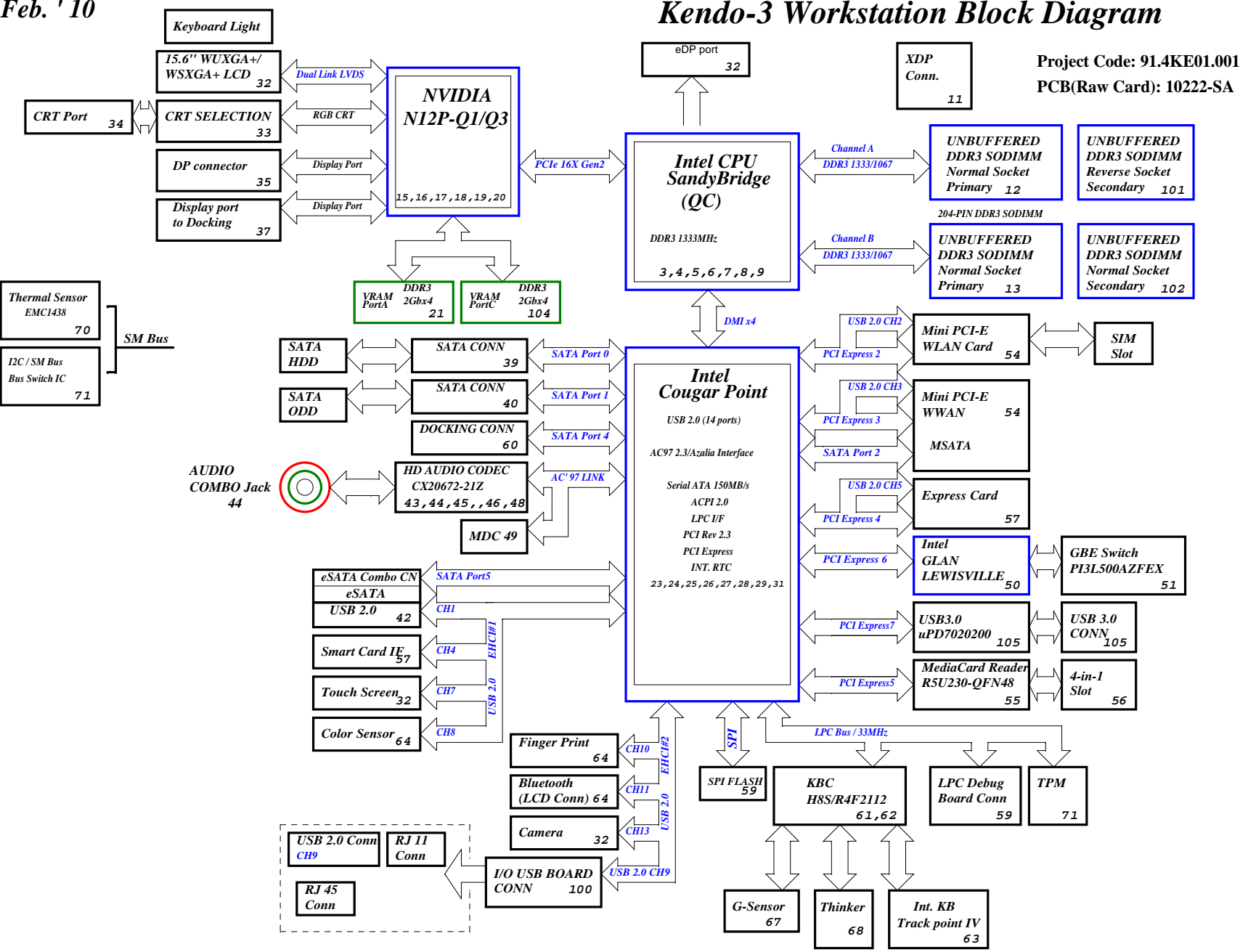


Feb. '10

# Kendo-3 Workstation Block Diagram

Project Code: 91.4KE01.001  
PCB(Raw Card): 10222-SA



**PCB Layer Stackup**

- L1: TOP
- L2: Signal 1
- L3: GND
- L4: Signal 2
- L5: VCC
- L6: GND
- L7: Signal 3
- L8: GND
- L9: Signal 4
- L10: BOTTOM

**Battery Charger/Selector**  
BQ24742RHDR 78

INPUTS	OUTPUTS
DOCK_PWR20_F	M-BAT-PWR
	S-BAT-PWR

**System DC/DC**  
TPS51222RTV 82

VINT20	VCC5M
	VCC3M

**CPU DC/DC**  
VT1317MFQX/VT1317SFCX 79

VINT20	VCCFCUCORE
--------	------------

**GFXCORE\_D**  
ISL6282HRTZ 83

VINT20	VCCGFXCORE
--------	------------

**VCC1R5VIDEO**  
MAX8792ETD 88

VCC5M	VCC1R5VIDEO
-------	-------------

**VCC1R5A/DDR3\_REF**  
VCC0R75B  
TPS51116RGER 86

VCC5M	DDR3_VREF
	VCC0R75B
	VCC1R5A

**VCC1R8B**  
TPS62290DRVR 89

VCC3M	VCC5M
	VCC1R8B

**VCC1R1B\_VTT**  
VCC1R0SLAN  
VT358/VT357 85

VINT20	VCC1R1B_VTT
VCC5M	VCC1R0SLAN

BOM

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Title: **Block Diagram**

Size: Custom Document Number: **Kendo-3 WS** Rev: SA

Date: Tuesday, December 07, 2010 Sheet 1 of 107



From Cougar Point



To Cougar Point



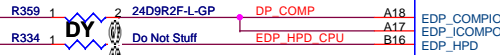
To Cougar Point



From Cougar Point



VCC1R05B\_VTT\_CPU



- × C15 EDP\_AUX
- × D15 EDP\_AUX#
- × C17 EDP\_TX0
- × F16 EDP\_TX1
- × C16 EDP\_TX2
- × G15 EDP\_TX3
- × C18 EDP\_TX#0
- × E16 EDP\_TX#1
- × D16 EDP\_TX#2
- × F15 EDP\_TX#3

SKT8A

SANDY

DMI

Intel(R) FDI

PCI EXPRESS\* - GRAPHICS

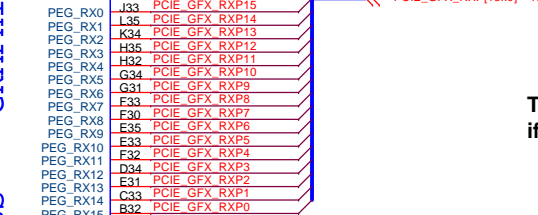
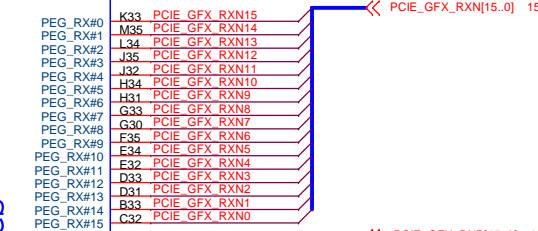
edp

SANDY

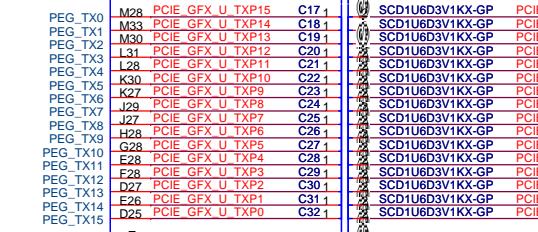
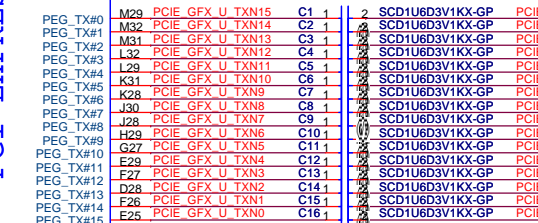
1 OF 9



VCC1R05B\_VTT\_CPU



These PEG interface is left as NC, if external GFX is not mounted..



BOM

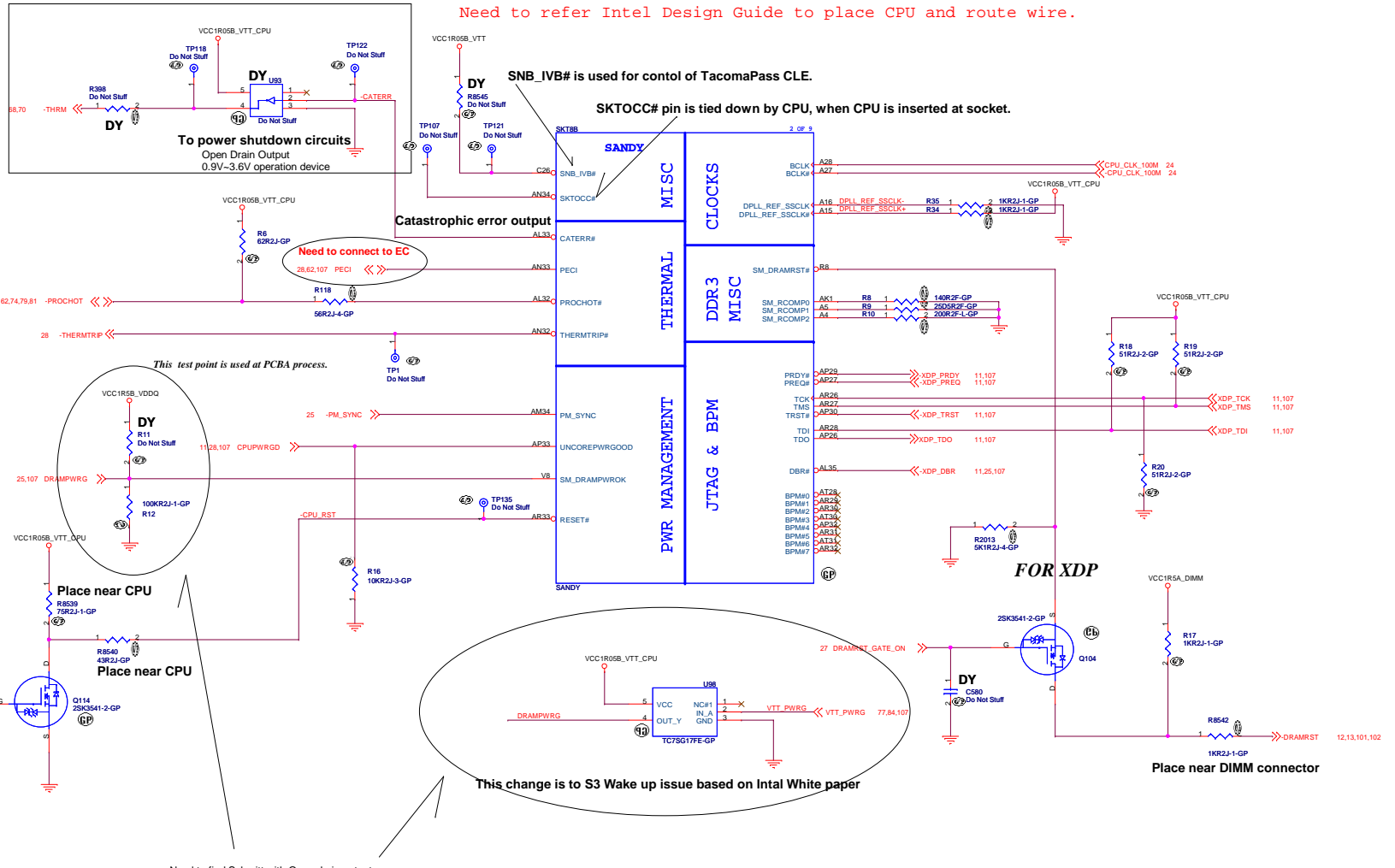
**緯創資通 Wistron Corporation**  
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Title: **CPU(17):DMI/PEG/FDI**

Size A3 Document Number **Kendo-3 WS** Rev SA

Date: Tuesday, December 07, 2010 Sheet 3 of 107

Need to refer Intel Design Guide to place CPU and route wire.



Need to find Schmitt with Open drain output

This change is to S3 Wake up issue based on Intel White paper



Should be add pulldown 1K based on configuration specification.

When PEG Lane reversible function is used,  
CFG2 should have pull down.

eDP Function is used, CFG4 port should be tie Down.  
If not, this port can be left as floating.

When PCIe Port Bifurcation function is used,  
CFG5 & 6 should have pull down.

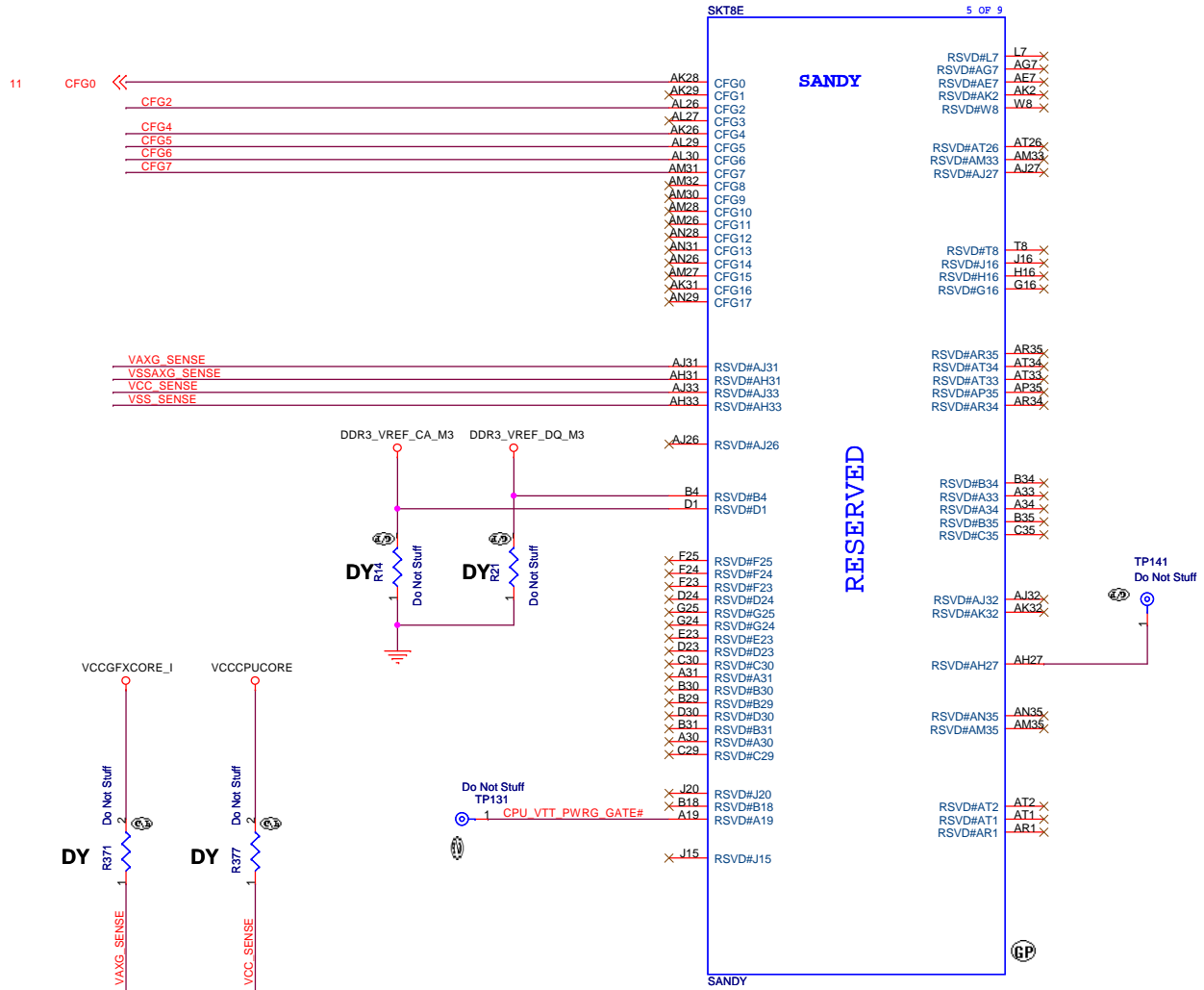
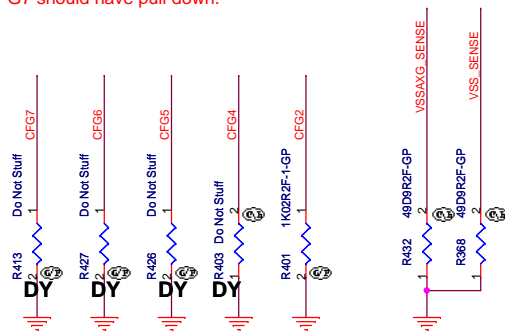
Low/Low : x8 , x4 and x4

Low/High : Reserved

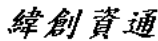
High/Low : x8 and x8

High/High : x16

When PEG Defer training function is used,  
CFG7 should have pull down.

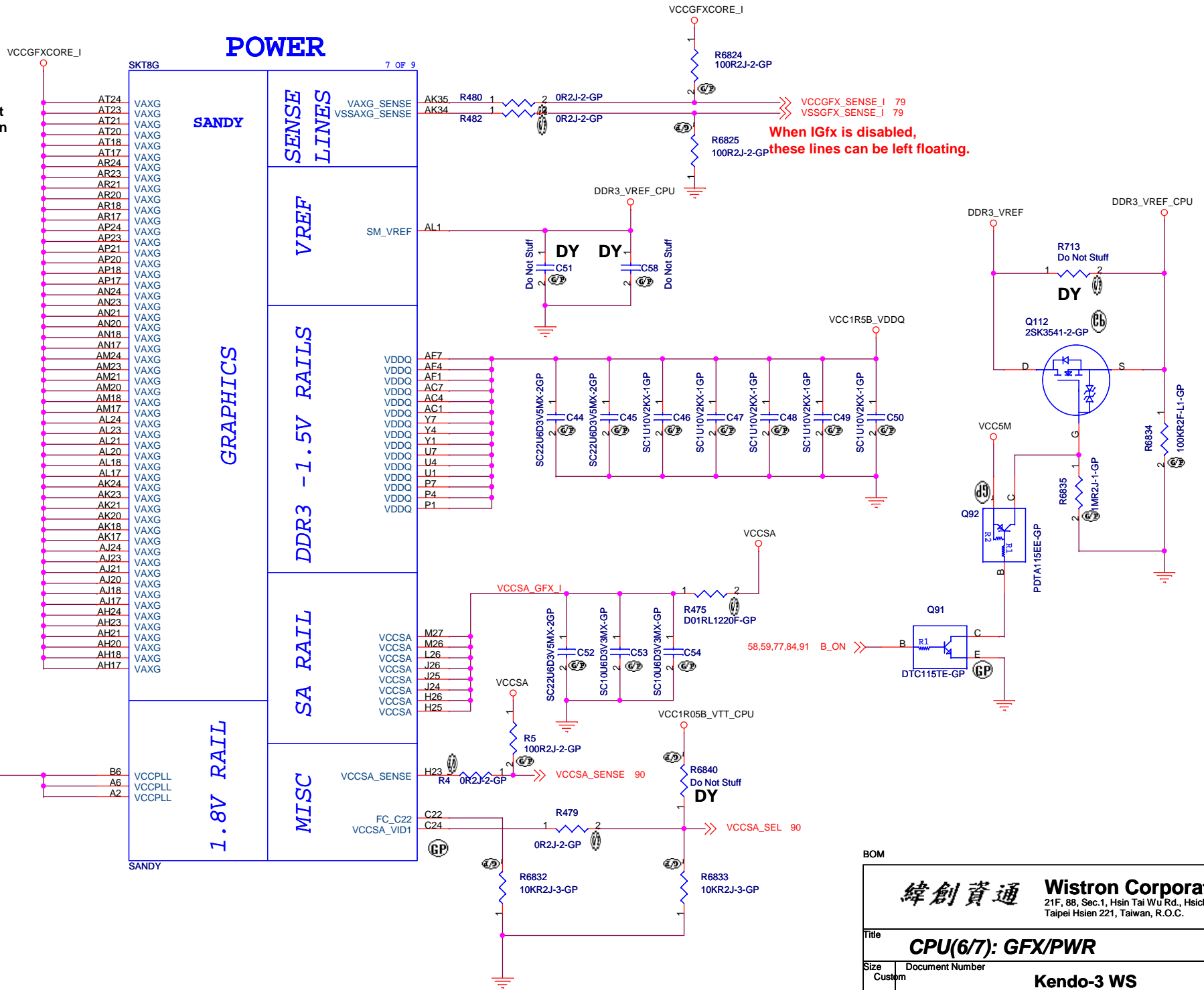


BOM

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Title	
<b>CPU(4/7): CFG/RSVD</b>	
Size	Document Number
A3	Kendo-3 WS
Date:	Rev
Tuesday, December 07, 2010	SA
Sheet	of
6	107



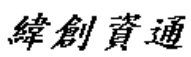
Caps on Page.8 are not required. It's enough on Page.81.



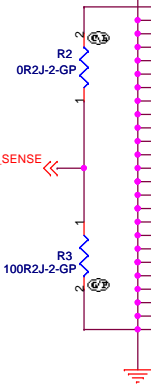
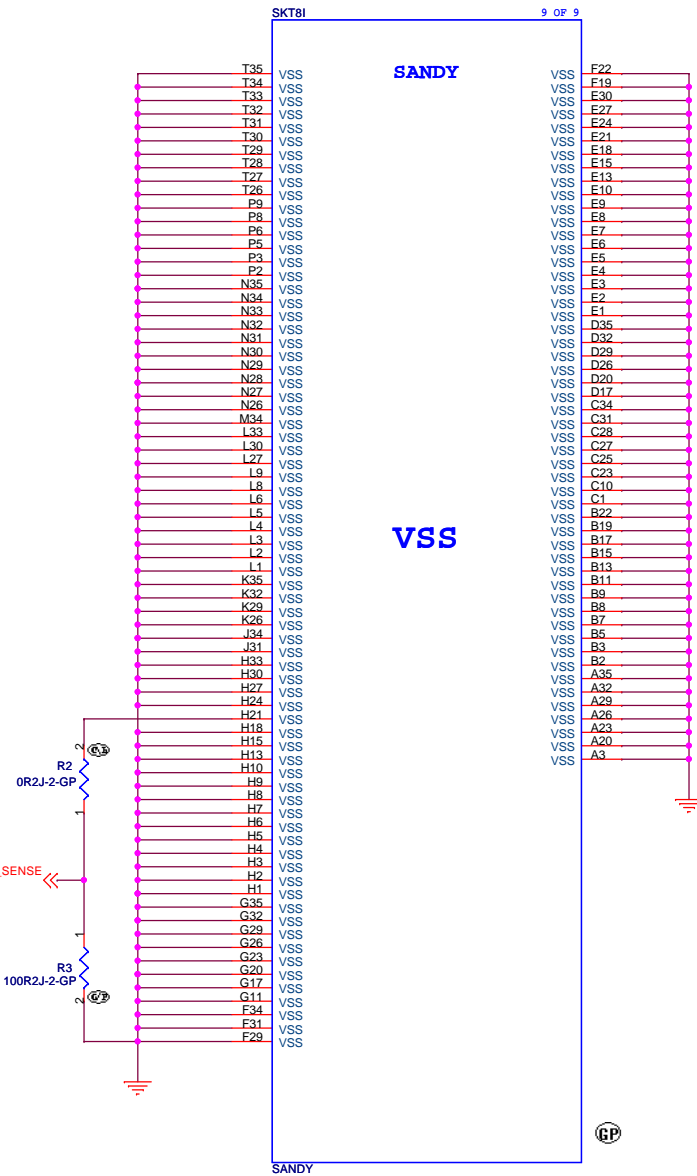
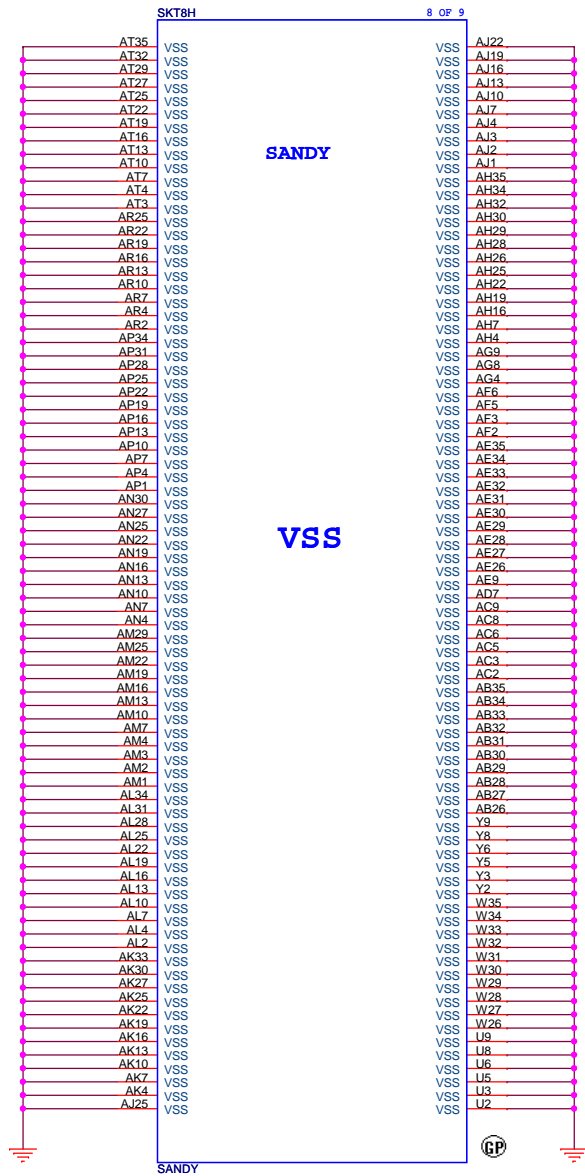
When IGfx is disabled, these lines can be left floating.

58,59,77,84,91 B\_ON

BOM

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<b>Title</b> <b>CPU(6/7): GFX/PWR</b>	
<b>Size</b> Custom	<b>Document Number</b> <b>Kendo-3 WS</b>
<b>Date:</b> Tuesday, December 07, 2010	<b>Rev</b> <b>SA</b>
<b>Sheet</b> 8 <b>of</b> 107	





**BLANK**

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Taipei Hsien 221, Taiwan, R.O.C.

Title

**BLANK**

Size  
A3

Document Number

**Kendo-3 WS**

Rev  
**SA**

Date: Tuesday, December 07, 2010

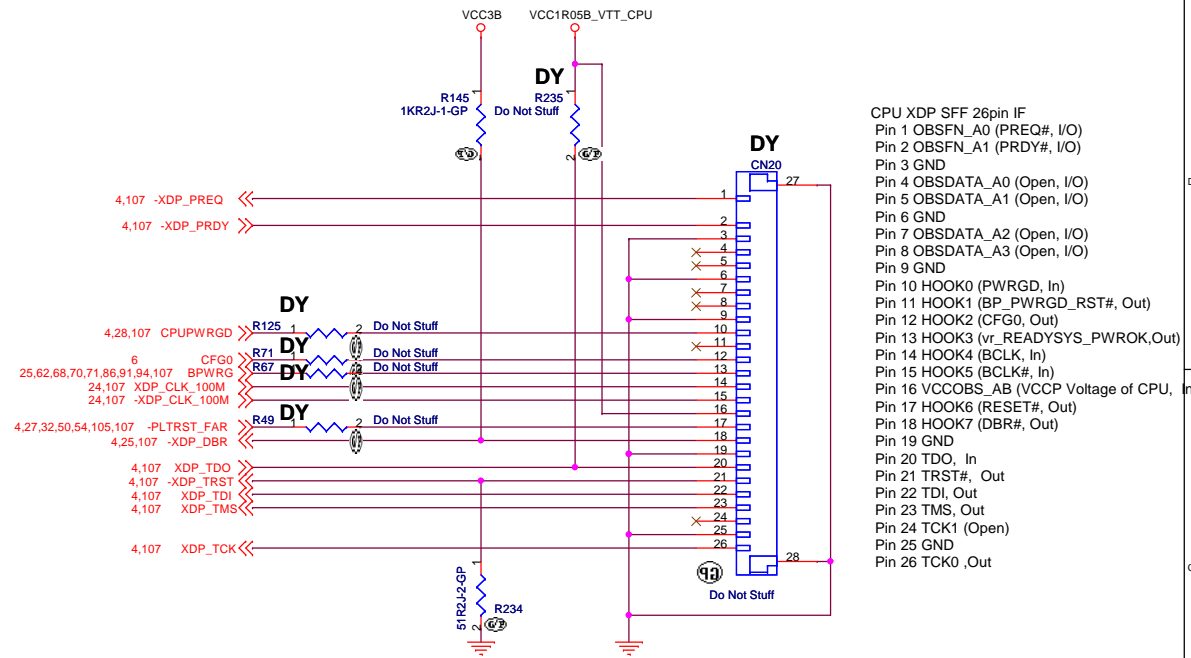
Sheet 10 of 107

SIGNAL	REF DES	ENABLE	DISABLE
TDO	R235	ASM	NO_ASM
TRST#	R234	ASM	ASM
DBRST#	R145	ASM	ASM
RESET#	R49	ASM	NO_ASM
CFG0	R71	ASM	NO_ASM
PWRGD	R125	ASM	NO_ASM
BPWRG	R67	ASM	NO_ASM
	CN20	ASM	NO_ASM

↑  
LOGIC

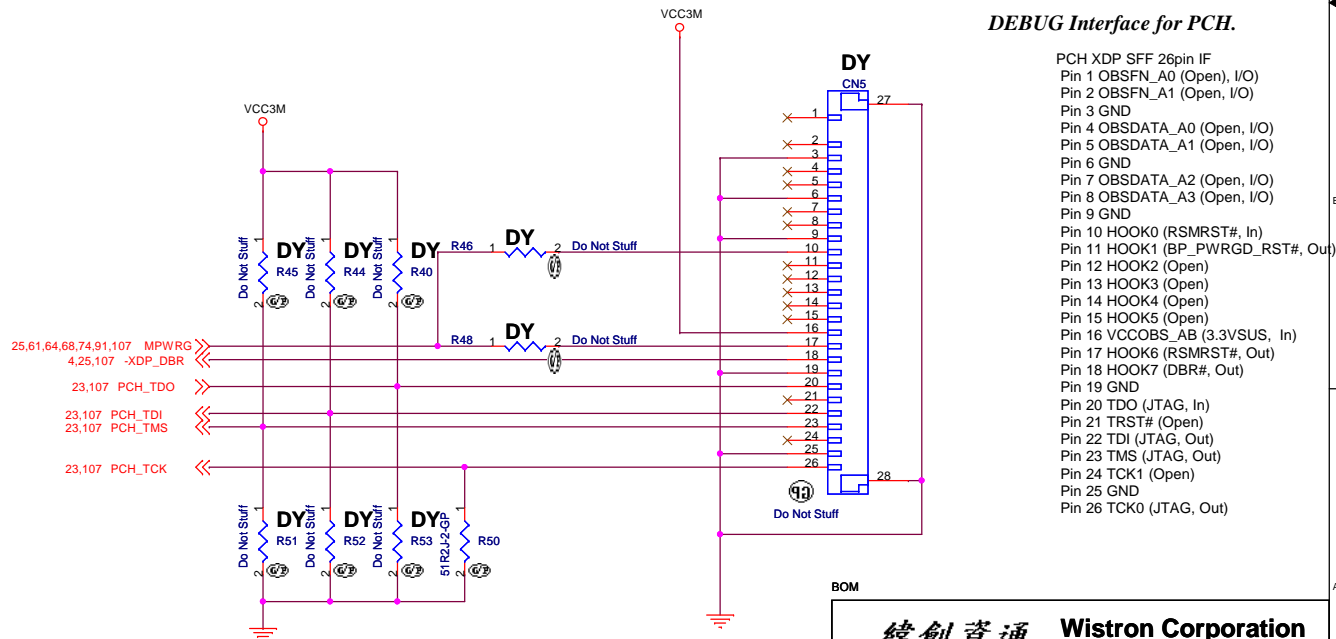
SIGNAL	REF DES	ENABLE	DISABLE
TDO	R40 R53	220 100	NO_ASM NO_ASM
TMS	R45 R51	220 100	NO_ASM NO_ASM
TDI	R44 R52	220 100	NO_ASM NO_ASM
TCK	R50	51	51
MPWRG	R46 R48	ASM ASM	NO_ASM NO_ASM
	CN5	ASM	NO_ASM

↑  
LOGIC



- CPU XDP SFF 26pin IF
- Pin 1 OBSFN\_A0 (PREQ#, I/O)
  - Pin 2 OBSFN\_A1 (PRDY#, I/O)
  - Pin 3 GND
  - Pin 4 OBSDATA\_A0 (Open, I/O)
  - Pin 5 OBSDATA\_A1 (Open, I/O)
  - Pin 6 GND
  - Pin 7 OBSDATA\_A2 (Open, I/O)
  - Pin 8 OBSDATA\_A3 (Open, I/O)
  - Pin 9 GND
  - Pin 10 HOOK0 (PWRGD, In)
  - Pin 11 HOOK1 (BP\_PWRGD\_RST#, Out)
  - Pin 12 HOOK2 (CFG0, Out)
  - Pin 13 HOOK3 (vr\_READYSYS\_PWROK, Out)
  - Pin 14 HOOK4 (BCLK, In)
  - Pin 15 HOOK5 (BCLK#, In)
  - Pin 16 VCCOBS\_AB (VCCP Voltage of CPU, In)
  - Pin 17 HOOK6 (RESET#, Out)
  - Pin 18 HOOK7 (DBR#, Out)
  - Pin 19 GND
  - Pin 20 TDO, In
  - Pin 21 TRST#, Out
  - Pin 22 TDI, Out
  - Pin 23 TMS, Out
  - Pin 24 TCK1 (Open)
  - Pin 25 GND
  - Pin 26 TCK0 ,Out

In production, All of parts should be not moounted except of pulldown 51 ohm on TCK.

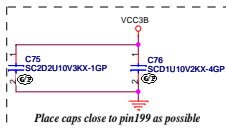
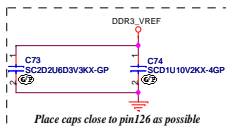
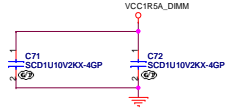
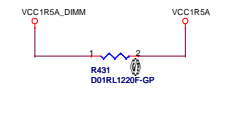


**DEBUG Interface for PCH.**

- PCH XDP SFF 26pin IF
- Pin 1 OBSFN\_A0 (Open, I/O)
  - Pin 2 OBSFN\_A1 (Open, I/O)
  - Pin 3 GND
  - Pin 4 OBSDATA\_A0 (Open, I/O)
  - Pin 5 OBSDATA\_A1 (Open, I/O)
  - Pin 6 GND
  - Pin 7 OBSDATA\_A2 (Open, I/O)
  - Pin 8 OBSDATA\_A3 (Open, I/O)
  - Pin 9 GND
  - Pin 10 HOOK0 (RSMRST#, In)
  - Pin 11 HOOK1 (BP\_PWRGD\_RST#, Out)
  - Pin 12 HOOK2 (Open)
  - Pin 13 HOOK3 (Open)
  - Pin 14 HOOK4 (Open)
  - Pin 15 HOOK5 (Open)
  - Pin 16 VCCOBS\_AB (3.3VSUS, In)
  - Pin 17 HOOK6 (RSMRST#, Out)
  - Pin 18 HOOK7 (DBR#, Out)
  - Pin 19 GND
  - Pin 20 TDO (JTAG, In)
  - Pin 21 TRST# (Open)
  - Pin 22 TDI (JTAG, Out)
  - Pin 23 TMS (JTAG, Out)
  - Pin 24 TCK1 (Open)
  - Pin 25 GND
  - Pin 26 TCK0 (JTAG, Out)

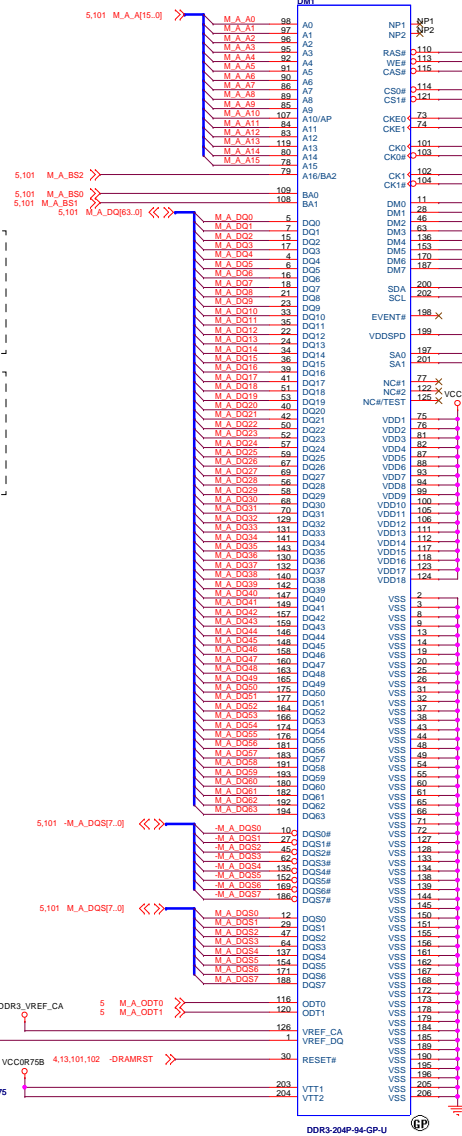
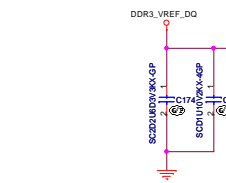
BOM

<b>緯創資通</b>		<b>Wistron Corporation</b>	
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
<b>XDP CONNECTOR</b>			
Size	Document Number		Rev
A3		<b>Kendo-3 WS</b>	SA
Date:	Tuesday, December 07, 2010	Sheet	11 of 107



Place caps close to pin126 as possible

Place caps close to pin199 as possible



5.101 -M\_A\_DQS[7..0]

5.101 M\_A\_DQS[7..0]

5 M\_A\_ODT0

5 M\_A\_ODT1

4.13.101.102 -DRAMRST

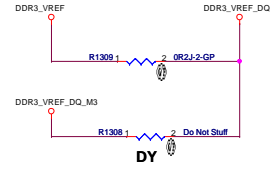
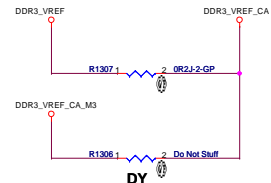
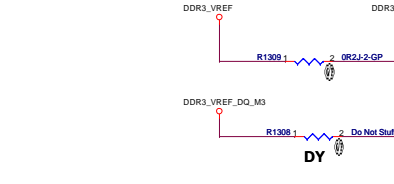
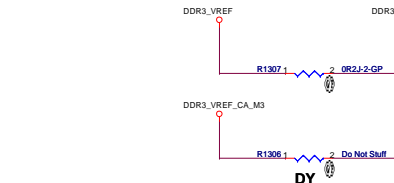
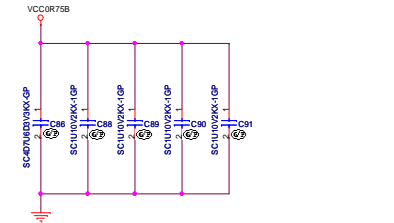
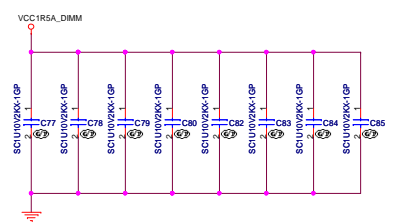
DDR3-204P-94-GP-U



SMB\_DATA\_3B 13.71.101.102

SMB\_CLK\_3B 13.71.101.102

VCC1R5A\_DMM



SPD Address : 50h

This connector should be placed on far side from CPU.

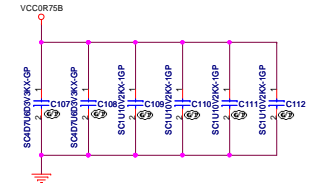
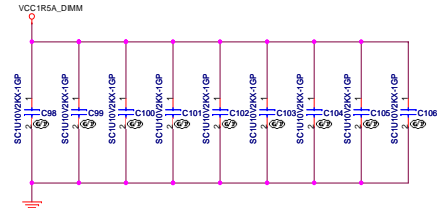
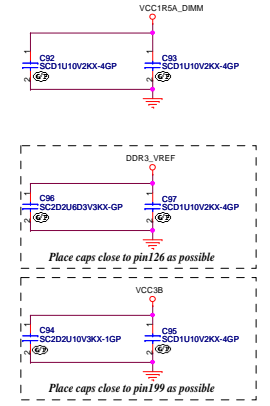
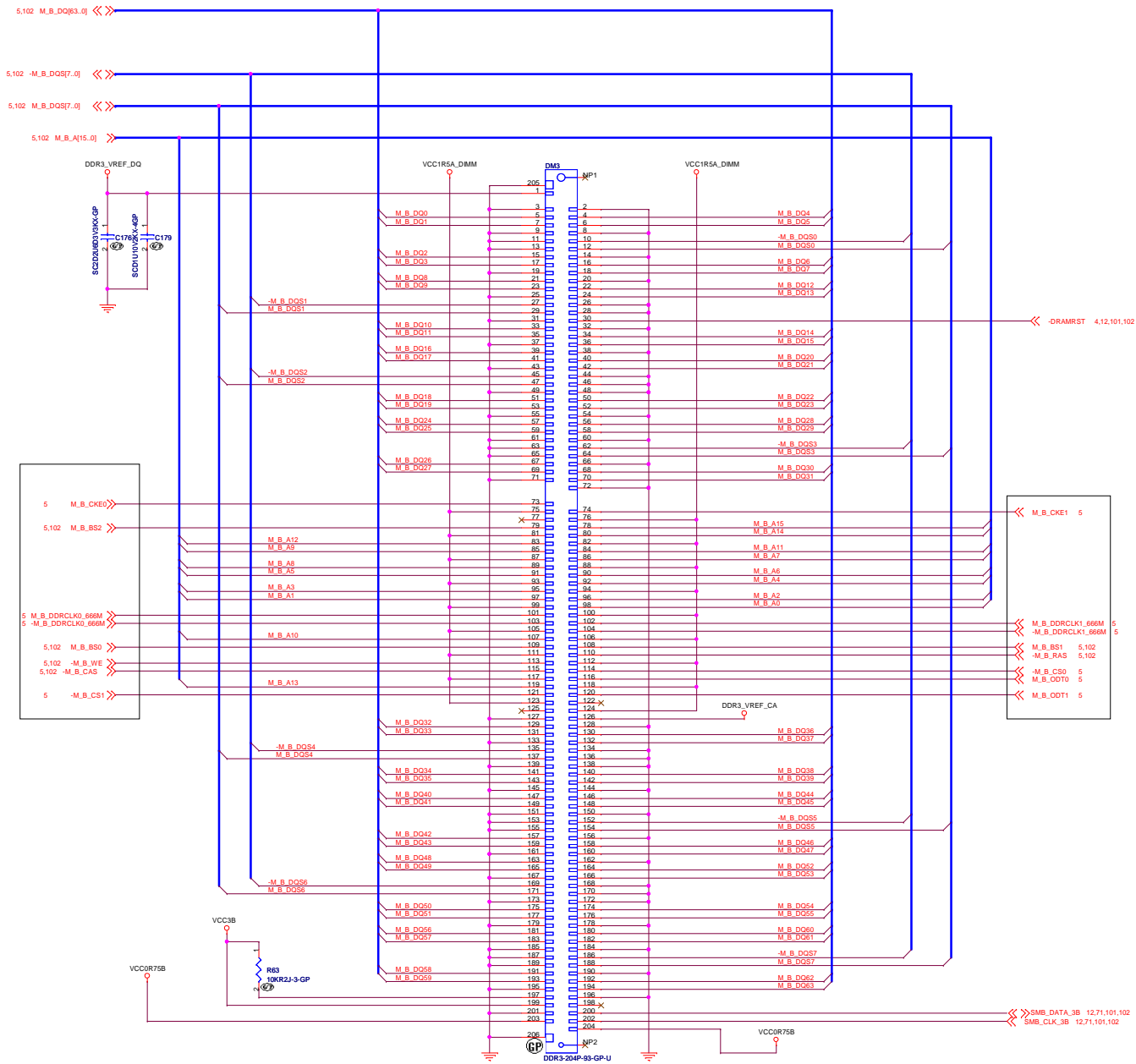
BOM

**緯創資通** Wistron Corporation  
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Title: **DDR3 SODIMM CH-A Primary**

Size A2 Document Number **Kendo-3 WS** Rev SA

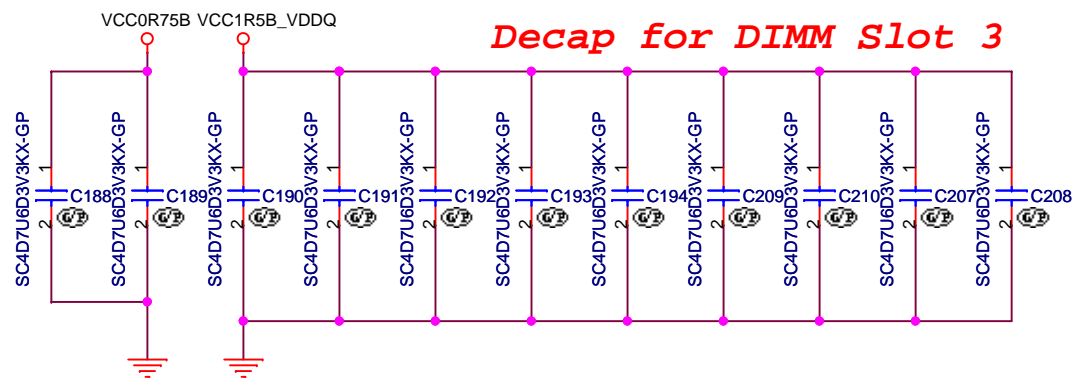
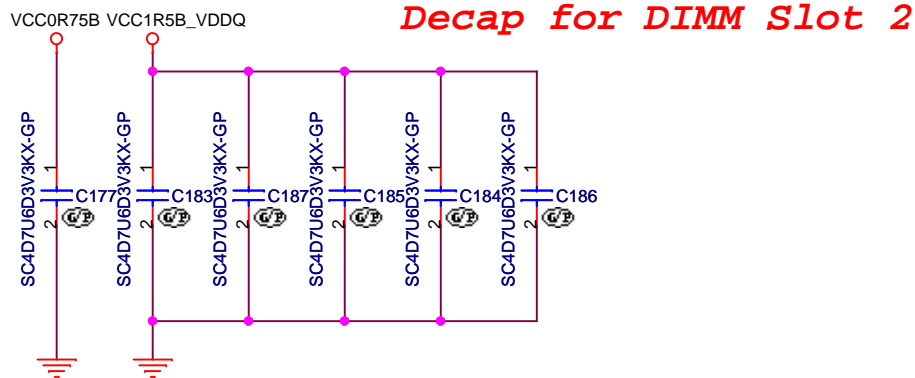
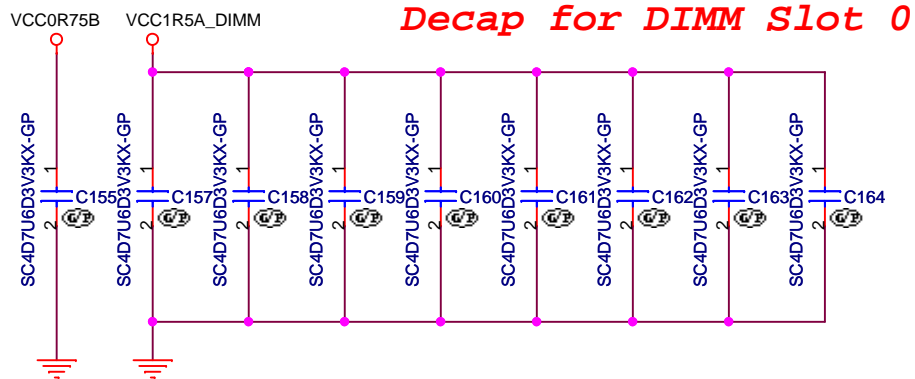
Date: Tuesday, December 07, 2010 Sheet 12 of 107



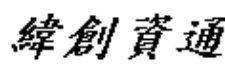
- 5 M.B. CKE0
- 5.102 M.B. BS2
- 5 M.B. DDRCLK0\_666M
- 5 -M.B. DDRCLK0\_666M
- 5.102 M.B. BS0
- 5.102 -M.B. WE
- 5.102 -M.B. CAS
- 5 -M.B. CS1

- M.B. CKE1 5
- M.B. A15
- M.B. A14
- M.B. A11
- M.B. A7
- M.B. A6
- M.B. A4
- M.B. A2
- M.B. A0
- M.B. DDRCLK1\_666M 5
- M.B. DDRCLK1\_666M 5
- M.B. BS1 5.102
- M.B. RAS 5.102
- M.B. CS0 5
- M.B. ODT0 5
- M.B. ODT1 5

SPD Address : 51h  
 This connector should be placed on far side from CPU.



BOM

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<b>DECAP For DIMMs</b>	
Title <b>DECAP For DIMMs</b>	Document Number <b>Kendo-3 WS</b>
Size A4	Rev <b>SA</b>
Date: Tuesday, December 07, 2010 Sheet 14 of 107	



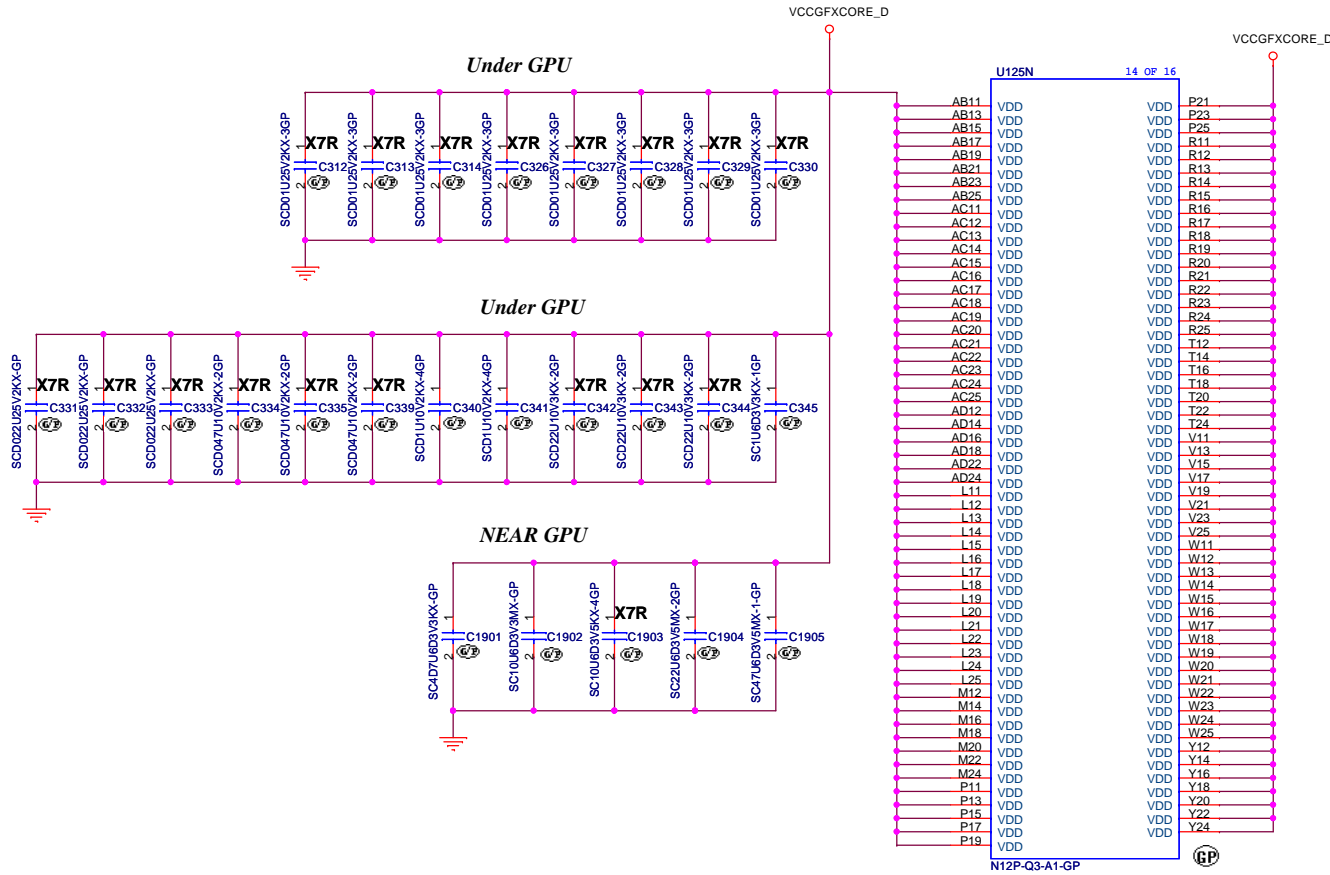




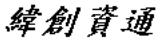


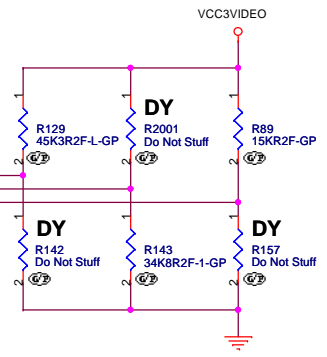
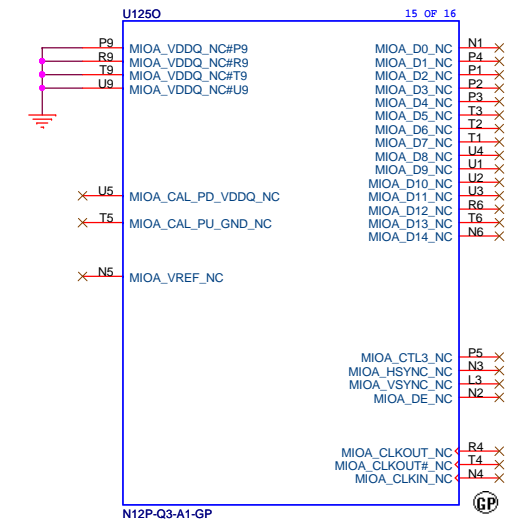
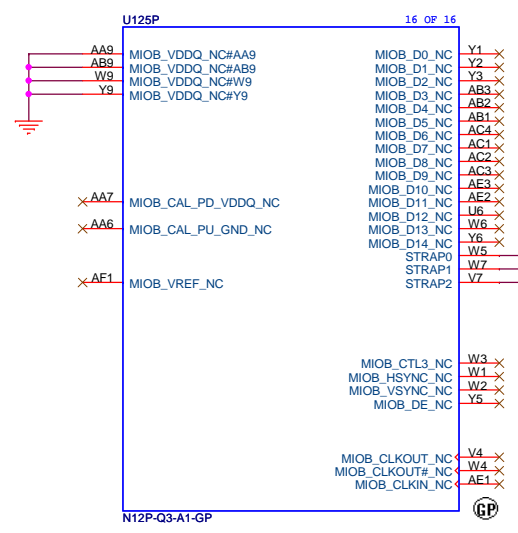
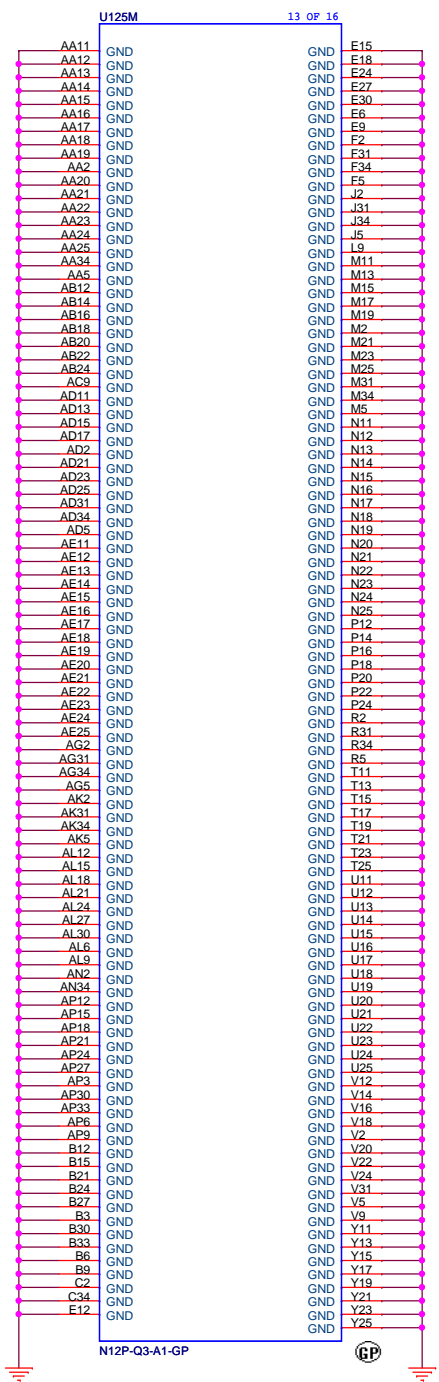


# EDP 50A (TDP 37W)



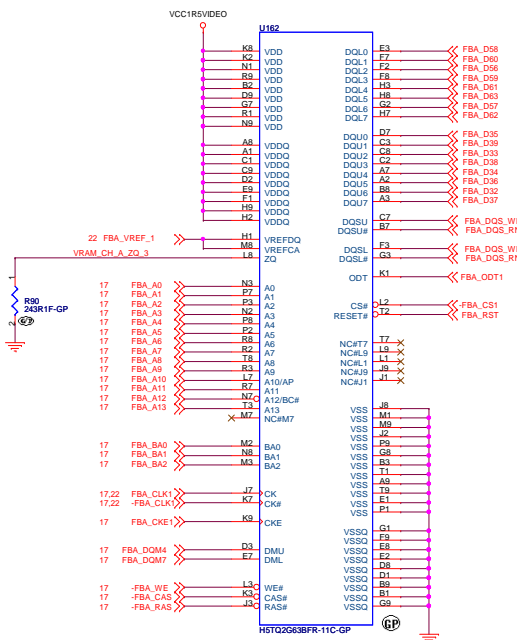
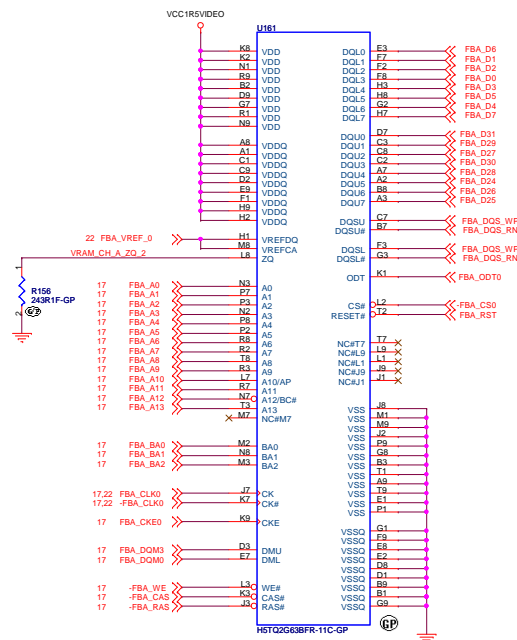
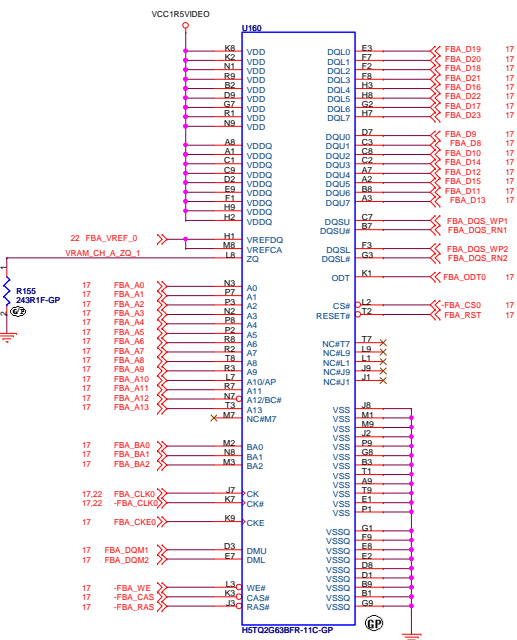
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 <b>Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>Title</b> <b>N12P-Q1/Q3 (5/6): POWER</b>		
<b>Size</b> A3	<b>Document Number</b> <b>Kendo-3 WS</b>	<b>Rev</b> <b>SA</b>
<b>Date:</b> Tuesday, December 07, 2010		<b>Sheet</b> 19 <b>of</b> 107

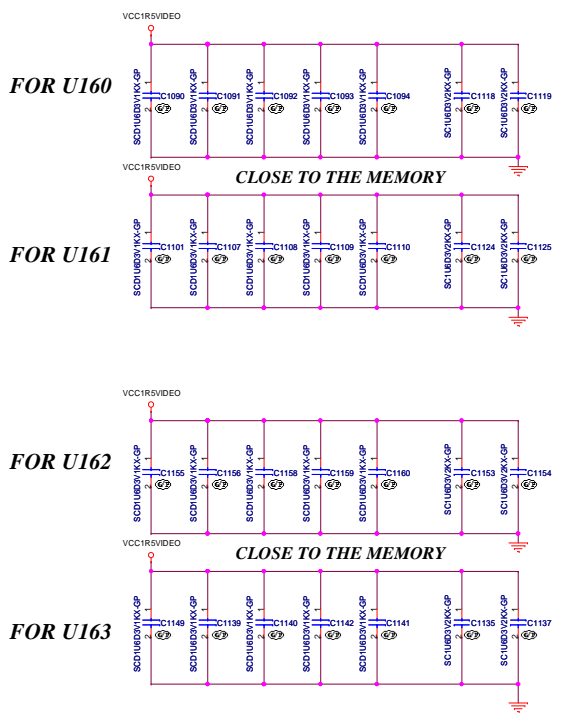


BOM

<b>Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>Title</b> N12P-Q1/Q3 (6/6): GND		
<b>Size</b> A3	<b>Document Number</b> <b>Kendo-3 WS</b>	<b>Rev</b> <b>SA</b>
<b>Date:</b> Tuesday, December 07, 2010 <b>Sheet</b> 20 <b>of</b> 107		



FB CMD mapping Mode D-N12x



DG requires 4x0.1uF and 8x1.0uF per VRAM chip

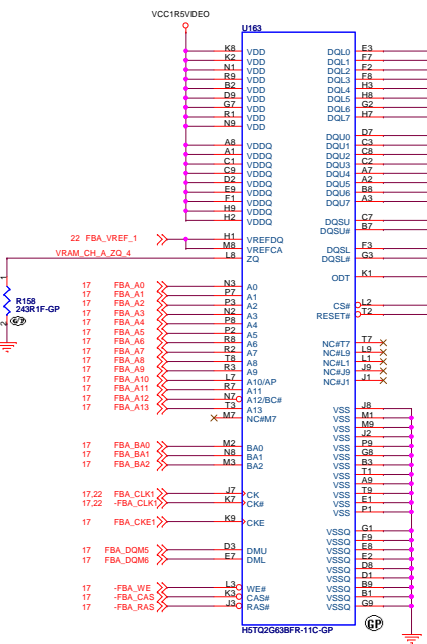
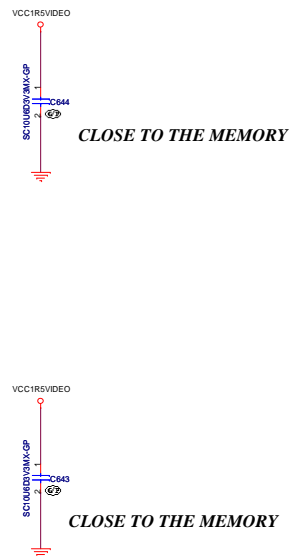
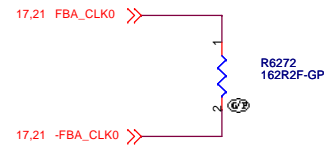
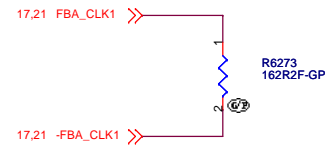
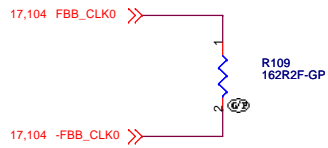
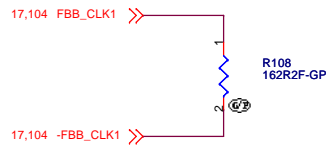
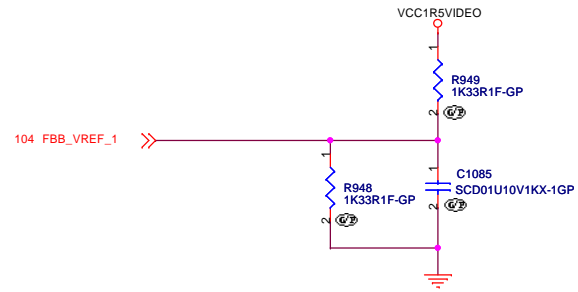
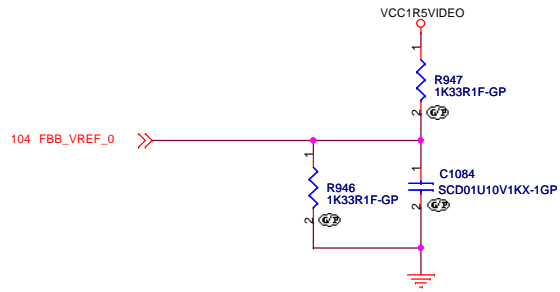
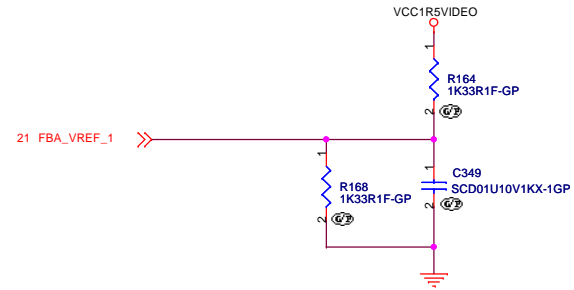
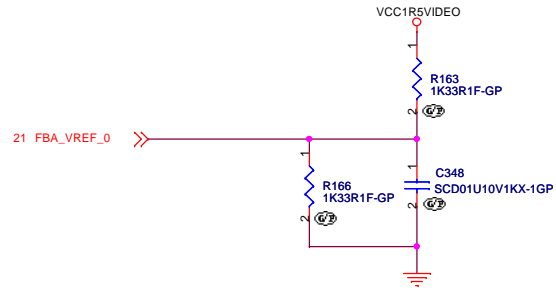


TABLE  
DDR3 VIDEO MEMORY FOR N12P-Q1 AND N12P-Q3

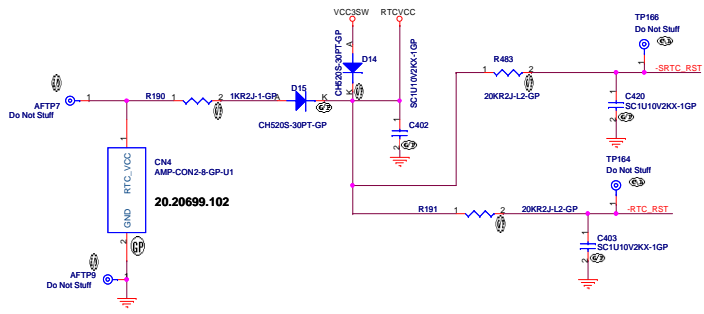
	HYNIX 2GBITS (128MX16)	SAMSUNG 2GBITS (128MX16)
U160 U12	HSTQ2G63BFR-11C	K4W2G1646C-HC11
U161 U13		
U162 U14		
U163 U15		



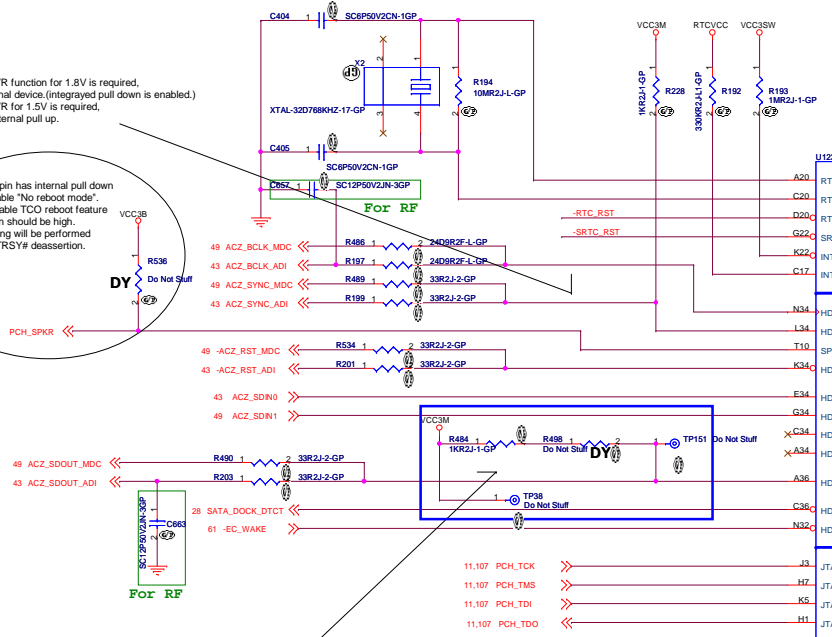
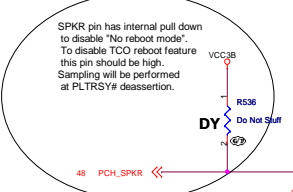
**FBCLK Termination**

BOM

<b>緯創資通</b>		<b>Wistron Corporation</b>	
		<small>21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.</small>	
<b>Title DYNAMIC MEMORY TERMINATION</b>			
Size A3	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>	
Date: Tuesday, December 07, 2010		Sheet 22	of 107



When On die VR function for 1.8V is required, No need External device, (integrated pull down is enabled.)  
 When On die VR for 1.5V is required, Need to add external pull up.



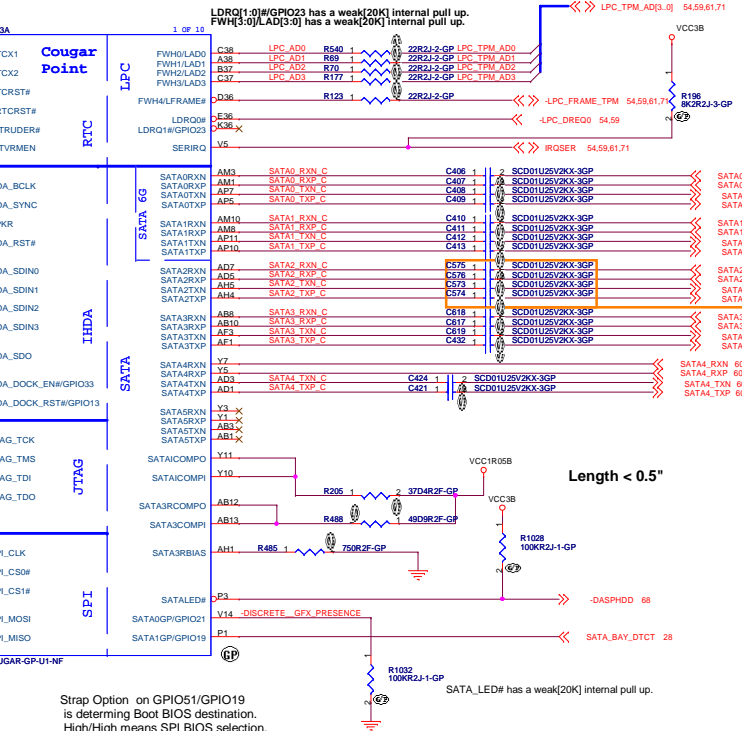
- 11.107 PCH\_TCK >>>
- 11.107 PCH\_TMS >>>
- 11.107 PCH\_TDI >>>
- 11.107 PCH\_TDO >>>
- 59 SPL\_CLK >>>
- 59 -SPL\_CS0 >>>
- 59 -SPL\_CS1# >>>
- 59 SPL\_MOSI >>>
- 59 SPL\_MISO >>>

Flash Descriptor Security Strap  
 This pin has internal pull down.  
 Asserting High at HDA\_SDO on rising of power OK, ME feature will be disabled.

SPI\_MOSI => High : iTPM Enable  
 SPI\_MOSI has a weak(20K) internal pull down.

- INTVRMEM pin should have pull up resistor to enable integrated 1.05V VRM.
- HDA\_SYNC has a weak(20K) internal pull down. The pin is low, 1.8V is provided by on die PLL VR. The pin is high, 1.5V is provided by on die PLL VR.
- HDA\_BCLK has a weak(20K) internal pull down.
- HDA\_RST# has a weak(20K) internal pull down.
- HDA\_SDN[3:0] has a weak(20K) internal pull down.
- SPKR has weak(20K) internal pull down. If external pull up is applied, PCH will disable TCO timer system reboot function.

HDA\_SDO has a weak(20K) internal pull up.  
 Low : the Flash Descriptor Security will be overridden.  
 High : The security measures defined in the Flash descriptor will be in effect.



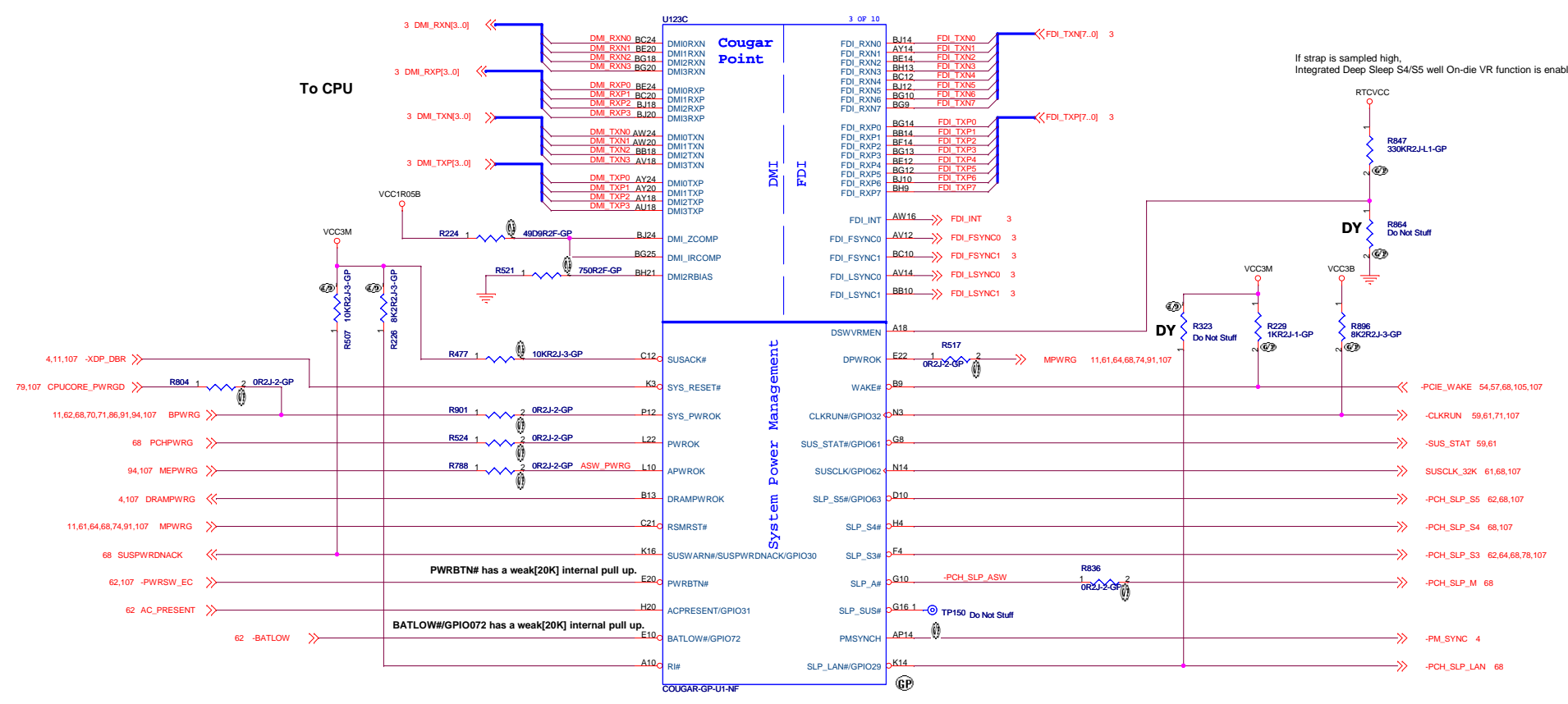
Strap Option on GPIO51/GPIO19 is determining Boot BIOS destination. High/High means SPI BIOS selection. Pull high at P.36

- SATA0: To HDD Bay
- SATA1: To ODD Bay
- SATA2: To MiniCard
- SATA3: To eSATA Combo Connector
- SATA4: To Docking Connector
- SATA5: Reserved
- Note: SATA4 and SATA5 support Multiplier

Place Near CN12







If strap is sampled high, Integrated Deep Sleep S4/S5 well On-die VR function is enabled.

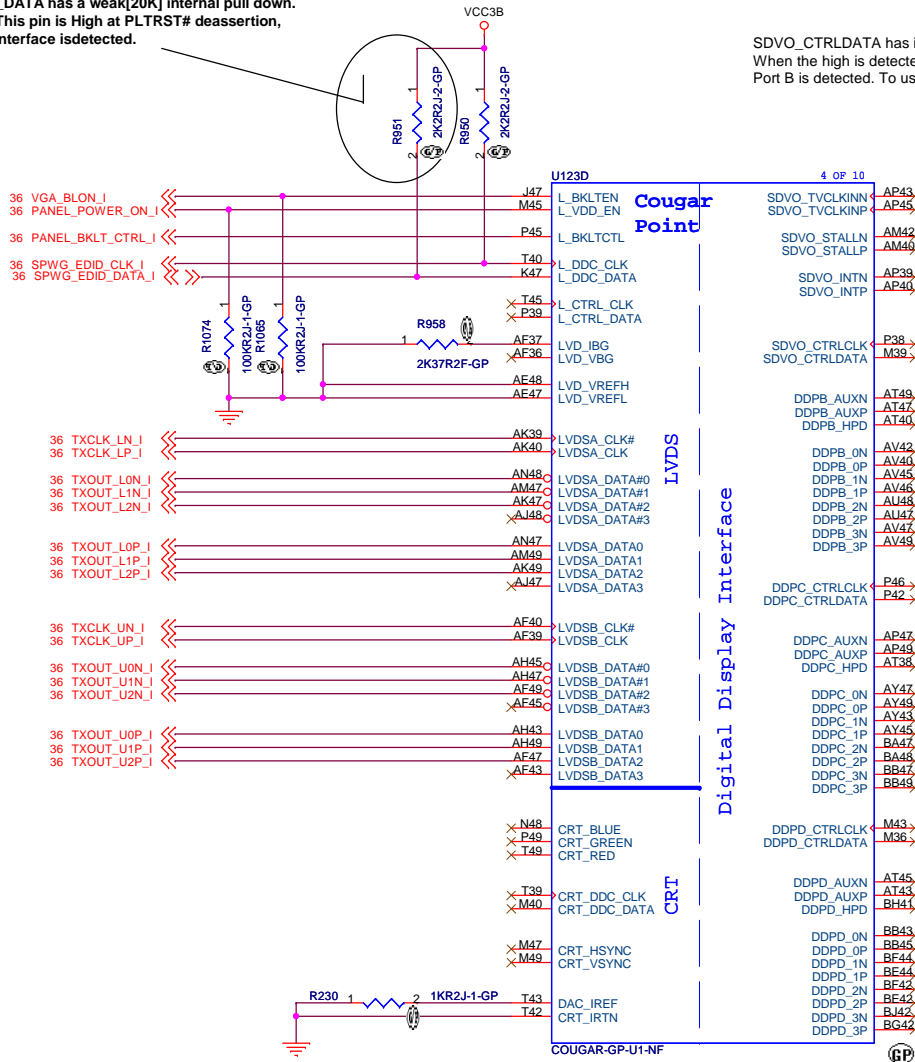
BOM

緯創資通		Wistron Corporation	
21F, 8B, Sec.1, Hsien Tai Wu Rd., Hsichü, Taipei Hsien 221, Taiwan, R.O.C.		21F, 8B, Sec.1, Hsien Tai Wu Rd., Hsichü, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
PCH (3/8):DMI/FDI/PM			
Size	Document Number	Rev	SA
Custom	Kendo-3 WS		
Date:	Tuesday, December 07, 2010	Sheet	25 of 107

L\_DDC\_DATA has a weak[20K] internal pull down.  
When This pin is High at PLTRST# deassertion,  
LVDS interface isdetected.

SDVO\_CTRLDATA has internal pull down.  
When the high is detected at PLTRST# deassertion,  
Port B is detected. To use Port B, need to add external pull up.

DDPC\_CTRLDATA has internal pull down.  
When the high is detected at PLTRST# deassertion,  
Port C is detected. To use Port C, need to add external pull up.



DDPD\_CTRLDATA has internal pull down.  
When the high is detected at PLTRST# deassertion,  
Port D is detected. To use Port D, need to add external pull up.

BOM

<b>緯創資通 Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>Title PCH (4/8):LVDS/CRT/DDI</b>	
Size A3	Document Number <b>Kendo-3 WS</b>
Date: Tuesday, December 07, 2010	Rev SA
Sheet 26	of 107

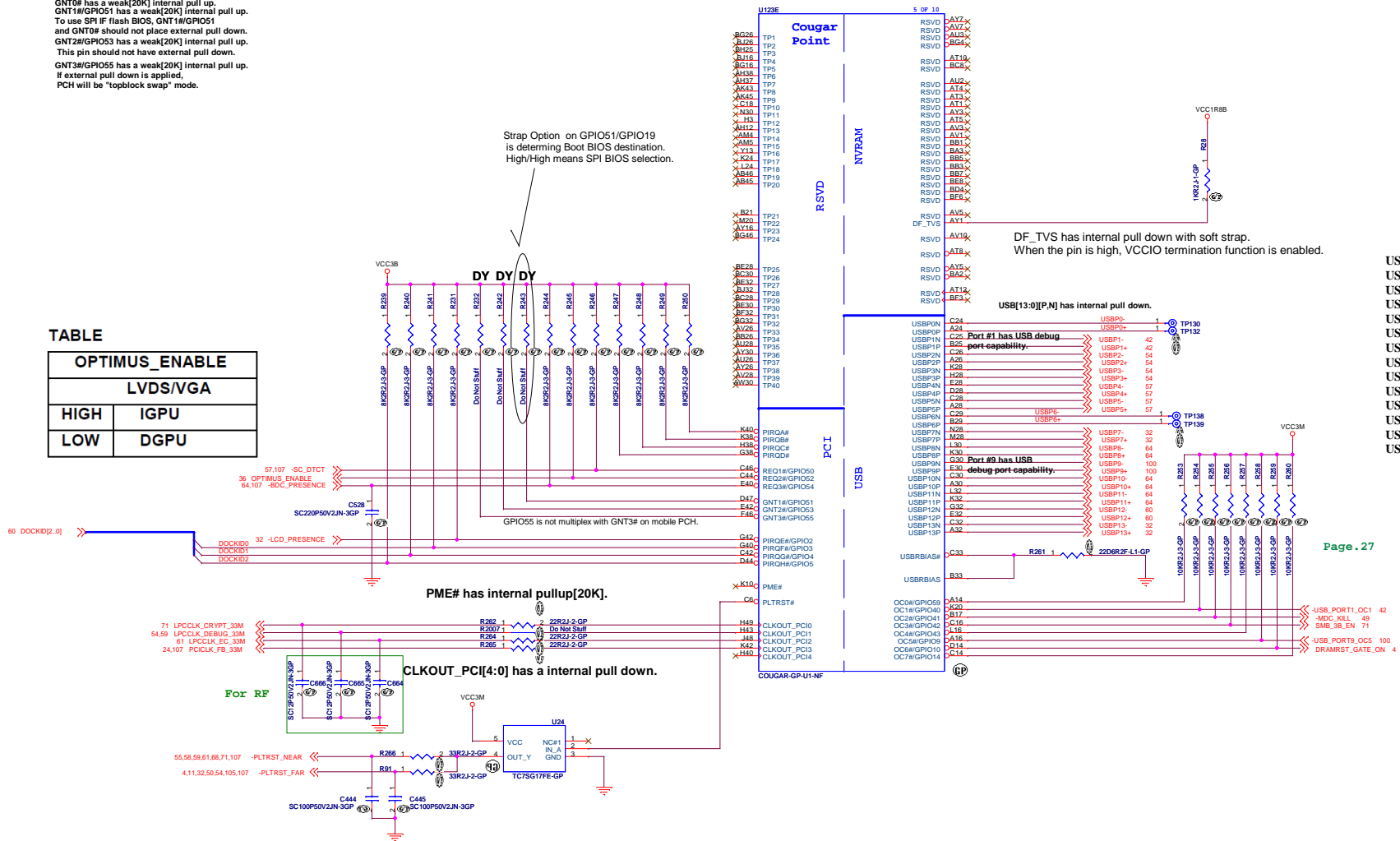
Because PCI IF is not used, ADX.C/BEX and GNTx are left as NC.

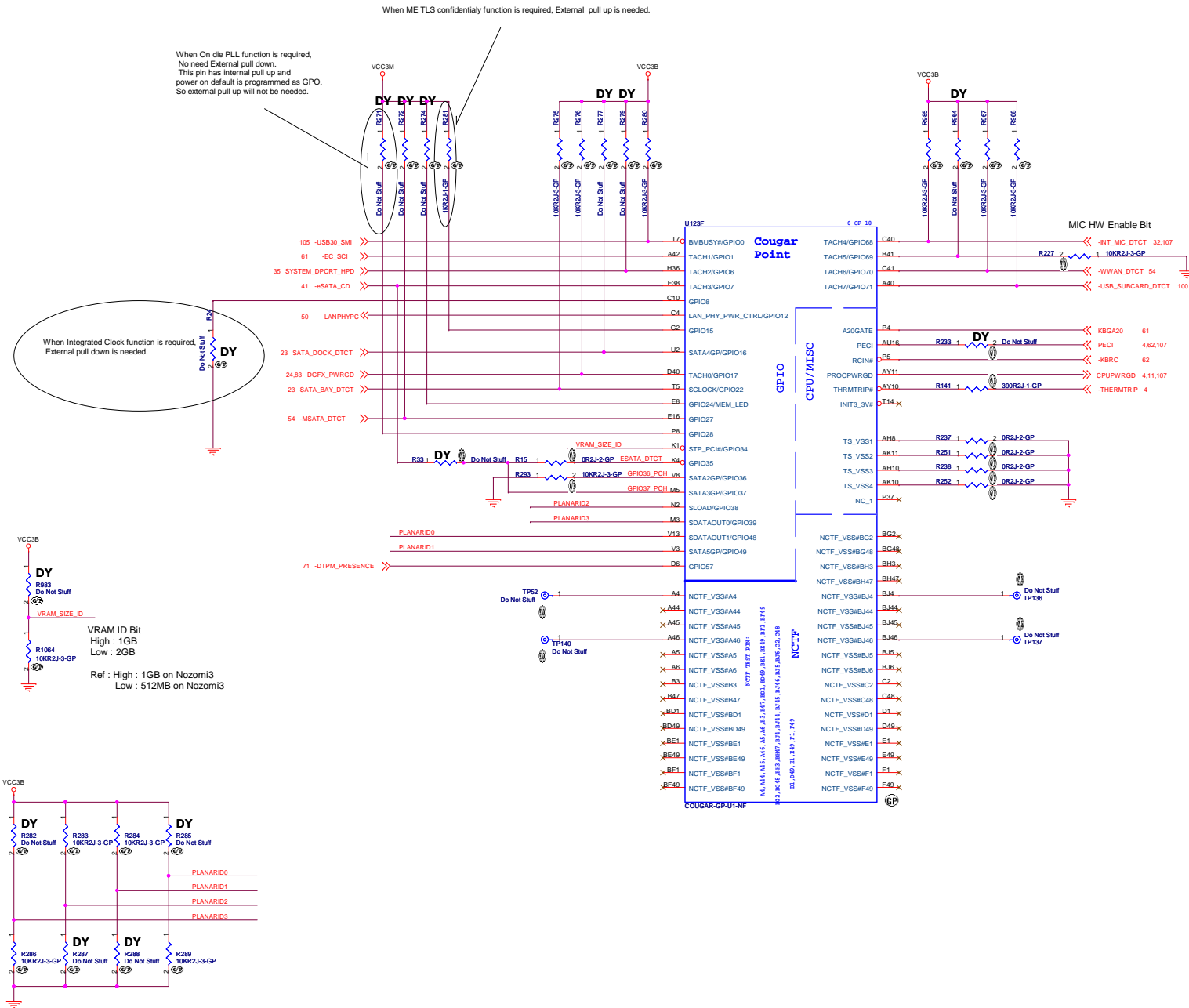
GNT0# has a weak[20K] internal pull up.  
 GNT1#/GPIO51 has a weak[20K] internal pull up.  
 To use SPI IF flash BIOS, GNT1#/GPIO51 and GNT0# should not place external pull down.  
 GNT2#/GPIO53 has a weak[20K] internal pull up.  
 This pin should not have external pull down.  
 GNT3#/GPIO55 has a weak[20K] internal pull up.  
 If external pull down is applied, PCH will be "topblock swap" mode.

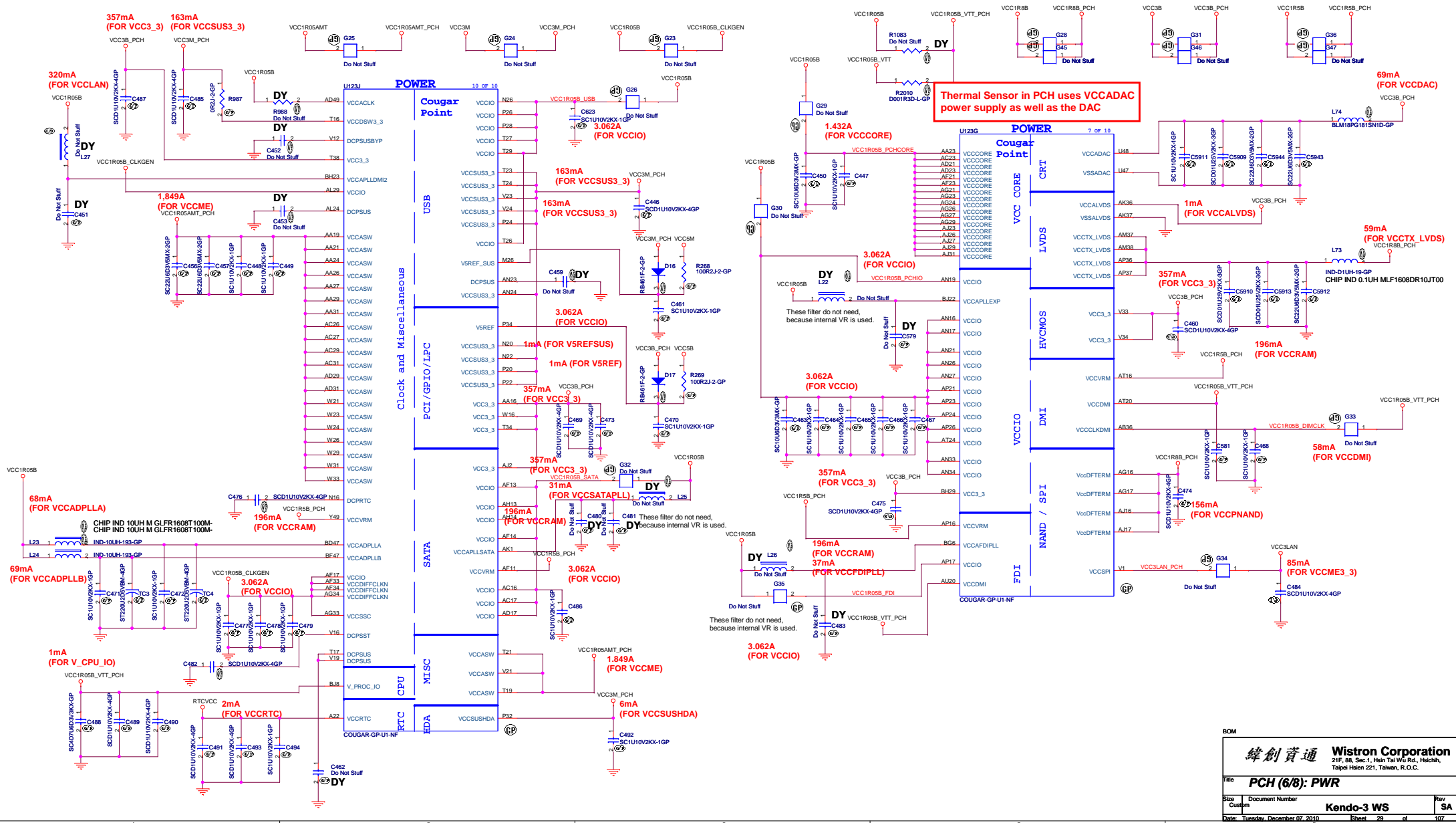
Strap Option on GPIO51/GPIO19 is determining Boot BIOS destination.  
 High/High means SPI BIOS selection.

TABLE

OPTIMUS_ENABLE	
LVDS/VGA	
HIGH	IGPU
LOW	DGPU







Thermal Sensor in PCH uses VCCADAC power supply as well as the DAC

BOM	
緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsinchu, Taipei Hsein 221, Taiwan, R.O.C.	
Title <b>PCH (6/8): PWR</b>	
Size: Custom	Document Number <b>Kendo-3 WS</b>
Date: Tuesday, December 07, 2010	Sheet 29 of 107

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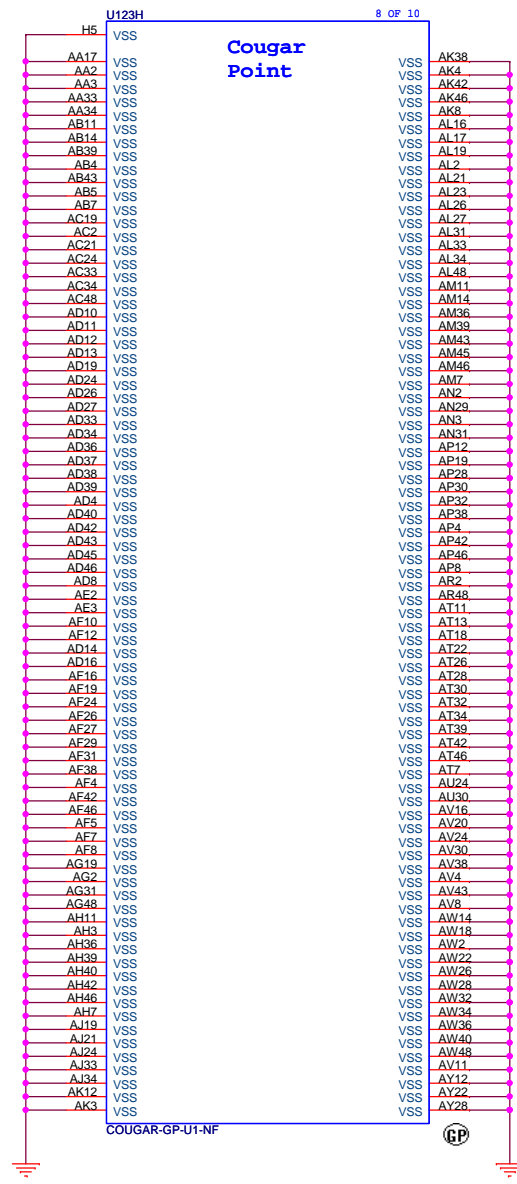
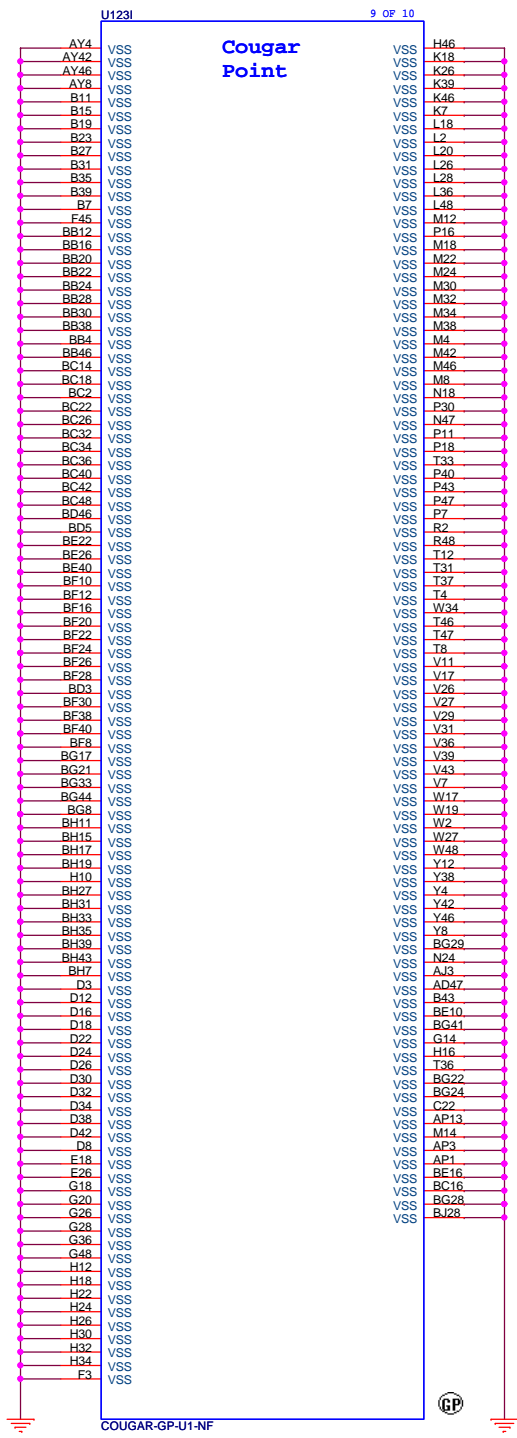
BOM

**緯創資通** **Wistron Corporation**  
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

Title **BLANK**

Size A3	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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Date: Tuesday, December 07, 2010 Sheet 30 of 107



BOM

**緯創資通 Wistron Corporation**  
 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

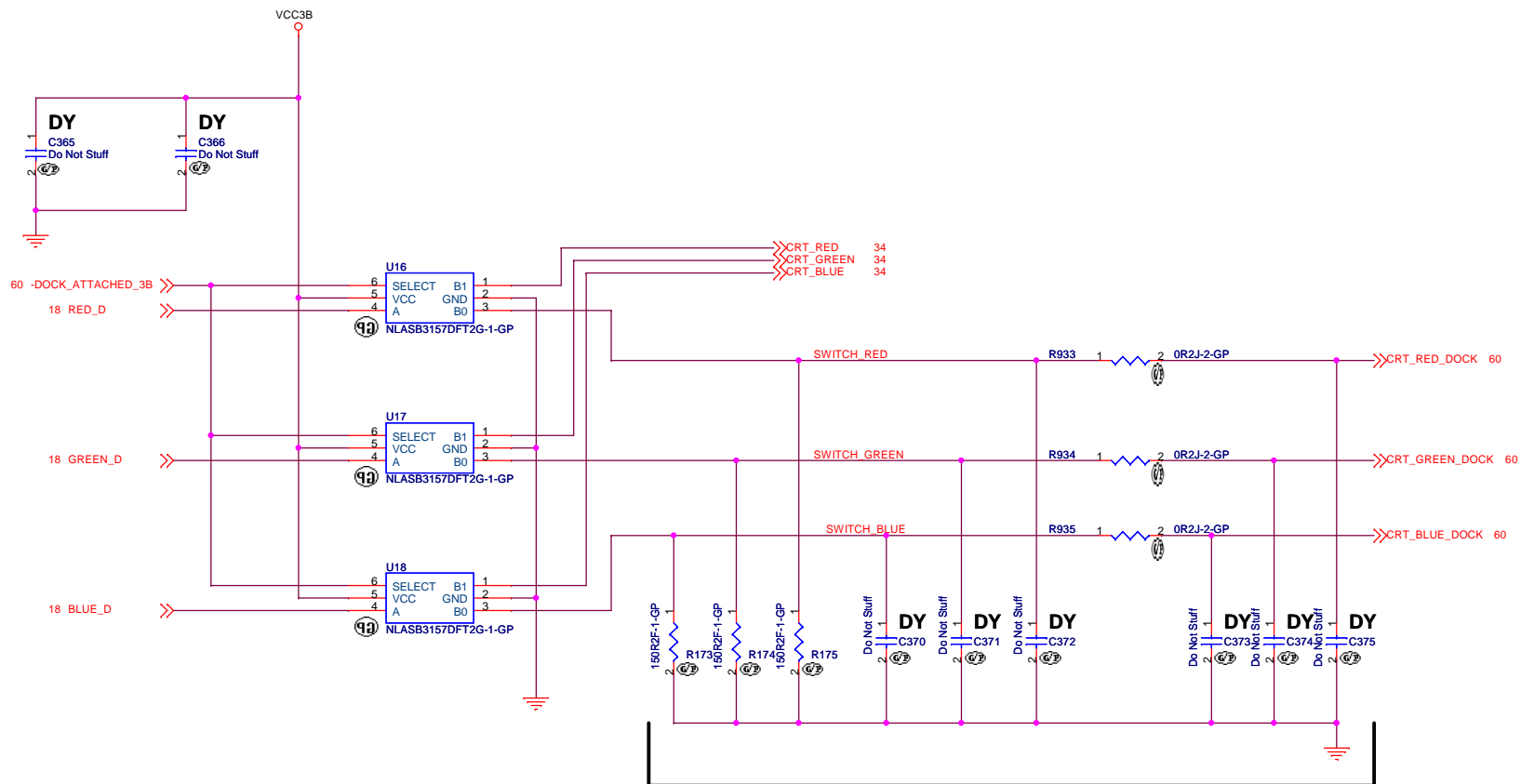
Title **PCH (8/8):GND**

Size A3 Document Number **Kendo-3 WS** Rev SA

Date: Tuesday, December 07, 2010 Sheet 31 of 107








Place near docking connector

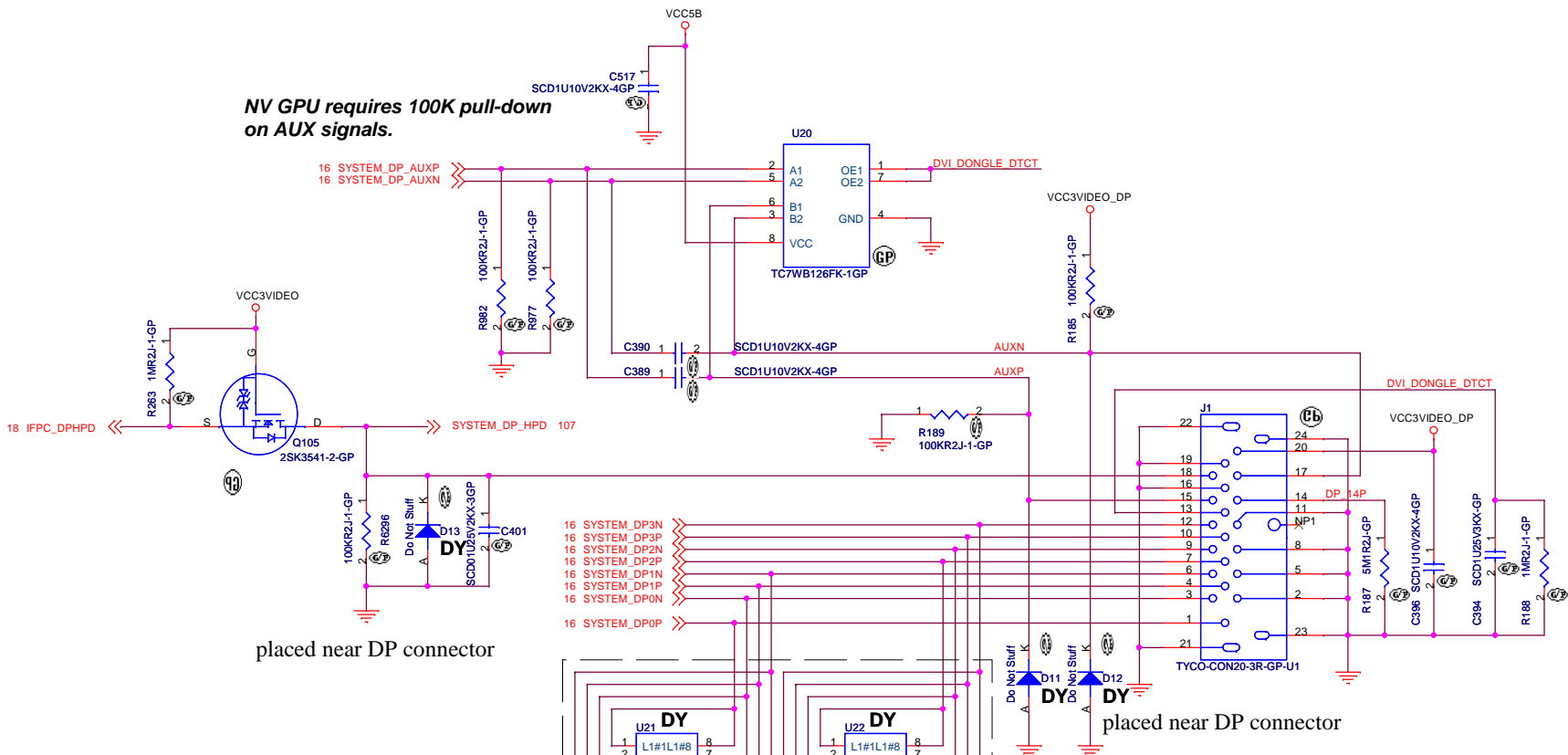
	Supplier	Vendo P/N	WISTRON P/N
1	ONSEMI	NLASB3157DFT2G	54Y9028CA
2	Toshiba	TC7SB3157CFU	73.03157.007
3	TI	74LVC1G3157DCKRE4	54Y9028BA

BOM

 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title		
<b>RGB SWITCH</b>		
Size A3	Document Number	Rev
	<b>Kendo-3 WS</b>	<b>SA</b>
Date: Tuesday, December 07, 2010	Sheet 33	of 107



**NV GPU requires 100K pull-down on AUX signals.**

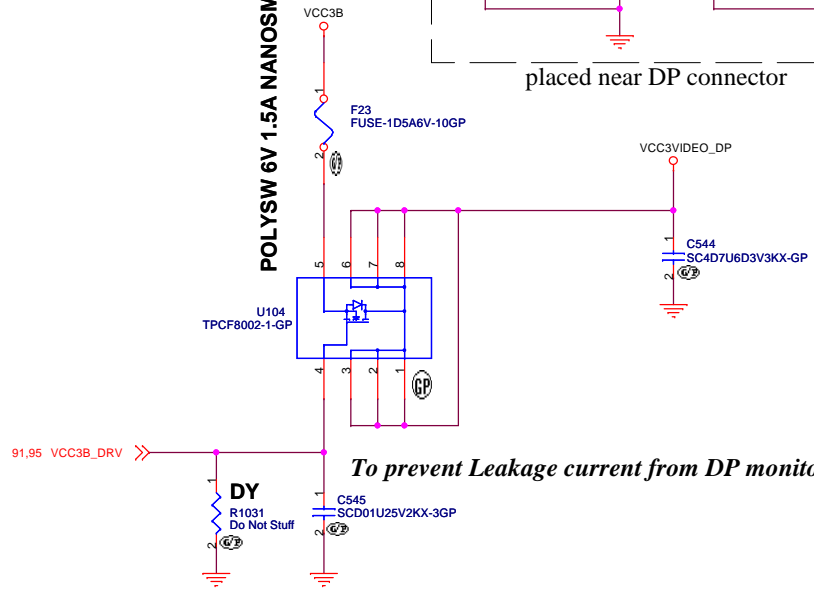


placed near DP connector

placed near DP connector

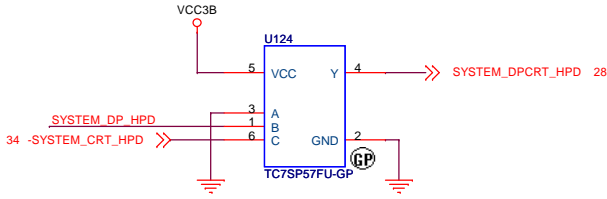
placed near DP connector

**POLYSW 6V 1.5A NANOSMDC150F**



*To prevent Leakage current from DP monitor.*

	Supplier	Vendo P/N	WISTRON P/N
1	ROHM	CDZC6.8B	83.00068.0AF
2	TOSHIBA	DF2S6.8UFS	83.00268.0AF



	Supplier	Vendo P/N	WISTRON P/N
1	TOSHIBA	TC7SP57FU	73.7SP57.0AJ
2	TI	SN74LVC1G57DCKR	73.01G57.AHJ

BOM

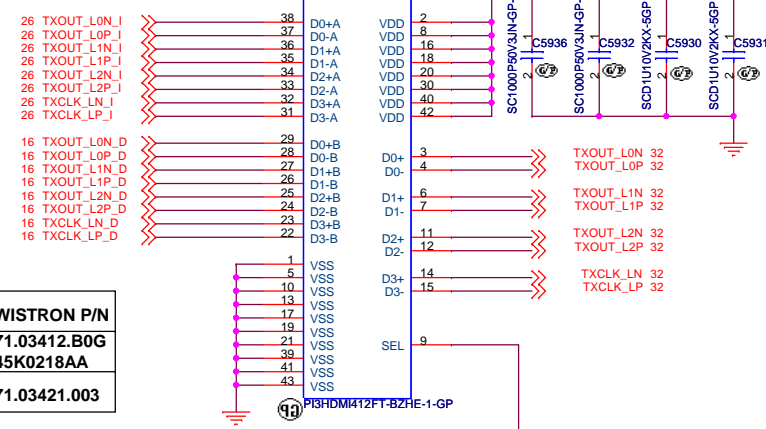
**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **DISPLAY PORT CONNECTOR**

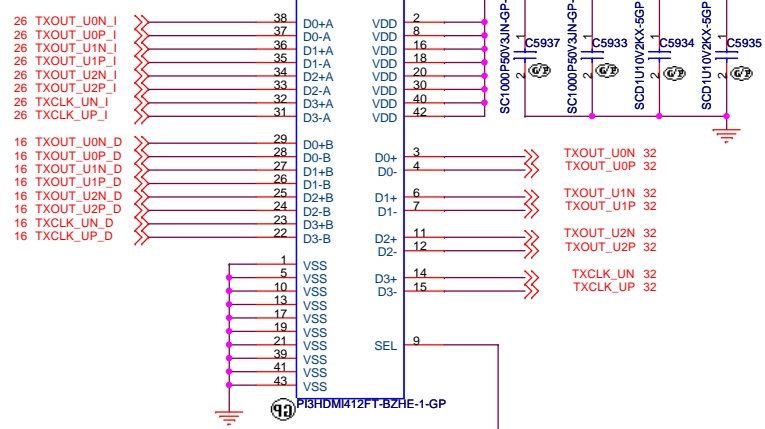
Size A3 Document Number: **Kendo-3 WS** Rev SA

Date: Tuesday, December 07, 2010 Sheet 35 of 107

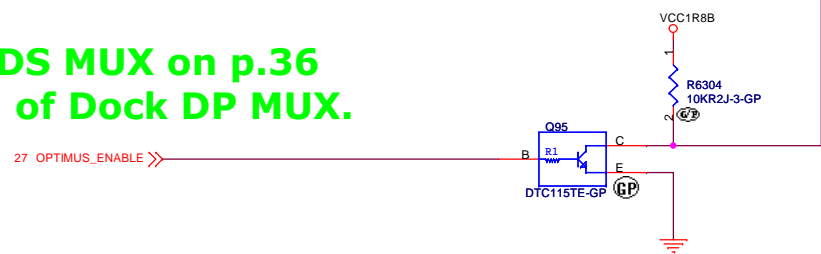
Signals can be arranged if there is wiring issue.



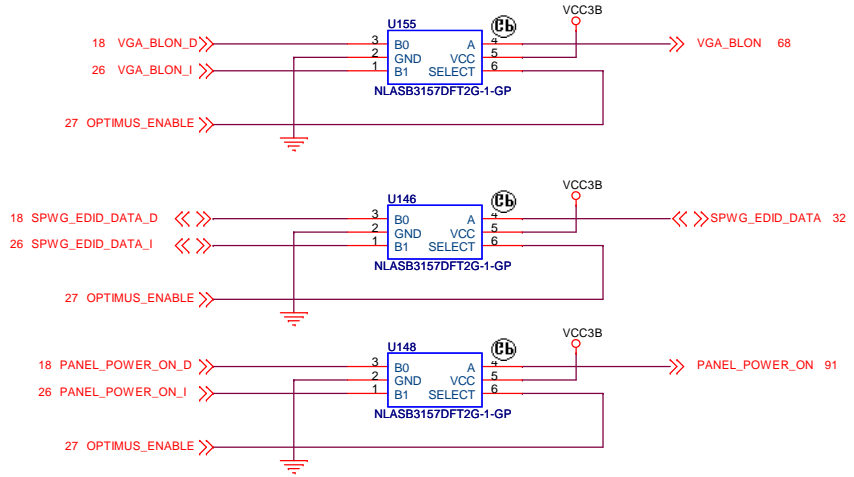
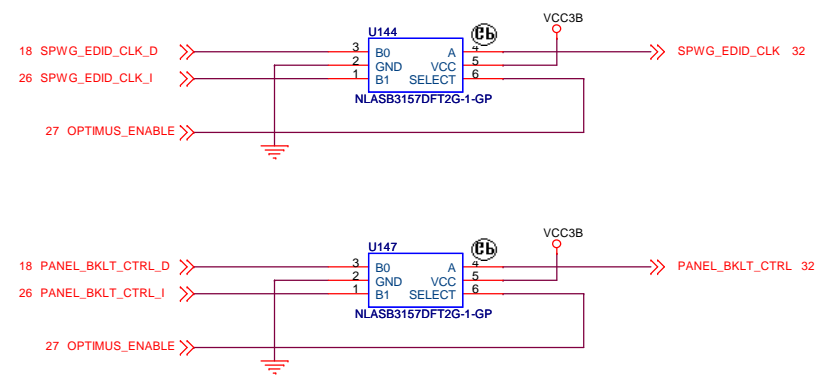
Signals can be arranged if there is wiring issue.



## Add LVDS MUX on p.36 instead of Dock DP MUX.



NZ-3 uses two of CBT3257ABQ due to space limitation.



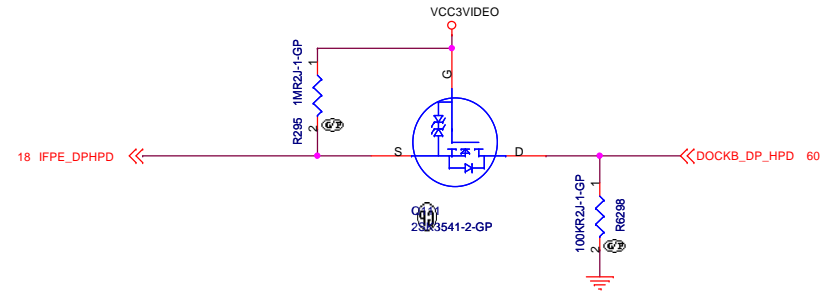
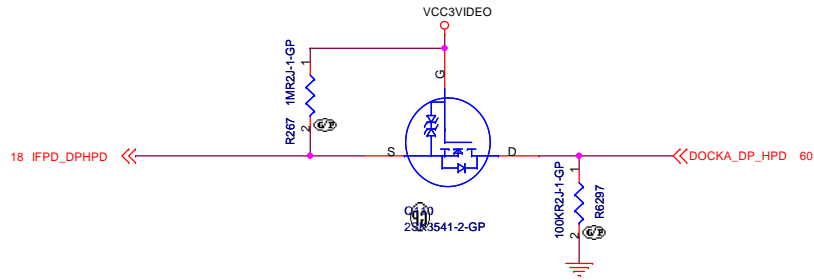
**BOM**

**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

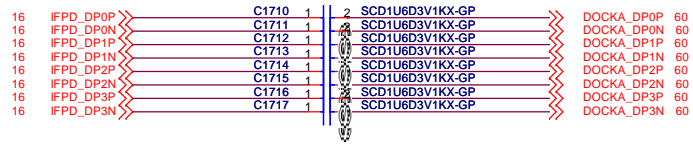
Title: **LVDS Switch**

Size A3 Document Number **Kendo-3 WS** Rev **SA**

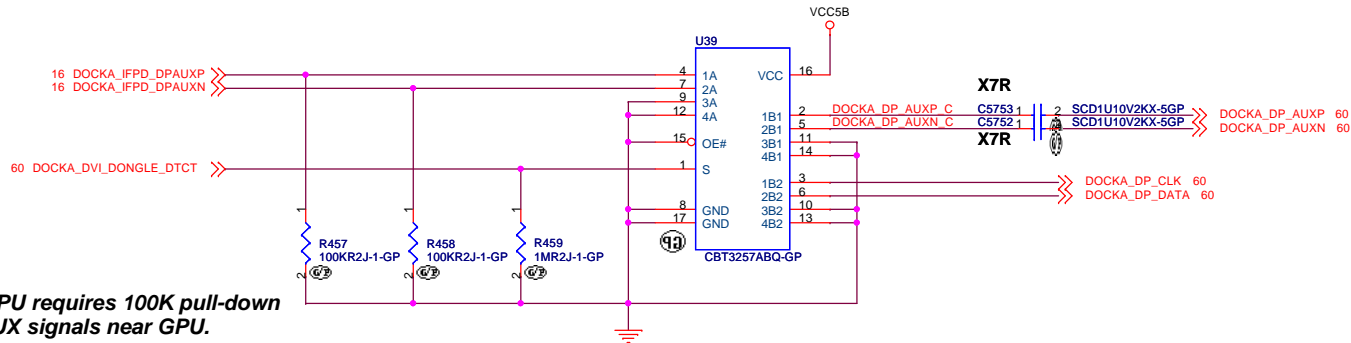
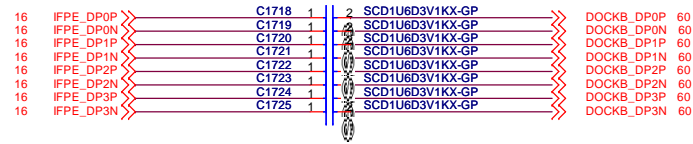
Date: Tuesday, December 07, 2010 Sheet 36 of 107



NEAR DOCK CONN



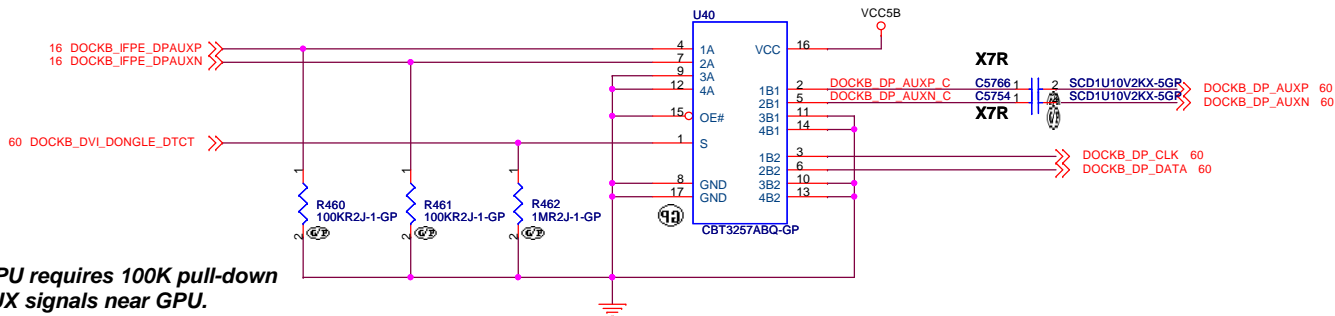
NEAR DOCK CONN



NV GPU requires 100K pull-down on AUX signals near GPU.

		U27, U39, U40	Wistron part number
1	NXP	CBT3257ABQ-GP	45K0213AA
2	OnSemi	74FST3257MNTWG-GP	45K0213BA

INPUTS		INPUT/OUTPUT	FUNCTION
OE#	S	A	
L	L	B1	A port = B1 port
L	H	B2	A port = B2 port
H	X	Z	Disconnect



NV GPU requires 100K pull-down on AUX signals near GPU.

BOM

**緯創資通 Wistron Corporation**  
 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **DISPLAY PORT MUX**

Size A3 Document Number **Kendo-3 WS** Rev SA

Date: Tuesday, December 07, 2010 Sheet 37 of 107

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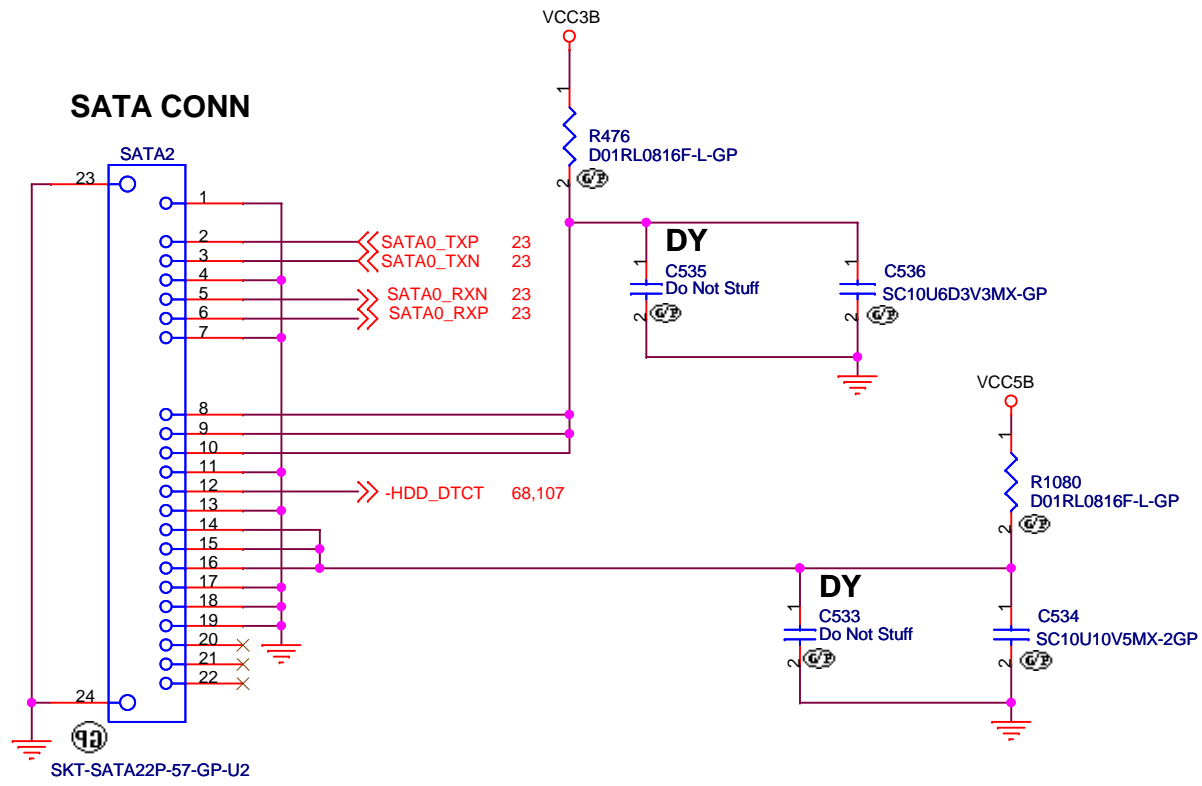
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**緯創資通** **Wistron Corporation**  
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

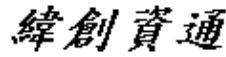
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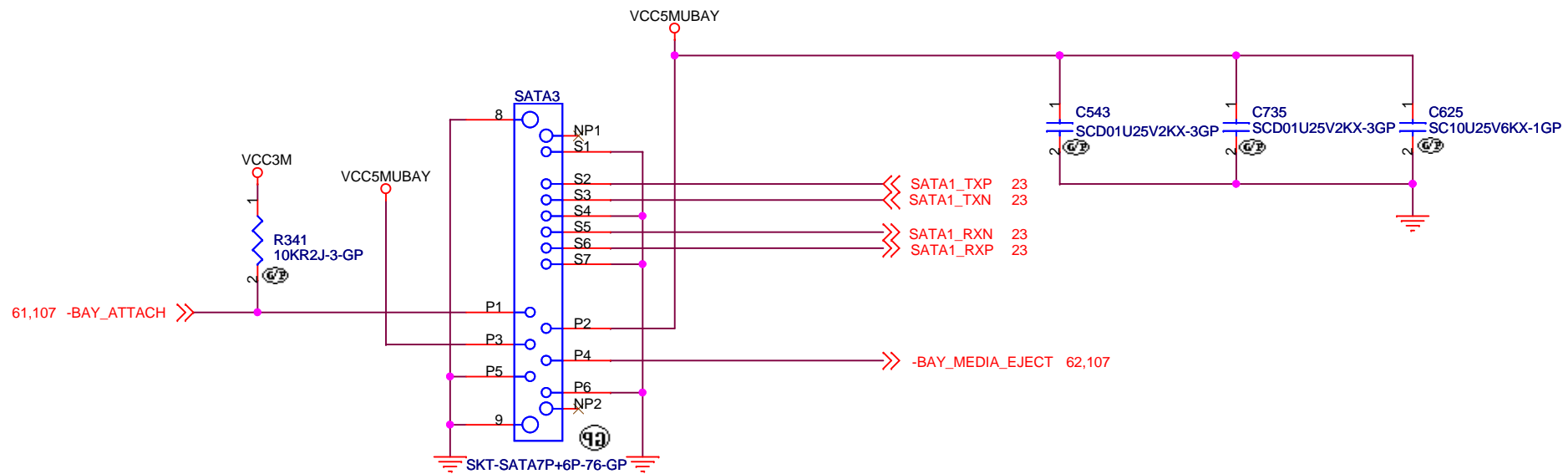
Size A3	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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Date: Tuesday, December 07, 2010 Sheet 38 of 107

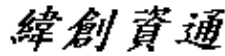


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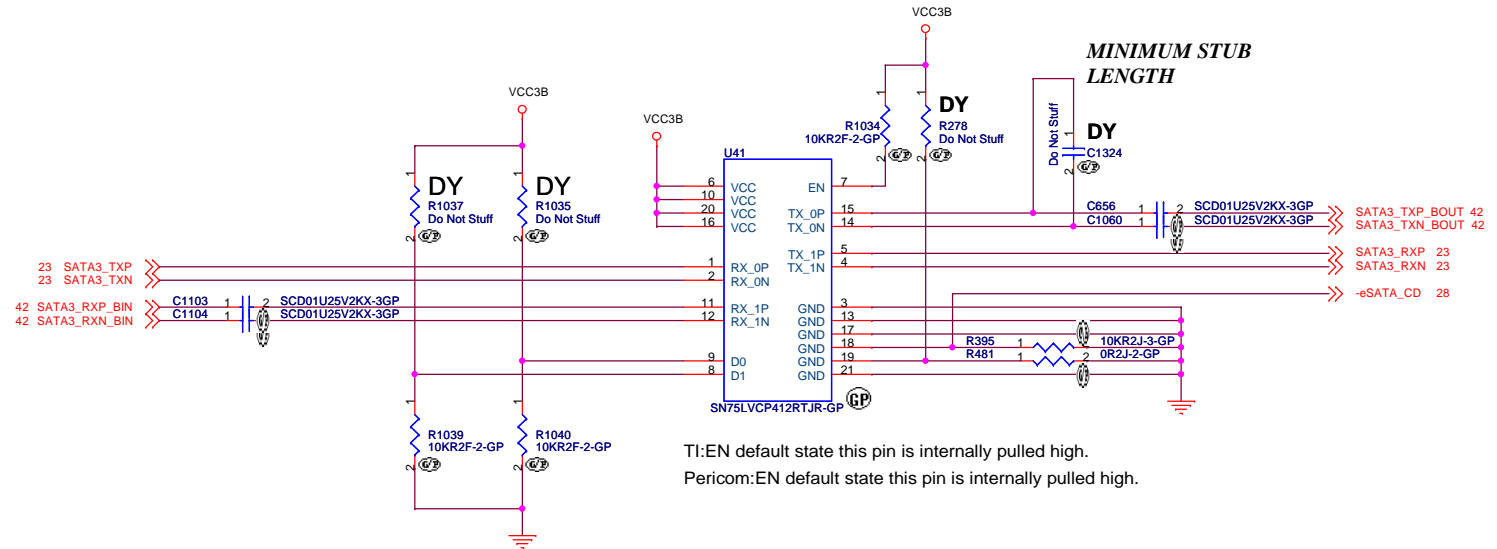
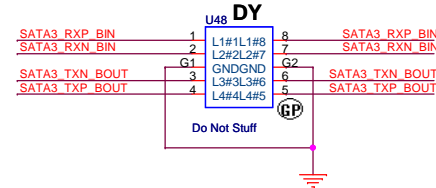
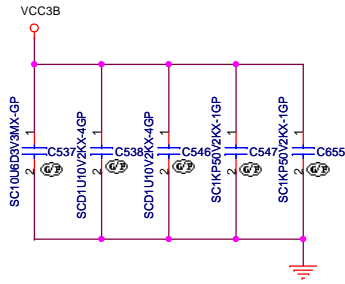
 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>Title</b> <b>SATA HDD CONN</b>	
<b>Size</b> A4	<b>Document Number</b> <b>Kendo-3 WS</b>
<b>Date:</b> Tuesday, December 07, 2010	<b>Rev</b> <b>SA</b>
<b>Sheet 39 of 107</b>	



BOM

 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>Title</b> <b>SATA BAY I/F CONN</b>	
Size A4	Document Number <b>Kendo-3 WS</b>
Date: Tuesday, December 07, 2010	Rev <b>SA</b>
Sheet 40 of 107	





TABLE

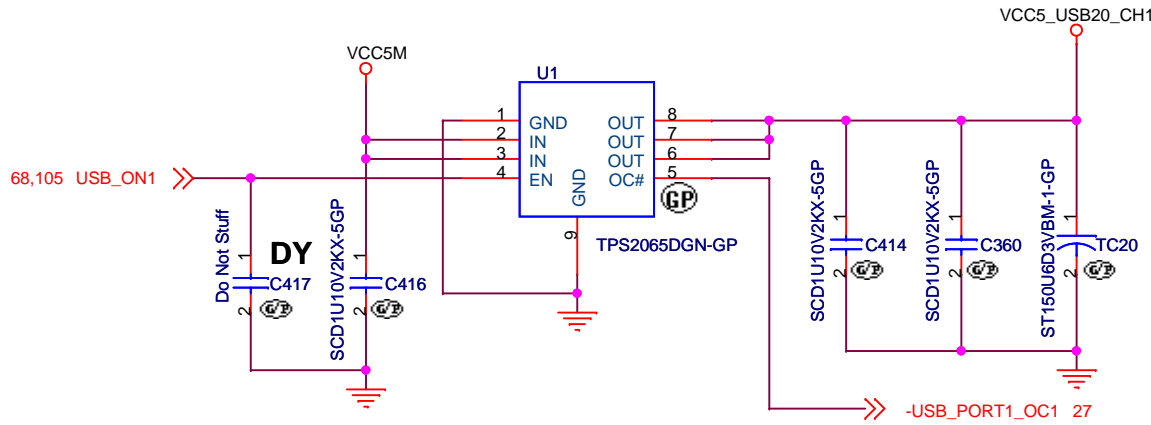
EN	D0	D1	CH - 0	CH - 1
0	X	X	STANDBY	STANDBY
1	0	0	STANDARD	STANDARD
1	1	0	BOOST	STANDARD
1	0	1	STANDARD	BOOST
1	1	1	BOOST	BOOST

← LOGIC

		U41	Part Number	R278	R395	R481
1	TI	SN75LVCP412ARTJR-GP	71.75412.A03	NO ASM	10K	0
2	Pericom	PI3EQX4951STZDEX-GT	71.34951.A03			
3	TI	SN75LVCP412CD	71.75412.B03	4.7K	NO ASM	
2	Pericom	PI3EQX6741STBZDE	71.36741.003			

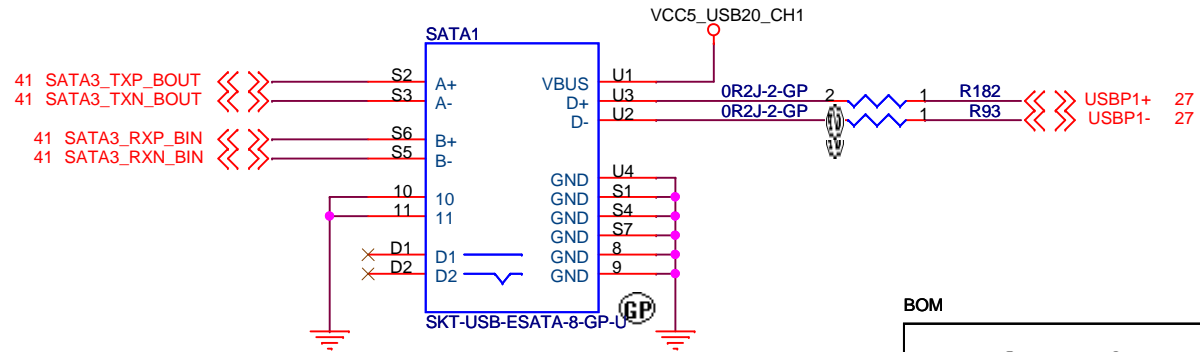
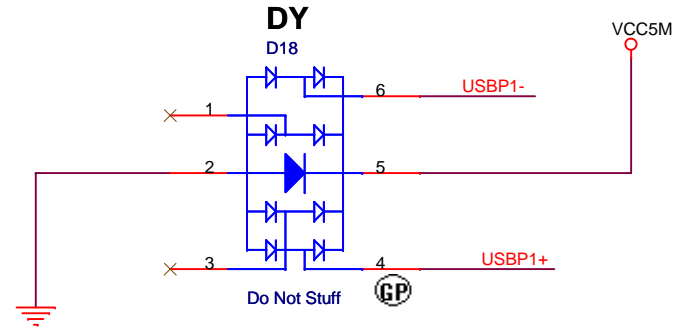
BOM

<b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>ESATA CONNECTOR</b>	
Title <b>ESATA CONNECTOR</b>	Document Number <b>Kendo-3 WS</b>
Size A3	Rev <b>SA</b>
Date: Tuesday, December 07, 2010	
Sheet 41 of 107	



### 1CH USB Power Switch w/o Output Discharge Function

	Supplier	Vendo P/N	WISTRON P/N
U1	TI	TPS2065DGN-GP	54Y9024BA



### eSATA Combo

BOM

**緯創資通** **Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

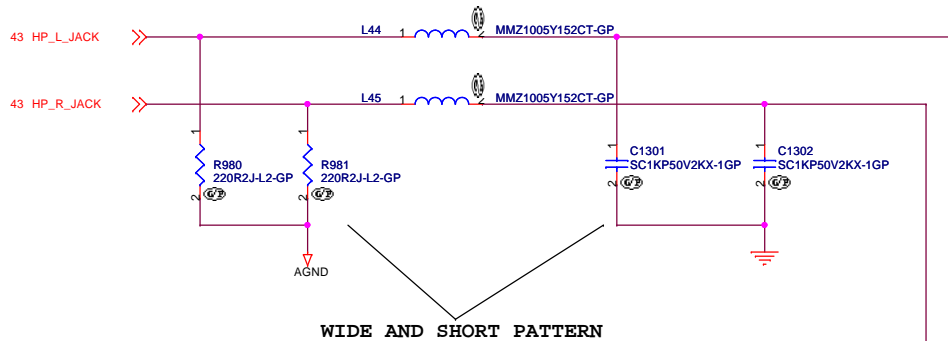
Title **USB POWER/ CONN**

Size A4	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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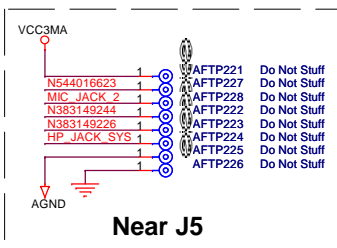
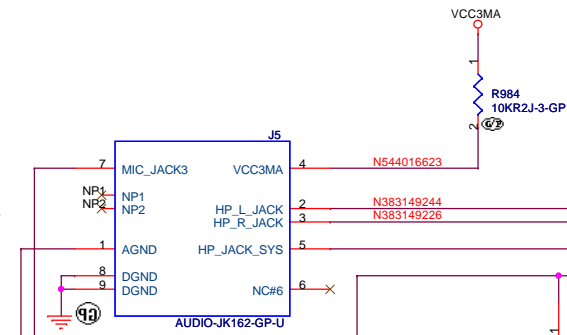
Date: Tuesday, December 07, 2010 Sheet 42 of 107



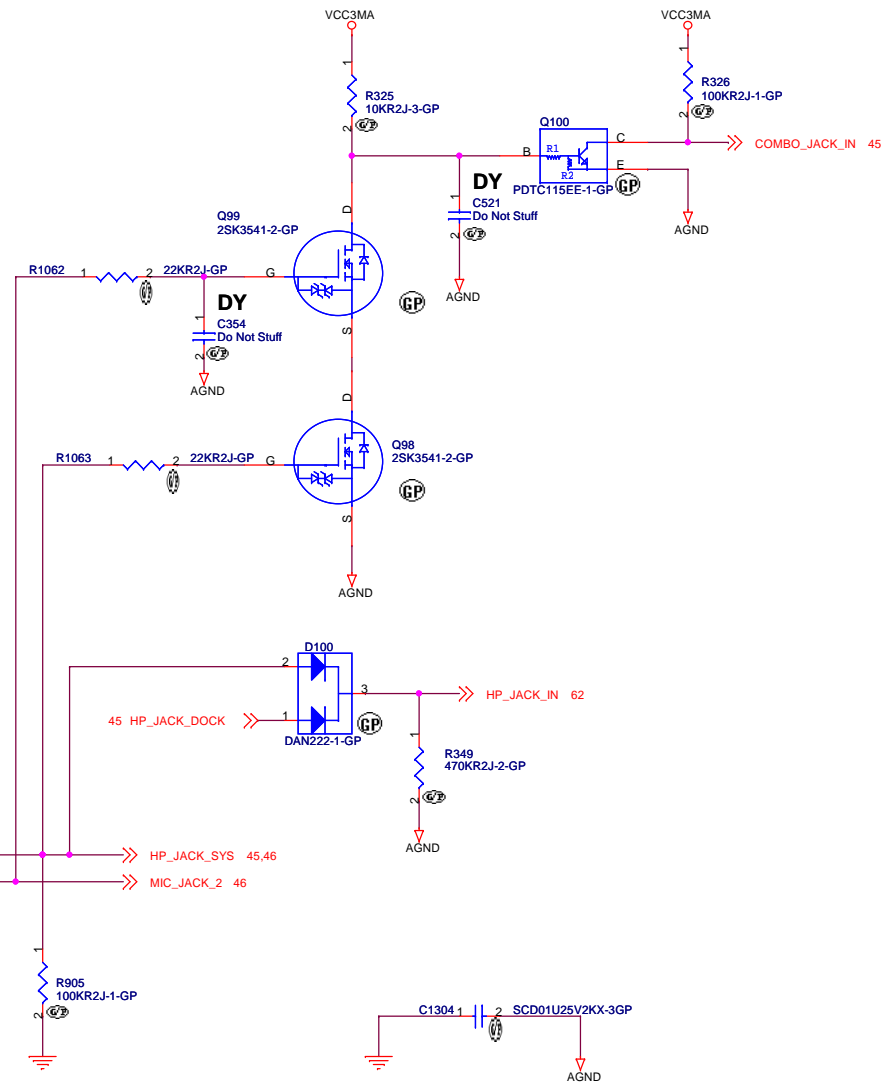
# NEAR HEADPHONE CONN



WIDE PATTERN

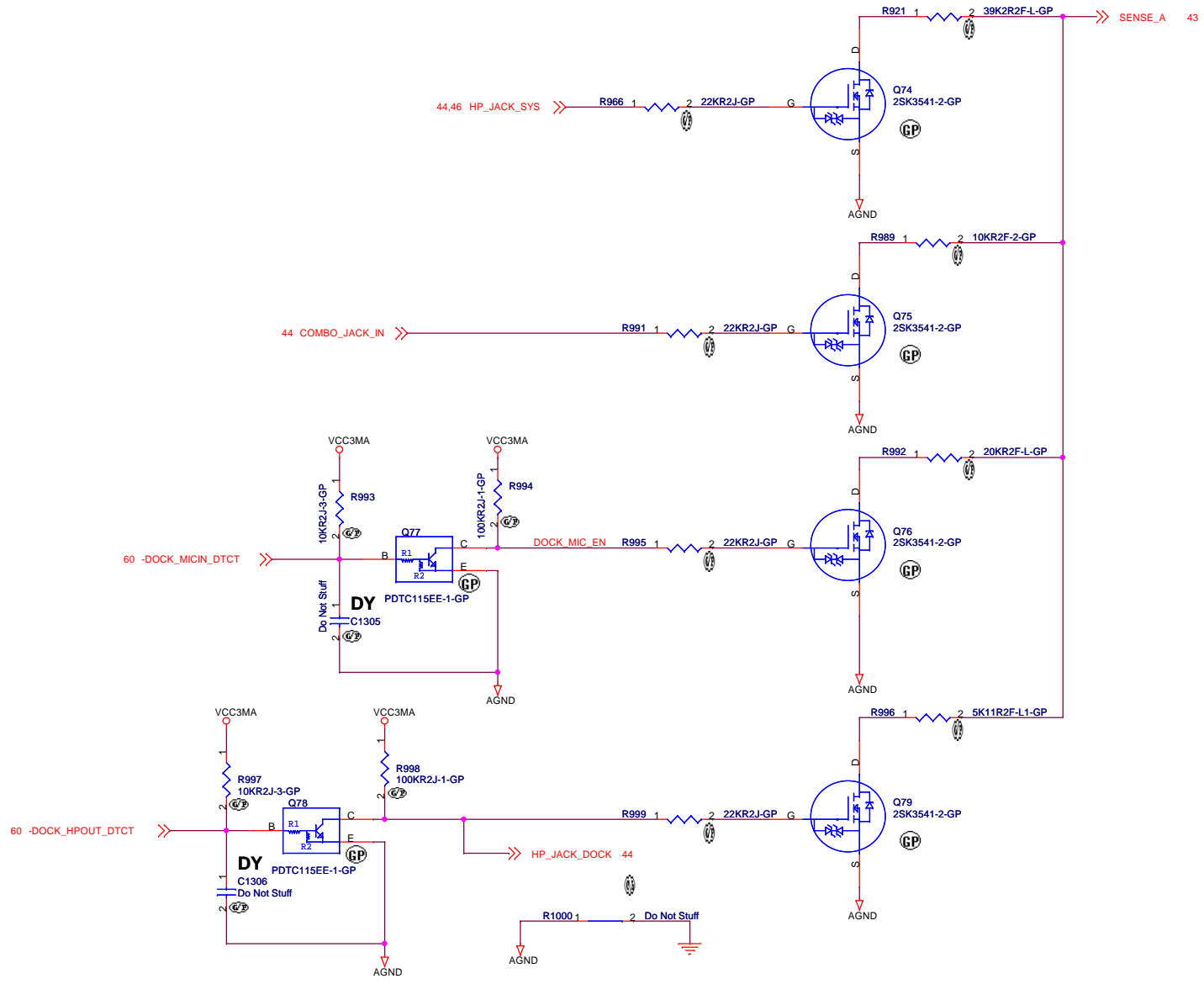


	Supplier	Vendo P/N	PART NUMBER
1	OnSemi	ESD5B5D0ST1G-GP	48Y9647BA
2	ROHM	RSB5.6S	48Y9647AA
3	NXP	PESD5V0S1BB	83.0005V.0AF

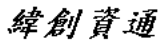


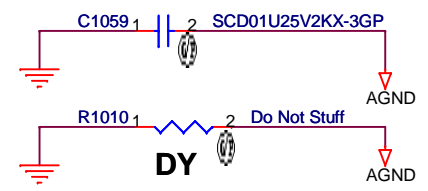
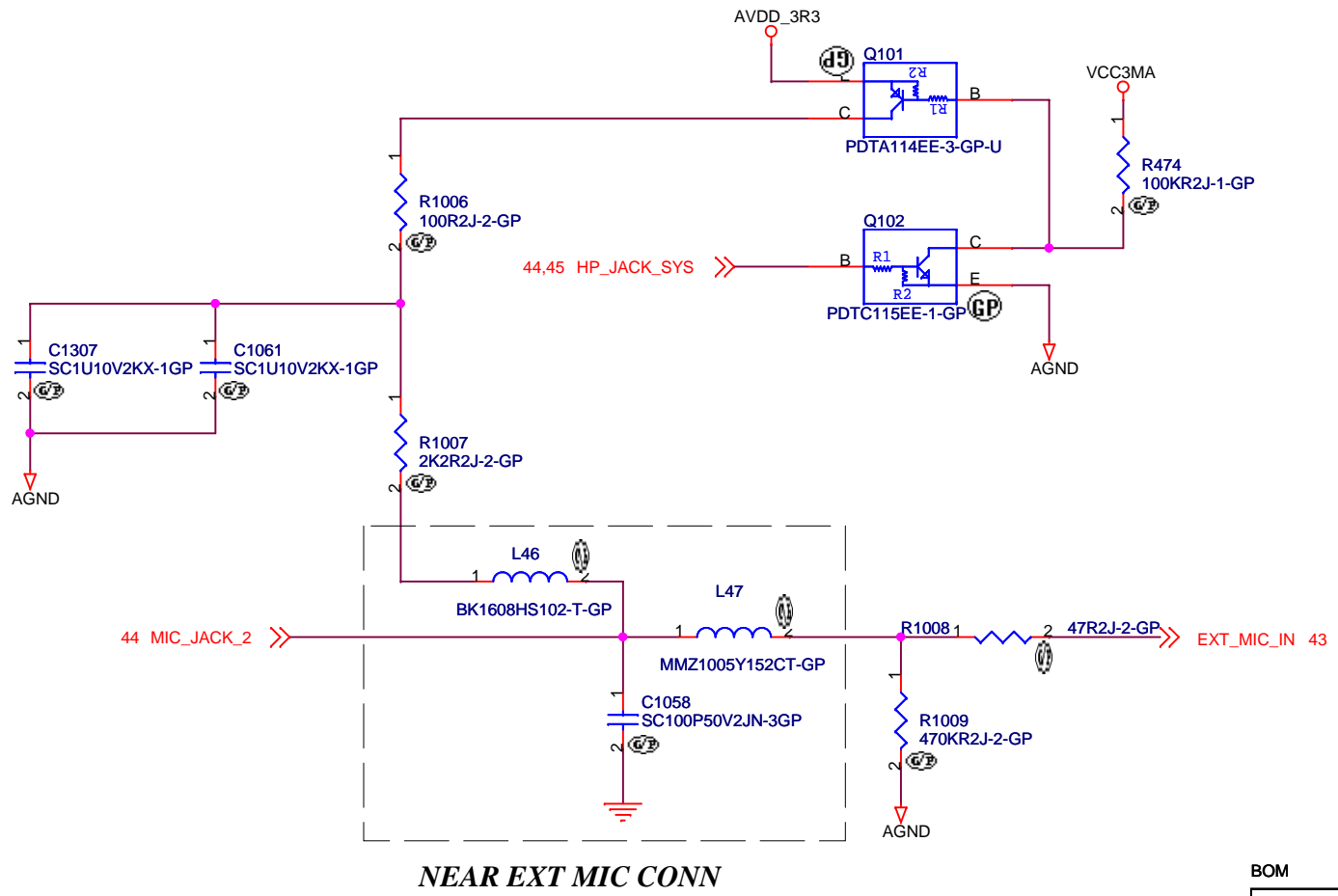
BOM

		<b>Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>AUDIO CONNECTOR</b>			
Title		Rev	
Size		Document Number	SA
Date		Kendo-3 WS	44 of 107
Tuesday, December 07, 2010		Sheet	of

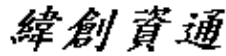


BOM

 <b>Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>AUDIO JACK SENSE</b>	
Title <b>A3</b>	Document Number <b>Kendo-3 WS</b>
Date: Tuesday, December 07, 2010	Sheet 45 of 107
Rev <b>SA</b>	



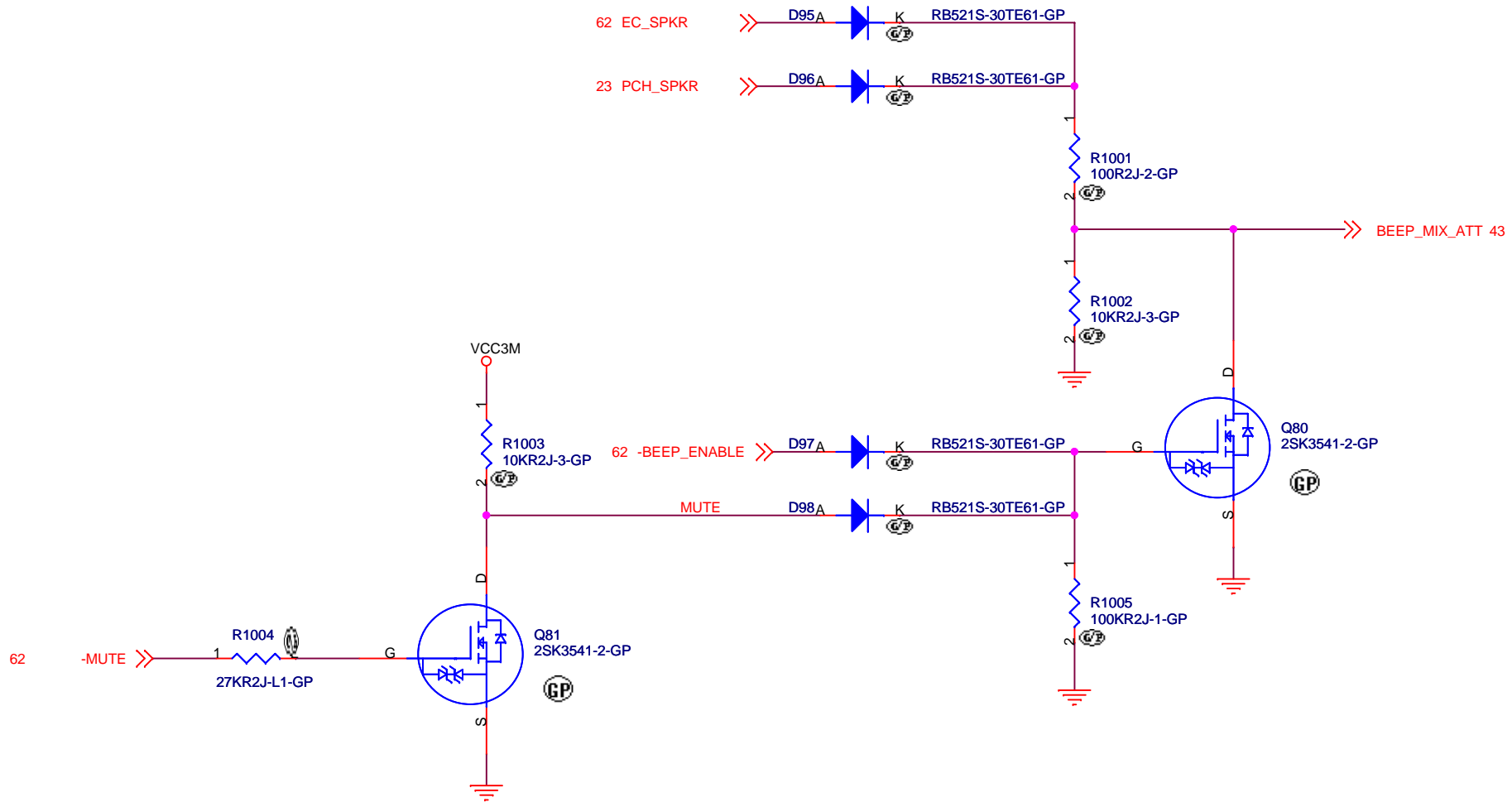
BOM

 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>AUDIO EXT MIC I/F</b>	
Size A4	Document Number <b>Kendo-3 WS</b>
Date Tuesday, December 07, 2010	Rev <b>SA</b>
Sheet 46 of 107	

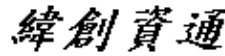
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BOM

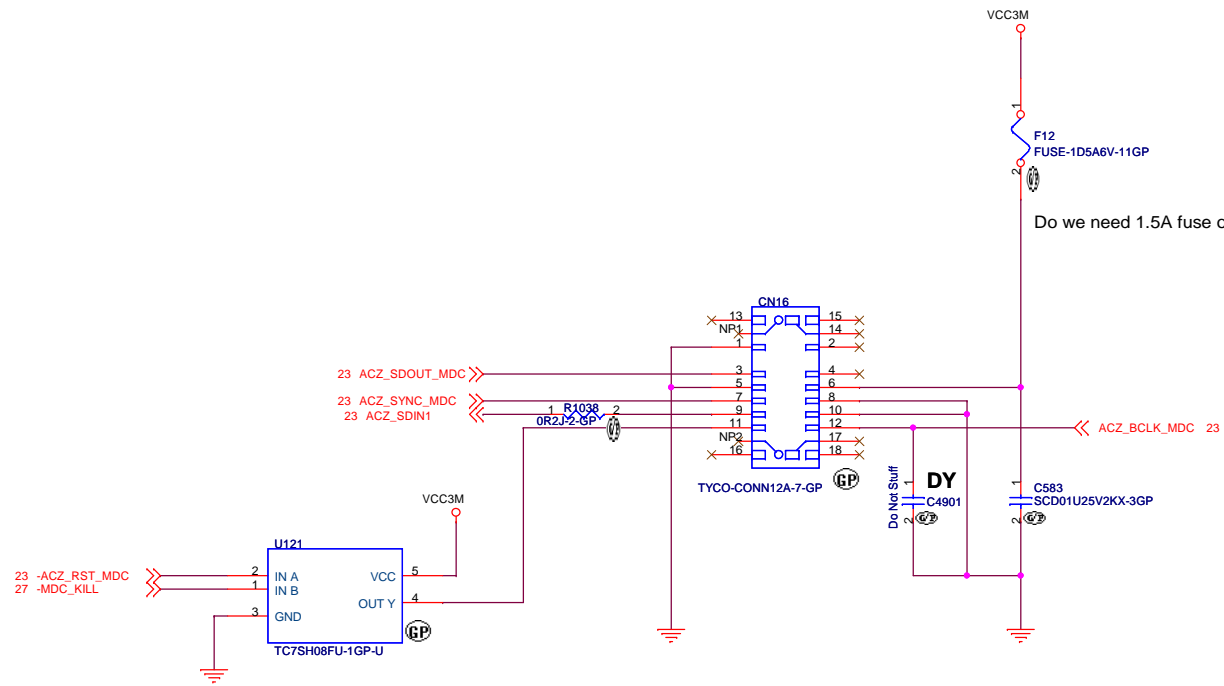
<b>緯創資通</b>		<b>Wistron Corporation</b>	
		21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
<b>BLANK</b>			
Size	Document Number		Rev
A3	<b>Kendo-3 WS</b>		<b>SA</b>
Date:	Tuesday, December 07, 2010	Sheet	47 of 107



BOM

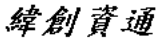
 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>BEEP CONTROL</b>	
Size A4	Document Number <b>Kendo-3 WS</b>
Date Tuesday, December 07, 2010	Rev <b>SA</b>
Sheet 48 of 107	

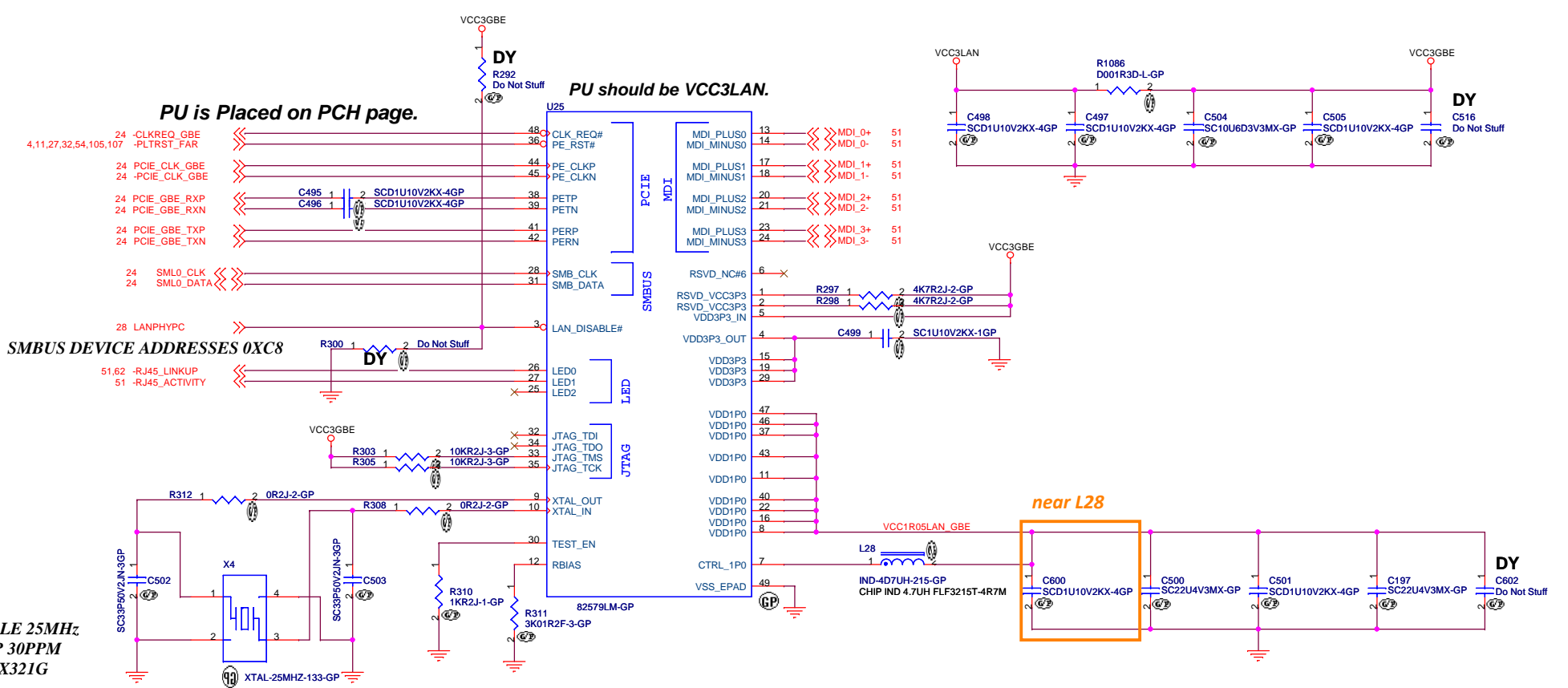




Do we need 1.5A fuse on this power rail?

BOM

 <b>Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>Title</b> <b>MDC Interface</b>		
<b>Size</b> A3	<b>Document Number</b> <b>Kendo-3 WS</b>	<b>Rev</b> <b>SA</b>
<b>Date:</b> Tuesday, December 07, 2010		<b>Sheet</b> 49 <b>of</b> 107



Supplier	Vendo P/N	WISTRON P/N
1 HARMONY	XTAL 25M 18P30PPM HSX321G SMD	82.30020.B21
2 HOSONIC	XATL 25M 18P30PPM HCX-3SB SMD	82.30020.B41
3 TXC	XTAL 25M 18P30PPM 4P SMD	82.30020.D21

HARMONY, TXC : C502, C503=22pF

NOTE: VCC1R05LAN WILL WORK AT 0.95V TO 1.15V

KDS Recommended Conditions: Normal Frequency: 25MHz. Frequency Tolerance: +/- 30ppm. Load Frequency: 18pF. Effective Series Resistance: 50-ohm. Effective Shunt Capacitance: 2pF.	HELE Recommended Conditions: Normal Frequency: 25MHz. Frequency Tolerance: +/- 30ppm. Load Frequency: 18pF. Effective Series Resistance: 50-ohm. Effective Shunt Capacitance: 2pF.	Intel Recommended Conditions: Normal Frequency: 25MHz. Frequency Tolerance: +/- 30ppm. Load Frequency: 18pF. Effective Series Resistance: 50-ohm. Effective Shunt Capacitance: 6pF.
--	---	--

BOM

<b>緯創資通</b>		<b>Wistron Corporation</b>	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>GBE HANKSVILLE</b>			
Title			
Size A3	Document Number	<b>Kendo-3 WS</b>	Rev SA
Date: Tuesday, December 07, 2010	Sheet 50	of	107



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BOM

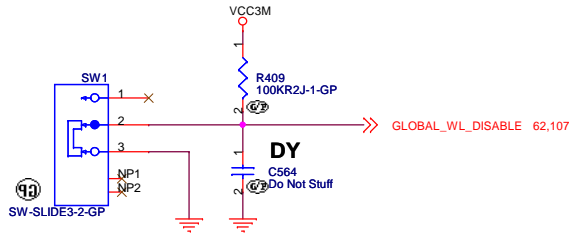
<b>緯創資通</b>		<b>Wistron Corporation</b>	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title <b>BLANK</b>			
Size A4	Document Number <b>Kendo-3 WS</b>		Rev <b>SA</b>
Date: Tuesday, December 07, 2010		Sheet 52 of	107

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BOM

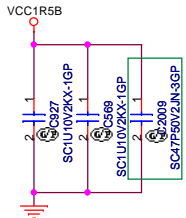
<b>緯創資通</b>		<b>Wistron Corporation</b>	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title <b>BLANK</b>			
Size A4	Document Number <b>Kendo-3 WS</b>		Rev <b>SA</b>
Date: Tuesday, December 07, 2010		Sheet 53 of	107

# WIRELESS DISABLE SWITCH

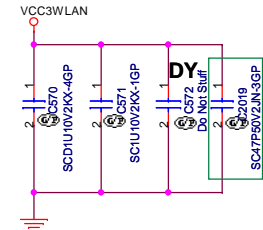


On WWAN Always on regular mode, This component have to be assembled, instead of above D+/D- jumper.

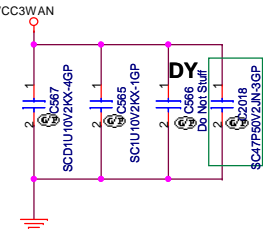
For RF



For RF, place near WLAN slot

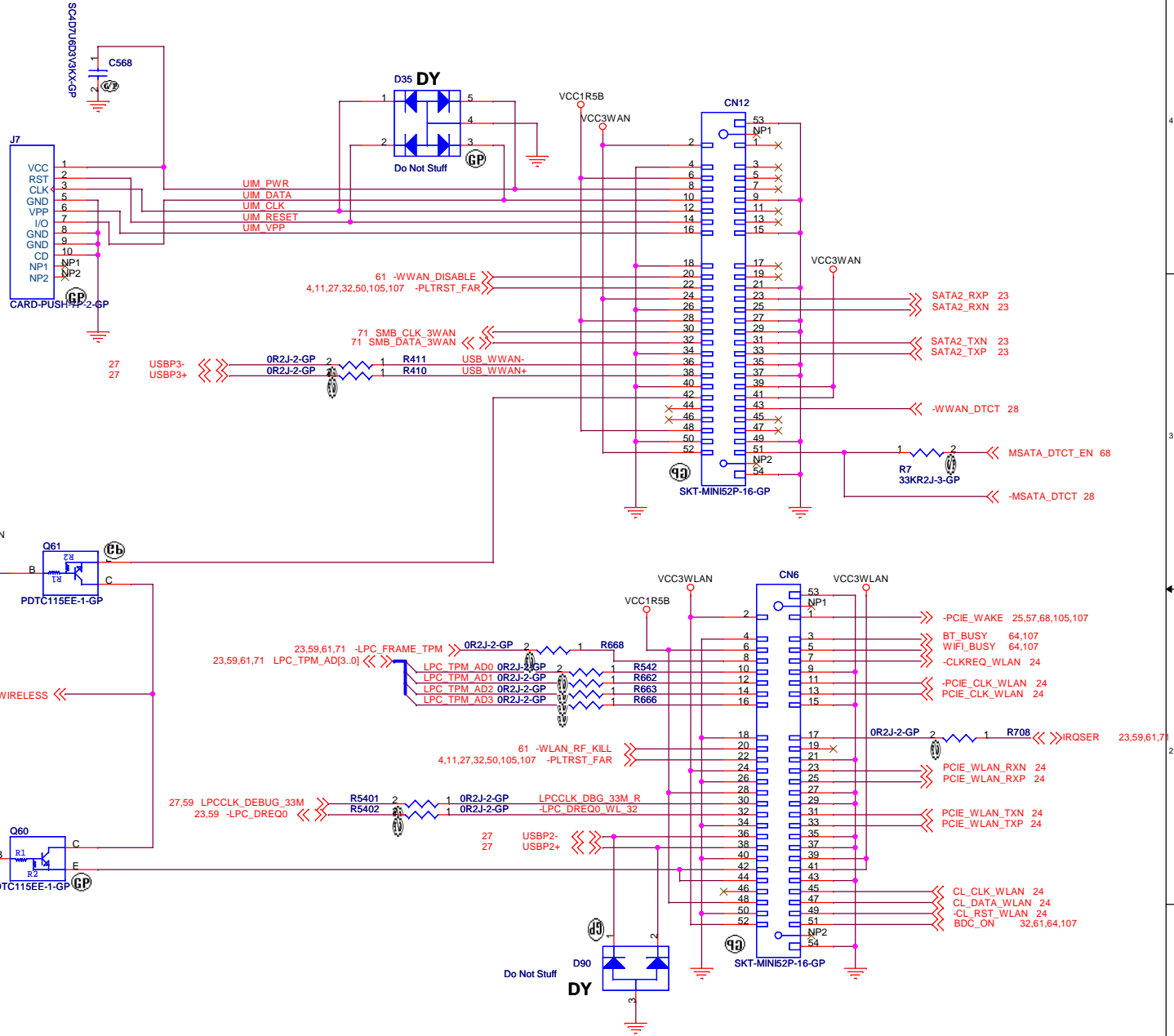


For RF, place near WWAN slot



WWAN	YES	NO
CN12	ASM	No_ASM
J7	ASM	No_ASM
C567	ASM	No_ASM
C565	ASM	No_ASM
C568	ASM	No_ASM
C2018	ASM	No_ASM

Logic



When PCIe IF device does not use, These signal will be removed.

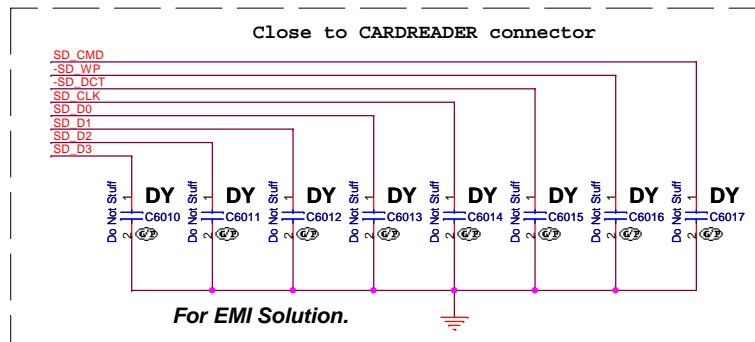
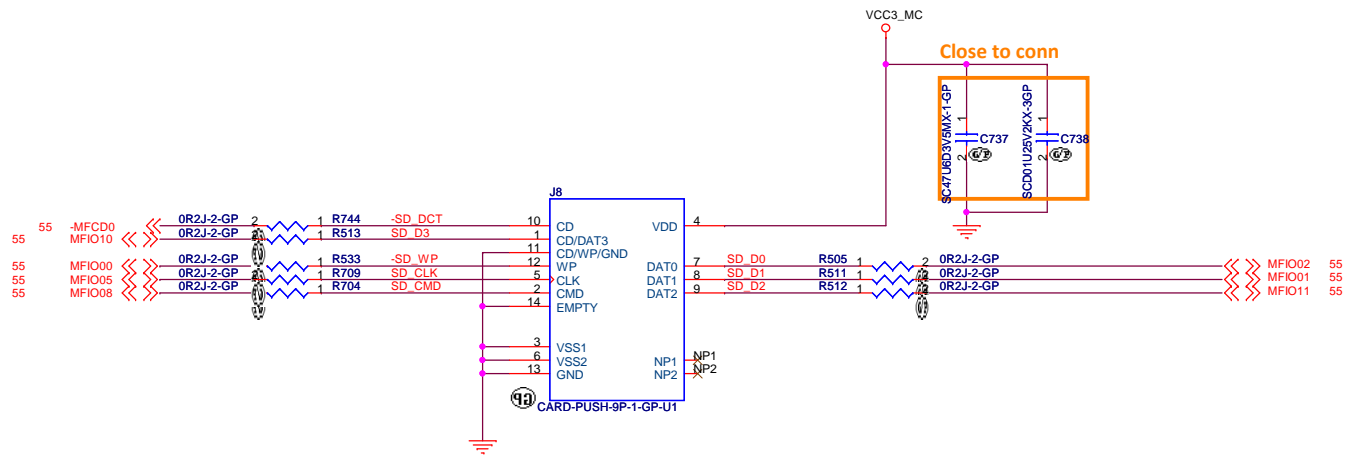
**緯創資通 Wistron Corporation**  
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **PCIE MINI CARD SLOT**

Size A3 Document Number: **Kendo-3 WS** Rev: **SA**

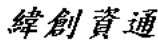
Date: Tuesday, December 07, 2010 Sheet 54 of 107



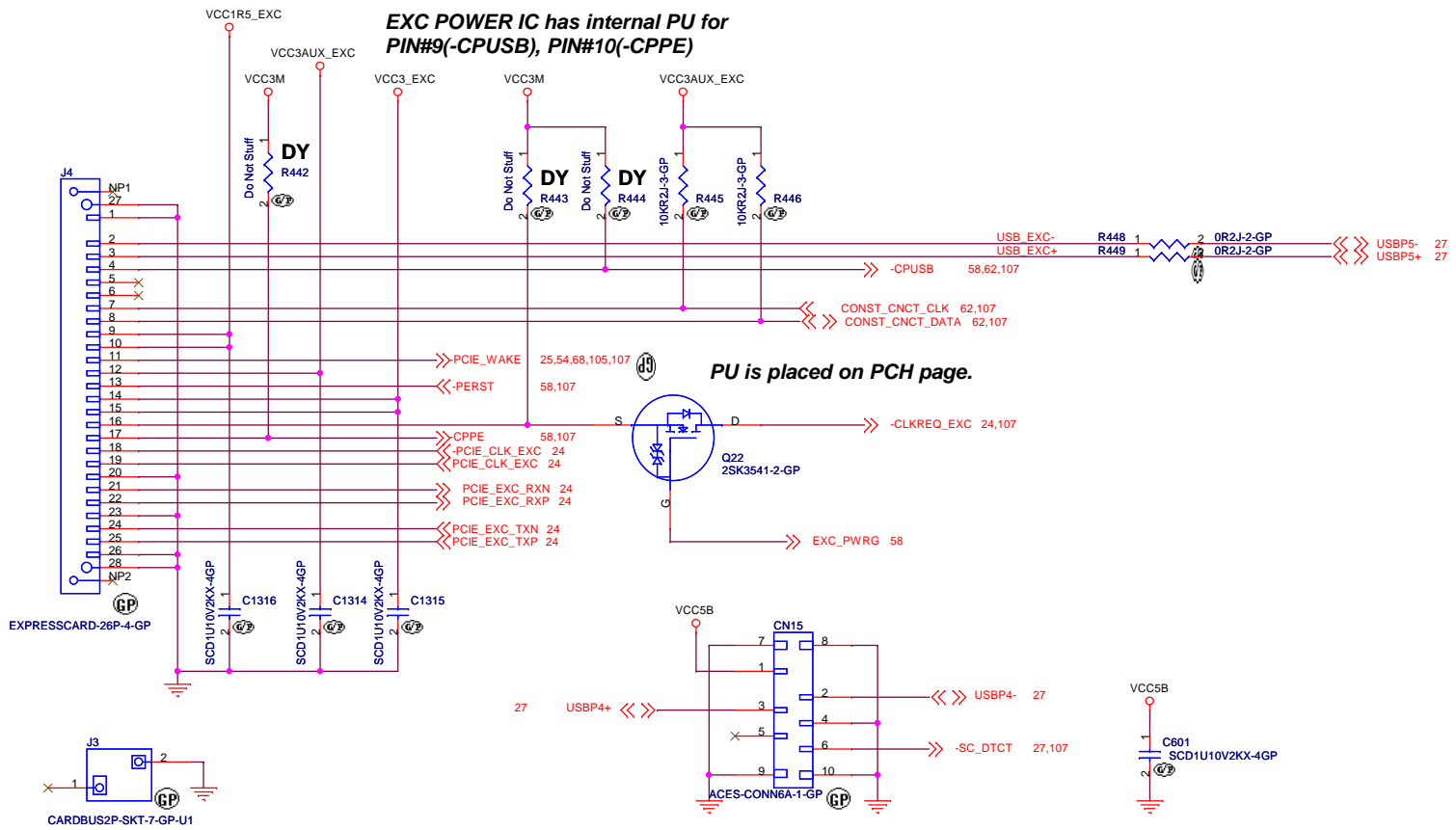


		U50, U51, U52, U53	Wistron part number
1	TOSHIBA	TC7SBL384AFU-GP	73.7S384.007
2	NXP	74LVC1G384GW	73.1G384.AHH
3	TI	TS5A3167DCKR	74.53167.A9F

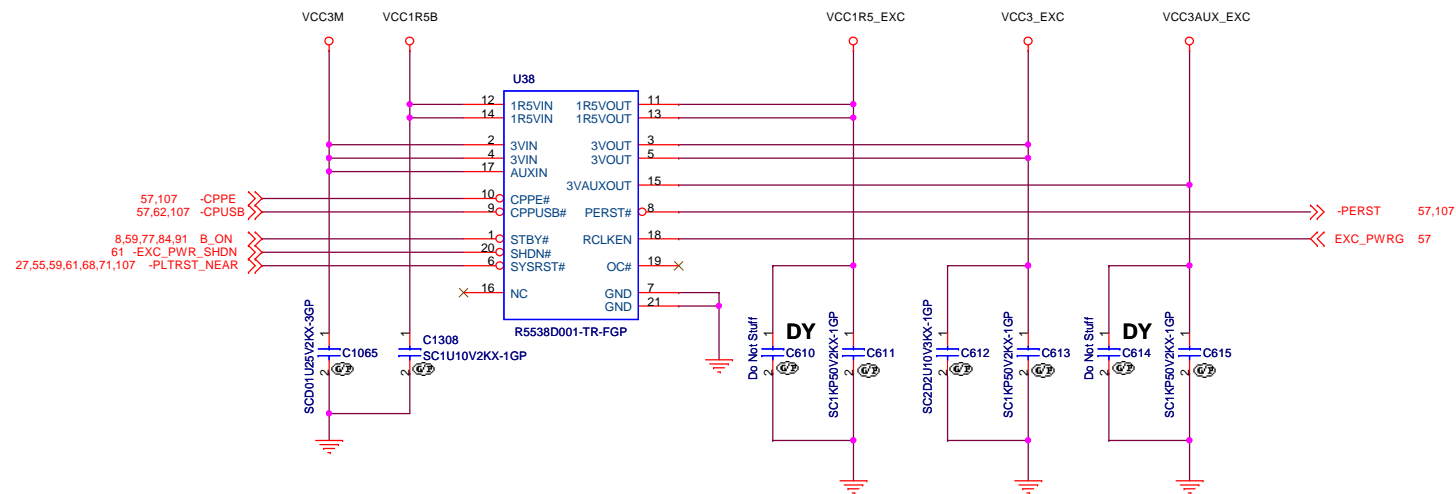
BOM

 <b>Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>MEDIA CARD INTERFACE</b>	
Title <b>MEDIA CARD INTERFACE</b>	Rev <b>SA</b>
Size A3	Document Number <b>Kendo-3 WS</b>
Date: Tuesday, December 07, 2010	Sheet 56 of 107





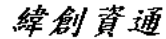
BOM		
<b>緯創資通 Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>Title</b> Express Card/SMART CARD IF		
Size A3	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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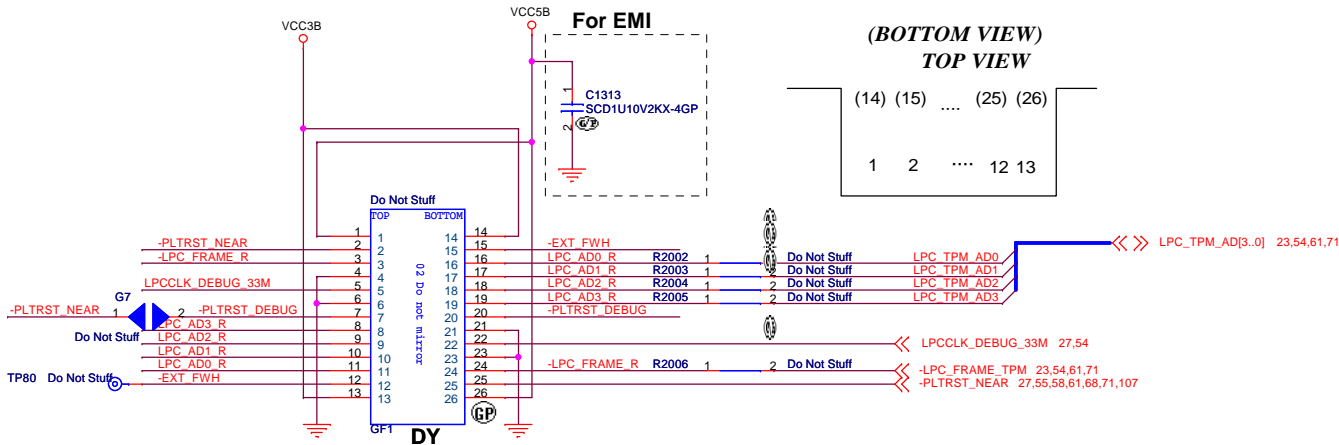
EXPRESS POWER SW table

		U38	Wistron part number
1	ROHM	BD4157MUV	74.04157.073
2	TI	TPS2231MRGPR	45K0234BA
3	NUVOTON	W83L351YG	74.83351.A73

BOM

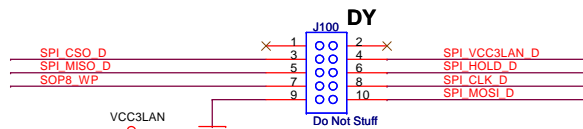
 <b>Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>Title</b> <b>SLOT POWER CONTROL</b>		
<b>Size</b> A3	<b>Document Number</b> <b>Kendo-3 WS</b>	<b>Rev</b> <b>SA</b>
<b>Date:</b> Tuesday, December 07, 2010		<b>Sheet</b> 58 <b>of</b> 107

# Golden Finger for Debug Board



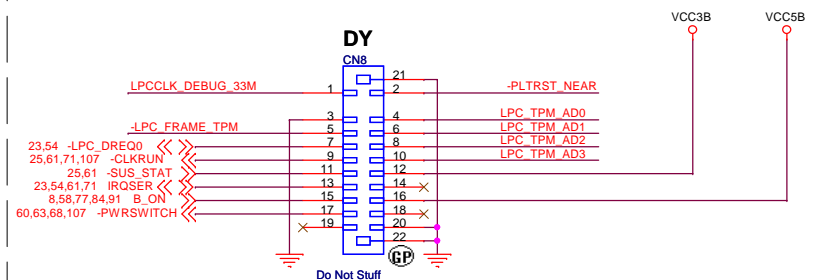
## 64Mbit SPI FLASH :

Package	Supplier	Vendor P/N	Lenovo P/N	Wistron P/N
SO8	Macronix	MX25L6436EM2I-10G		72.25643.001
	Winbond	W25Q64CVSSIG		72.25Q64.B01
	ATMEL	AT25DF641		72.25641.001
WSON	Numonyx	M25PX64-VMD6TG		72.25P64.E01



Dual foot print for WSON and SO8.

# Lenovo Debug Tool IF.

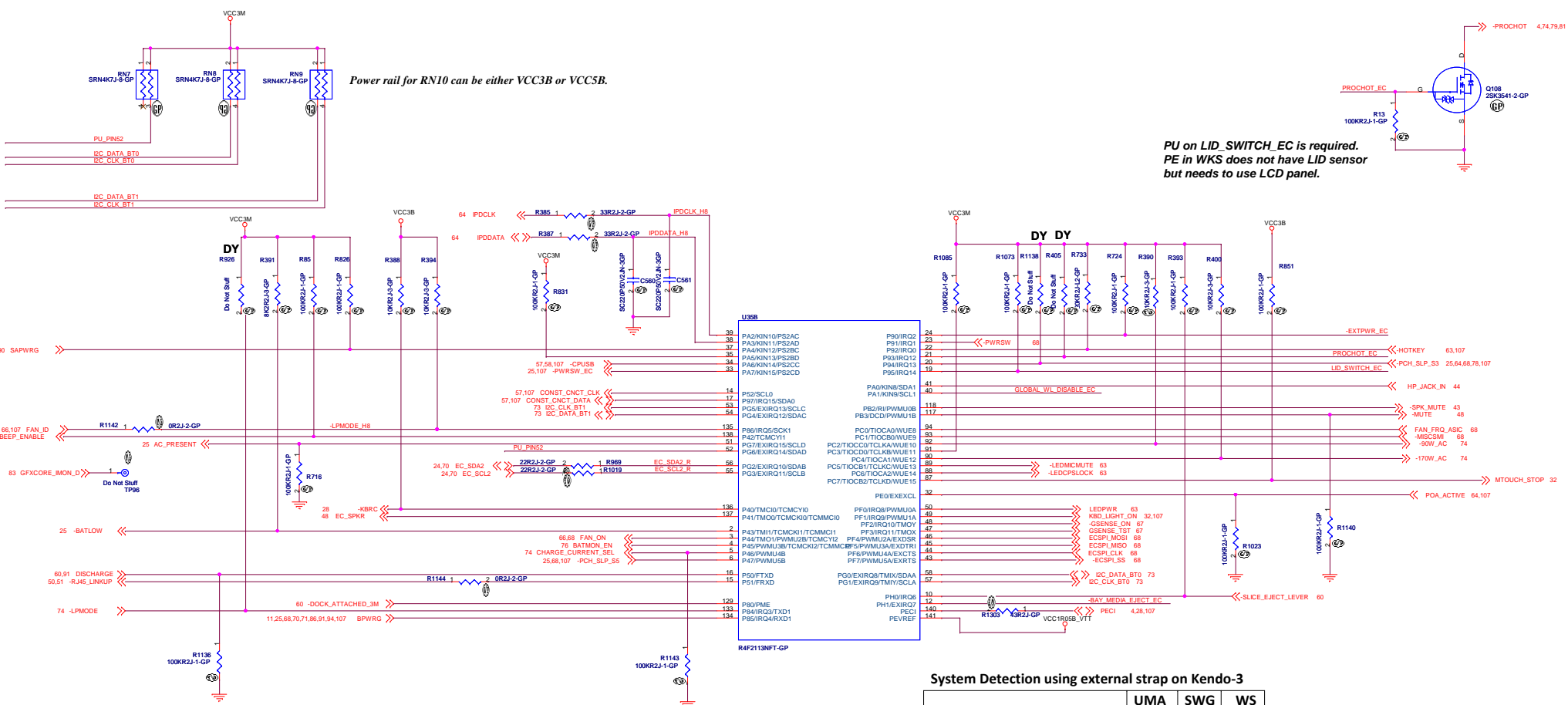


## BOM

		<b>Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.
Title: <b>SPI FLASH</b>		
Size: A3	Document Number: <b>Kendo-3 WS</b>	Rev: <b>SA</b>
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Table

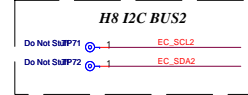
	EXT.	INT.
R831	ASM	NO_ASM
R674	NO_ASM	ASM

pls. modify this logic table

E10A Debug V/F	Enable	Disable
R392	NO_ASM	ASM
R466	NO_ASM	ASM
D25	ASM	NO_ASM
D26	ASM	NO_ASM
D20	ASM	NO_ASM
R360	ASM	ASM
R361	ASM	NO_ASM
R464	ASM	NO_ASM
R465	ASM	NO_ASM
R379	NO_ASM	ASM

LOGIC

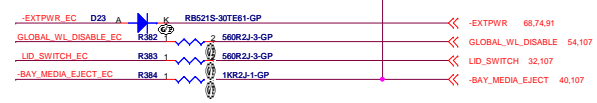
TEST PAD X2  
BOTTOM SIDE  
DO NOT MOVE AFTER FIX



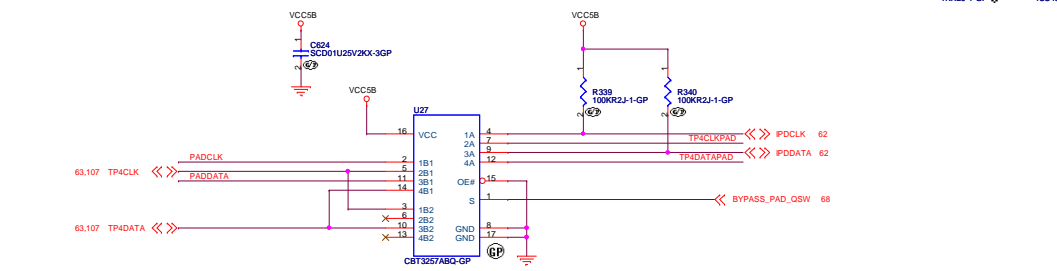
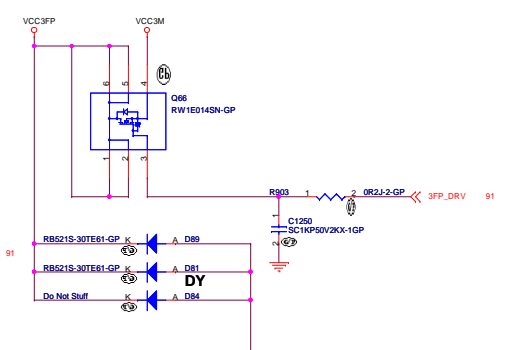
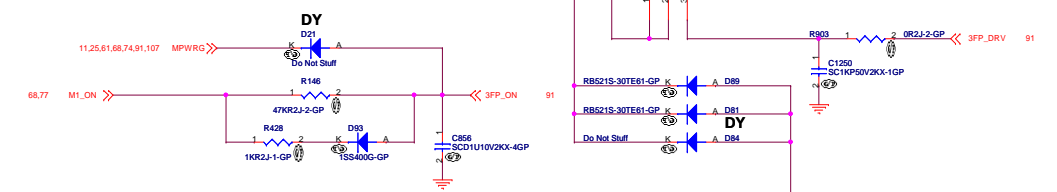
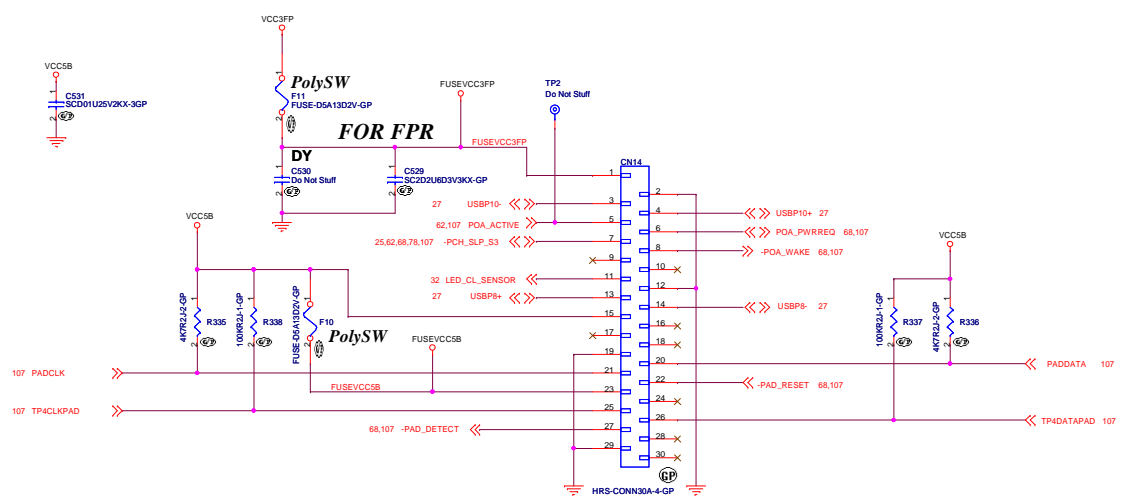
### System Detection using external strap on Kendo-3

	UMA	SWG	WS
#13 PGPIO3 of Thinker-1(U59)	L	L	H
#35 VIDEO_ID of H8(U35B)	L	H	H

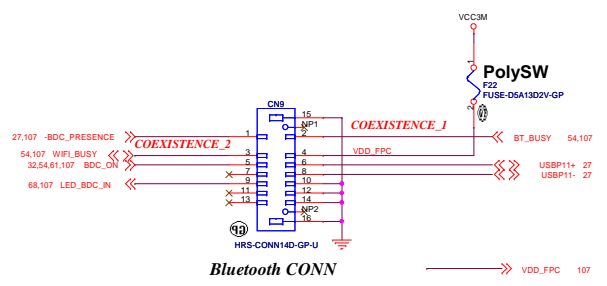
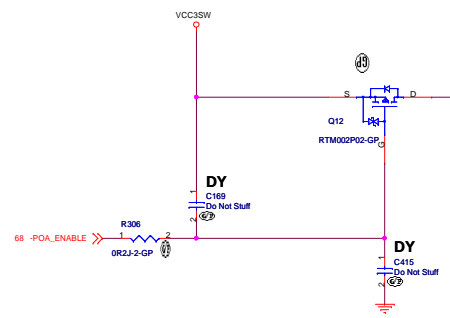
DO NOT MOVE







Delete Unused power on circuits for FPR



BOM			
<b>緯創資通 Wistron Corporation</b>			
21F, 8F, Sec.1, Hsin Tai Wu Rd., Hsichang, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
<b>TOUCH PAD CONNECTOR</b>			
Size	Document Number	Rev	
A2	Kendo-3 WS	SA	
Date:	Tuesday, December 07, 2010	Sheet	64 of 107

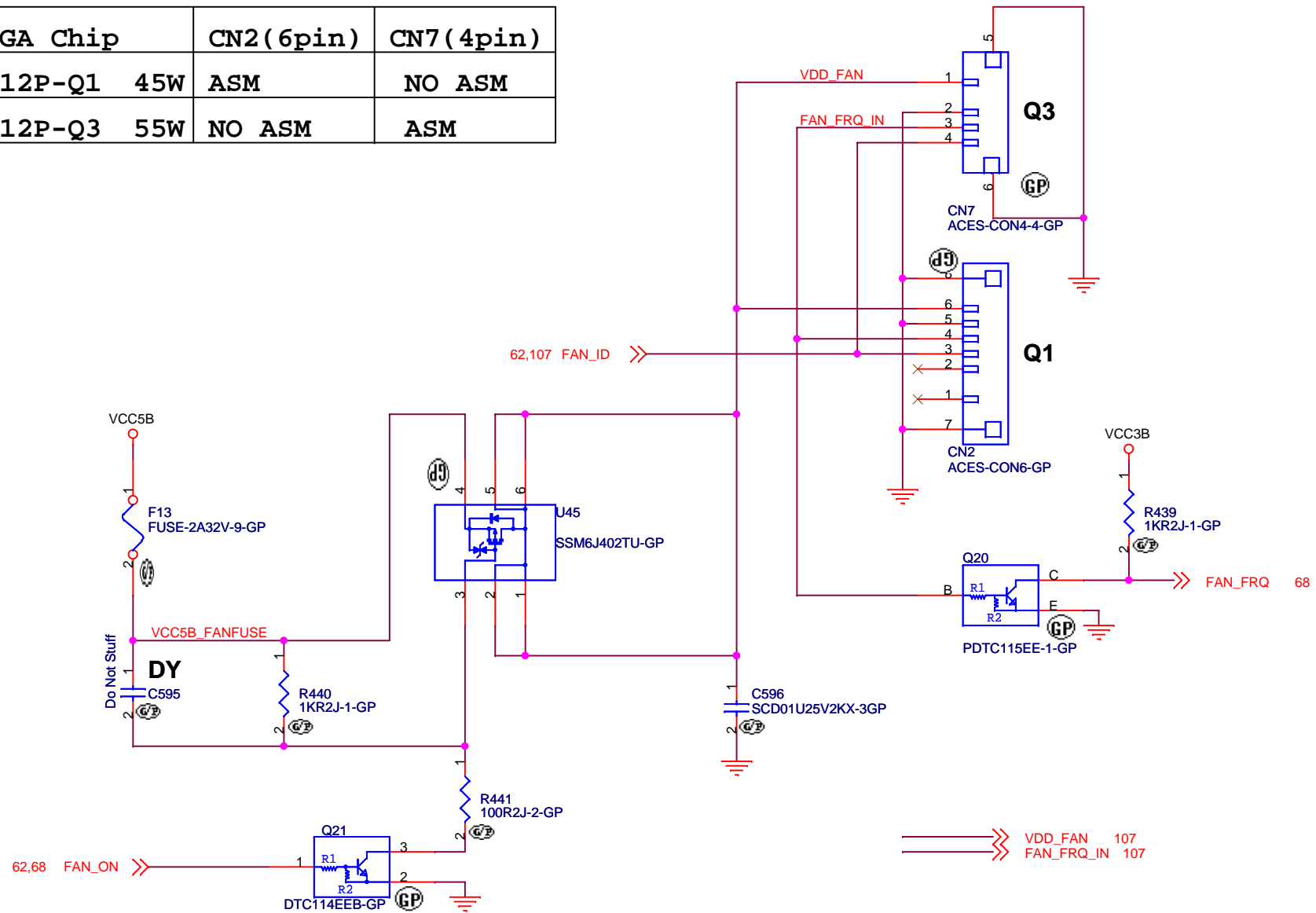


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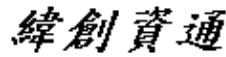
BOM

<b>緯創資通</b>		<b>Wistron Corporation</b>	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title <b>BLANK</b>			
Size A4	Document Number <b>Kendo-3 WS</b>		Rev <b>SA</b>
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VGA Chip		CN2 (6pin)	CN7 (4pin)
N12P-Q1	45W	ASM	NO ASM
N12P-Q3	55W	NO ASM	ASM

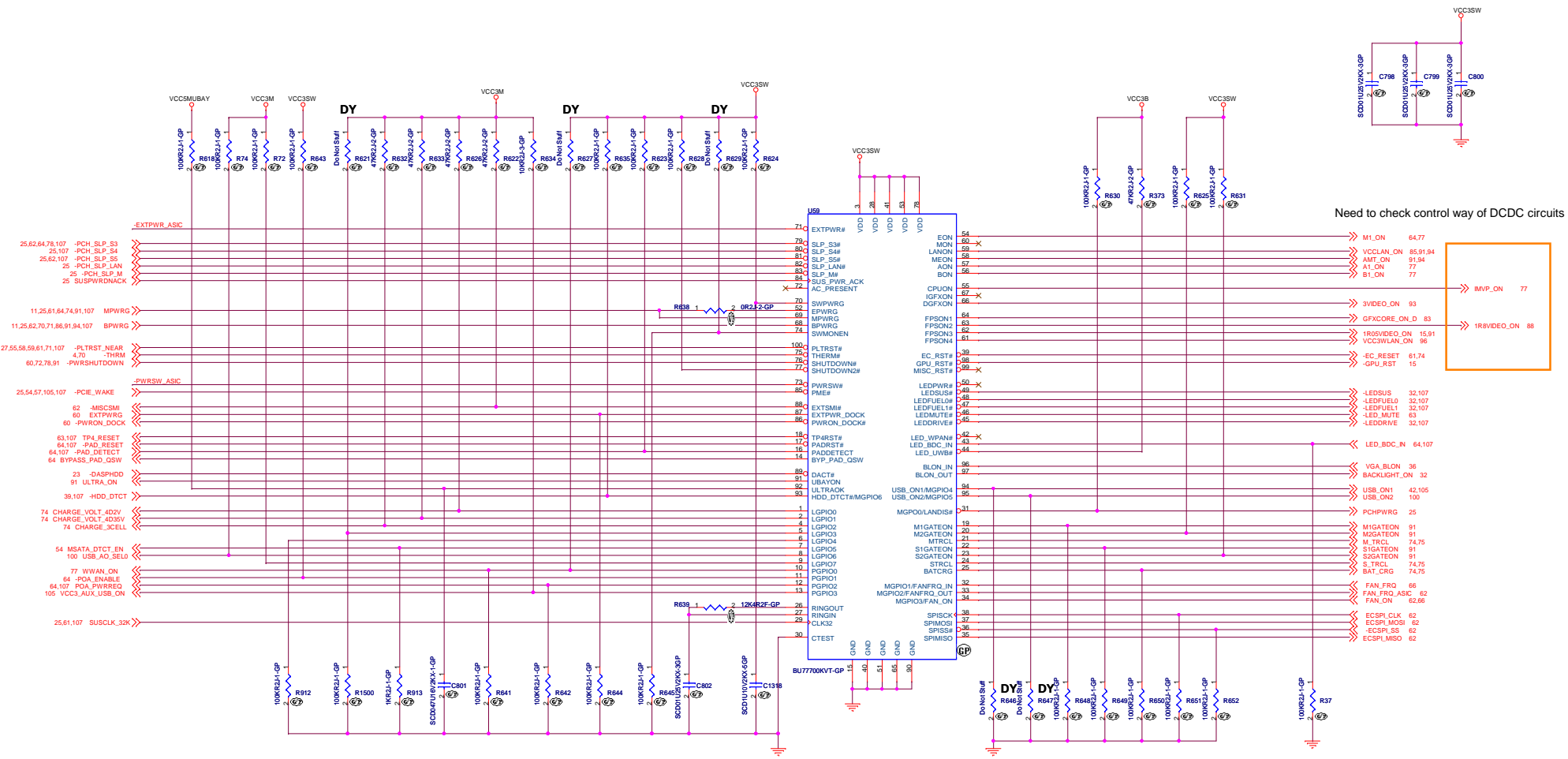


BOM

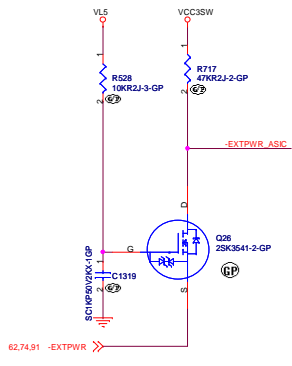
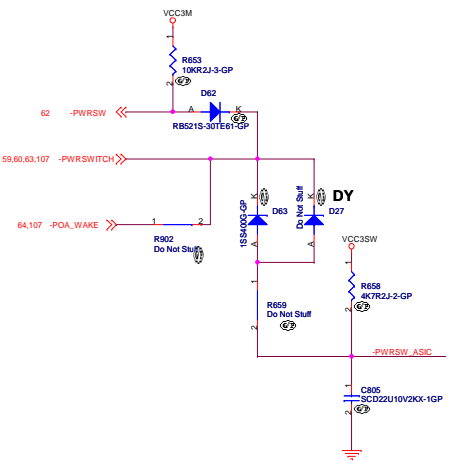
 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>FAN CONTROL</b>		
Size A4	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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Need to check control way of DCDC circuits



Supplier	Vendo P/N	WISTRON P/N
1 ROHM	BU77700KVT	71.77700.00G
2 TOSHIBA	TC200G02EFG-1036JQZ	71.20002.B0G



1023 update -> chand 1R8VIDEO\_PLL\_ON to 1R05VIDEO\_PLL\_ON

**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsien Tai Wu Rd., Hsuehchi,  
 Taipei Hsien 221, Taiwan, R.O.C.

File: **THINKER-1**

Size: A2 Document Number: **Kendo-3 WS** Rev: SA

Date: Tuesday, December 07, 2010 Sheet: 68 of 107

5

4

3

2

1

D

D

C

C

B

B

A

A

5

4

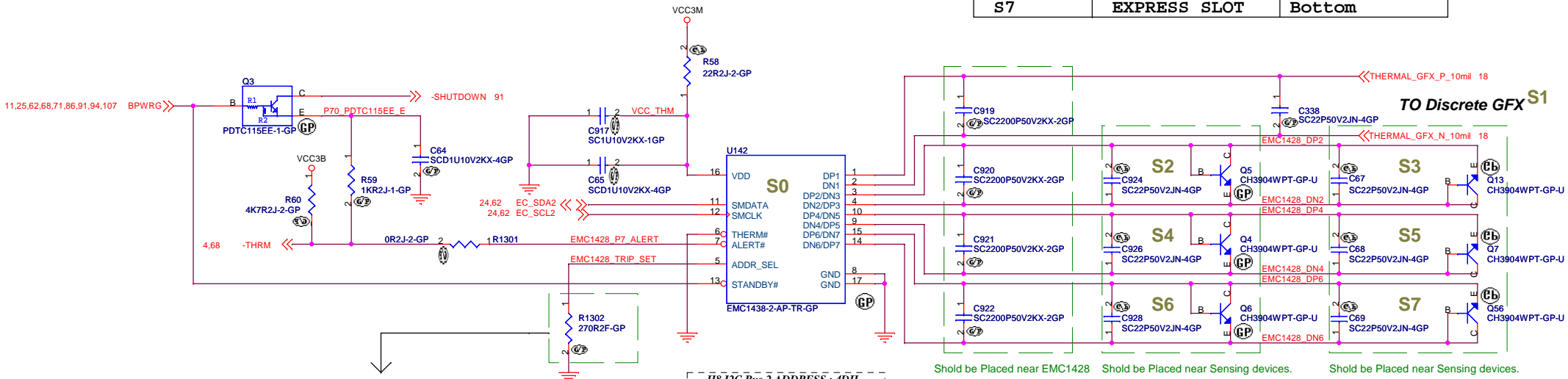
3

2

1

<b>BOM</b>			
Title			
<Title>			
Size	Document Number	Rev	
C	<Doc>	<Rev>	<Code>
Date:	Tuesday, December 07, 2010	Sheet	69 of 107

Sensor	Device	Placed on
S0 (Body)	PCH/BASE COVER	Bottom
S1	GFX_D	Top
S2	GBE	Bottom
S3	WWAN	Top
S4	DIMM(TOP)	Top
S5	DIMM(BOT)	Bottom
S6	WLAN	Top
S7	EXPRESS SLOT	Bottom



Resister Value	SMBUS Address
GND	1001 100, 4Ch
270	1001 101, 4Dh
560	1001 110, 4Eh
1K	1001 111, 4Fh
1.5K	1001 001, 49h
2.7K	1001 010, 4Ah
5.6K	1001 011, 4Bh
>=18K	0011 000, 18h

H8 I2C Bus 2 ADDRESS : 4DH

Sensor Location will be decided based on the placement.

- Layout Comment :
- (1) Thermal sensor trace lines should not be overlapped with other high frequency trace lines in other layers.
  - (2) Also, it should not be overlapped with large amplitude trace lines either.

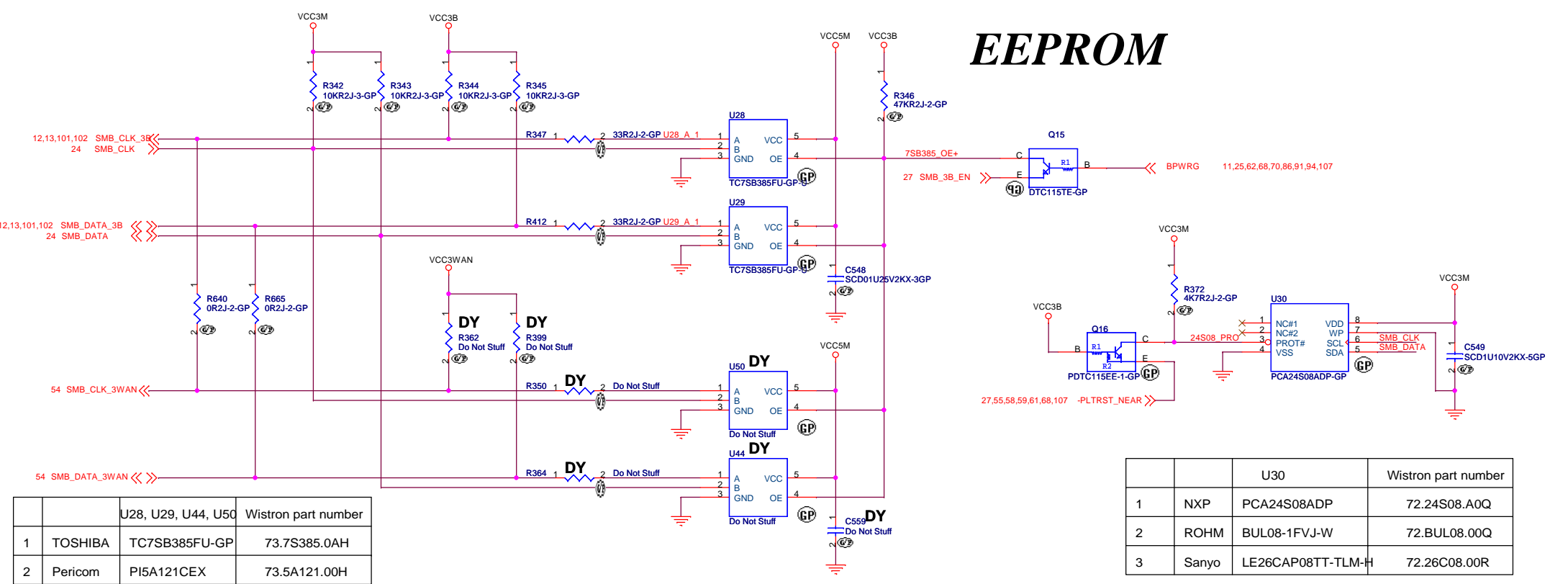
Should be Placed near EMC1428    Should be Placed near Sensing devices.    Should be Placed near Sensing devices.

Logic →

BOM

<b>緯創資通 Wistron Corporation</b>	
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>THERMAL SENSOR</b>	
Size A3	Document Number <b>Kendo-3 WS</b>
Date: Tuesday, December 07, 2010	Sheet 70 of 107

# EEPROM

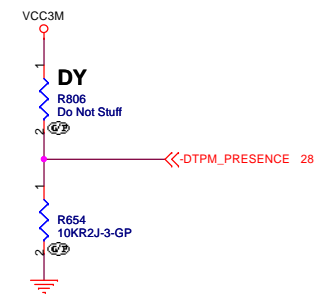
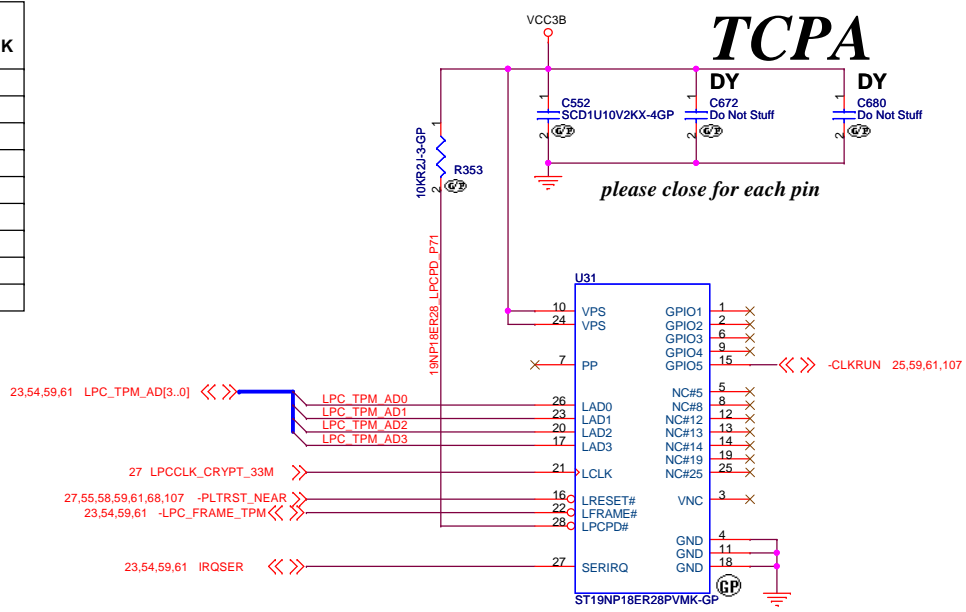


		U28, U29, U44, U50	Wistron part number
1	TOSHIBA	TC7SB385FU-GP	73.7S385.0AH
2	Pericom	PI5A121CEX	73.5A121.00H

		U30	Wistron part number
1	NXP	PCA24S08ADP	72.24S08.A0Q
2	ROHM	BUL08-1FVJ-W	72.BUL08.00Q
3	Sanyo	LE26CAP08TT-TLM-H	72.26C08.00R

	NO TPM	ST Micro ST19NP18ER28PVMK
U31	NO_ASM	ASM
C552	NO_ASM	ASM
C672	NO_ASM	NO_ASM
R354	NO_ASM	ASM
R371	NO_ASM	NO_ASM
R953	NO_ASM	NO_ASM
R353	NO_ASM	NO_ASM
R806	ASM	NO_ASM
R654	NO_ASM	ASM

↑  
**LOGIC**



**BOM**

**緯創資通 Wistron Corporation**  
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **EEPROM/TCPA**

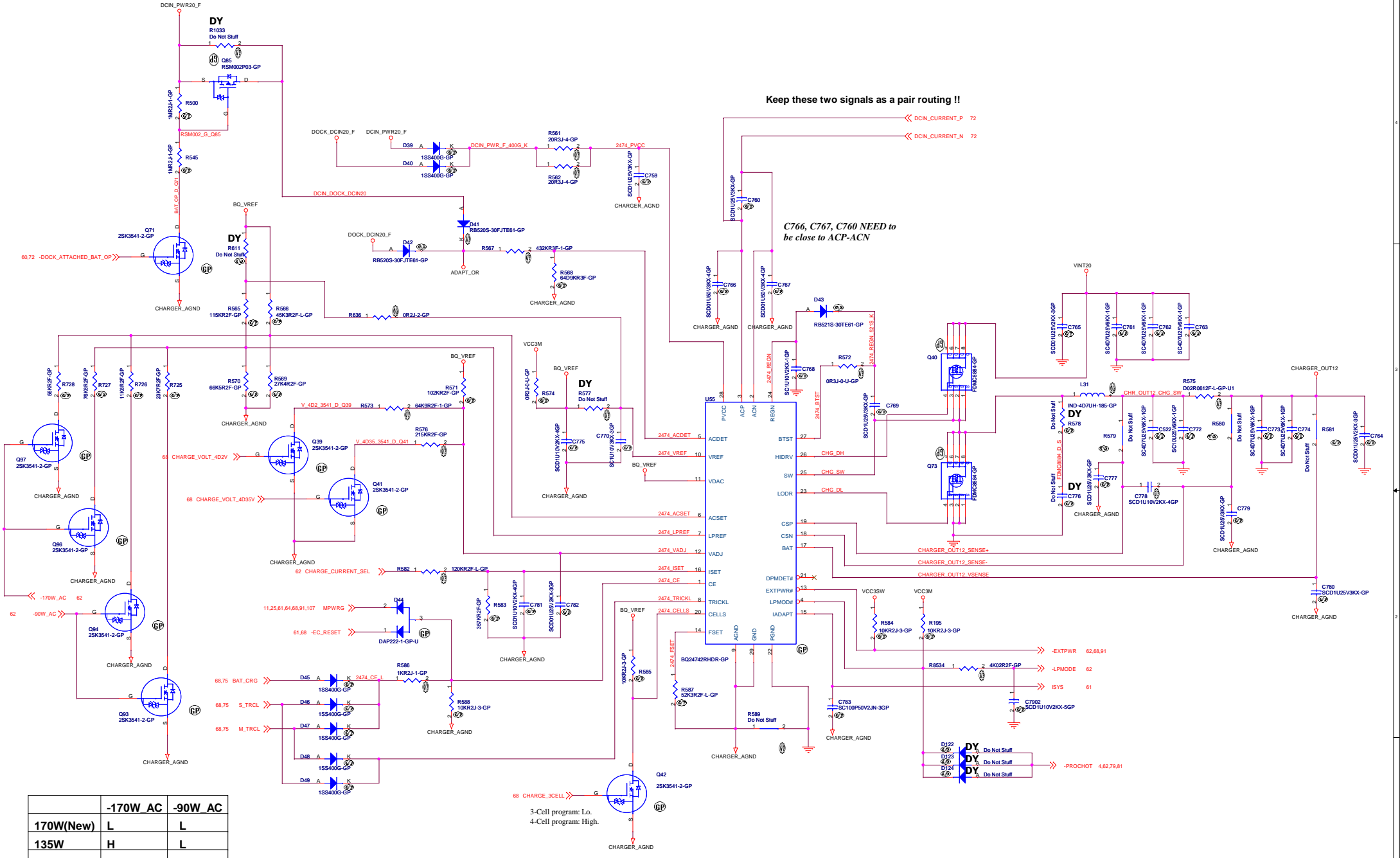
Size: A3 | Document Number: **Kendo-3 WS** | Rev: **SA**

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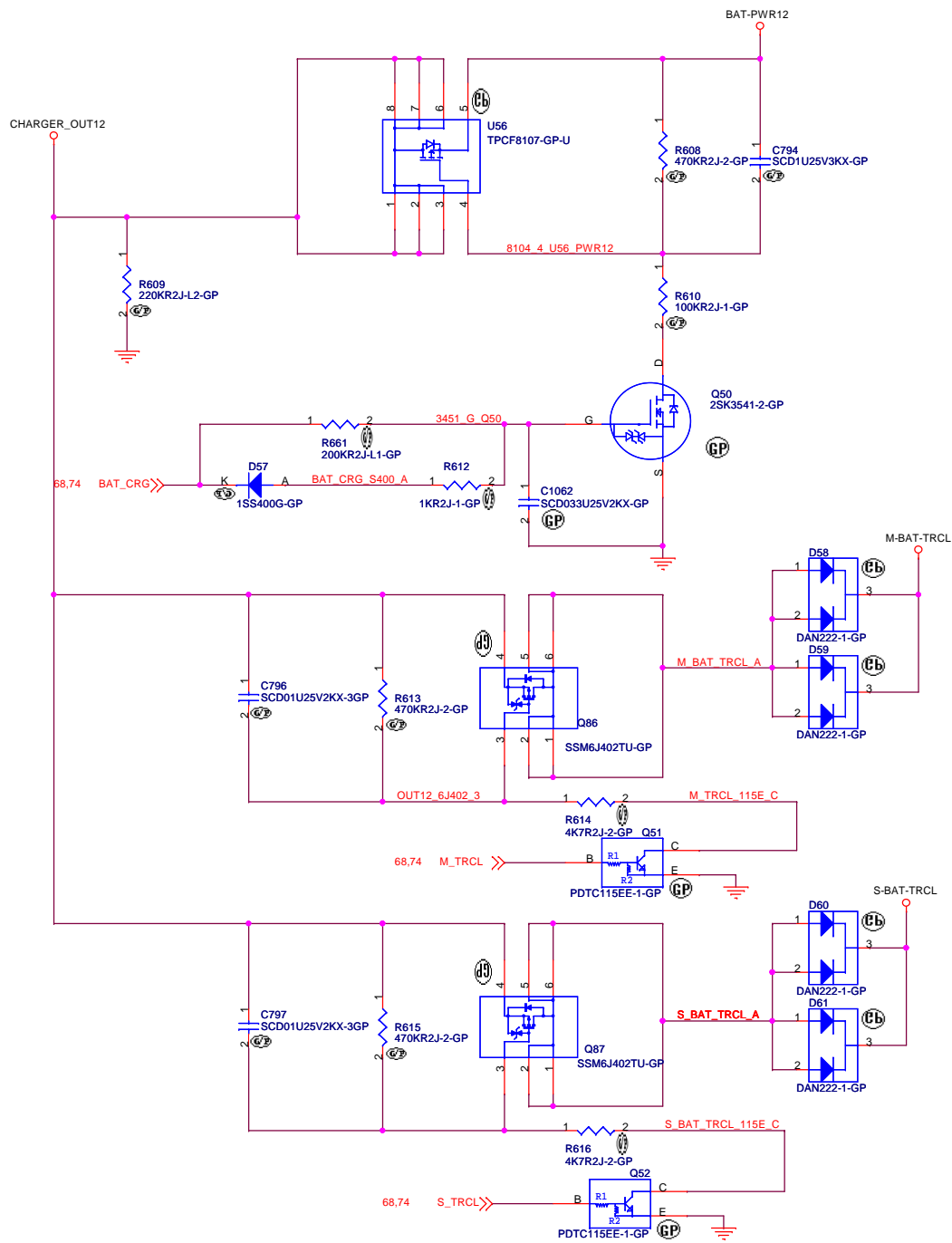






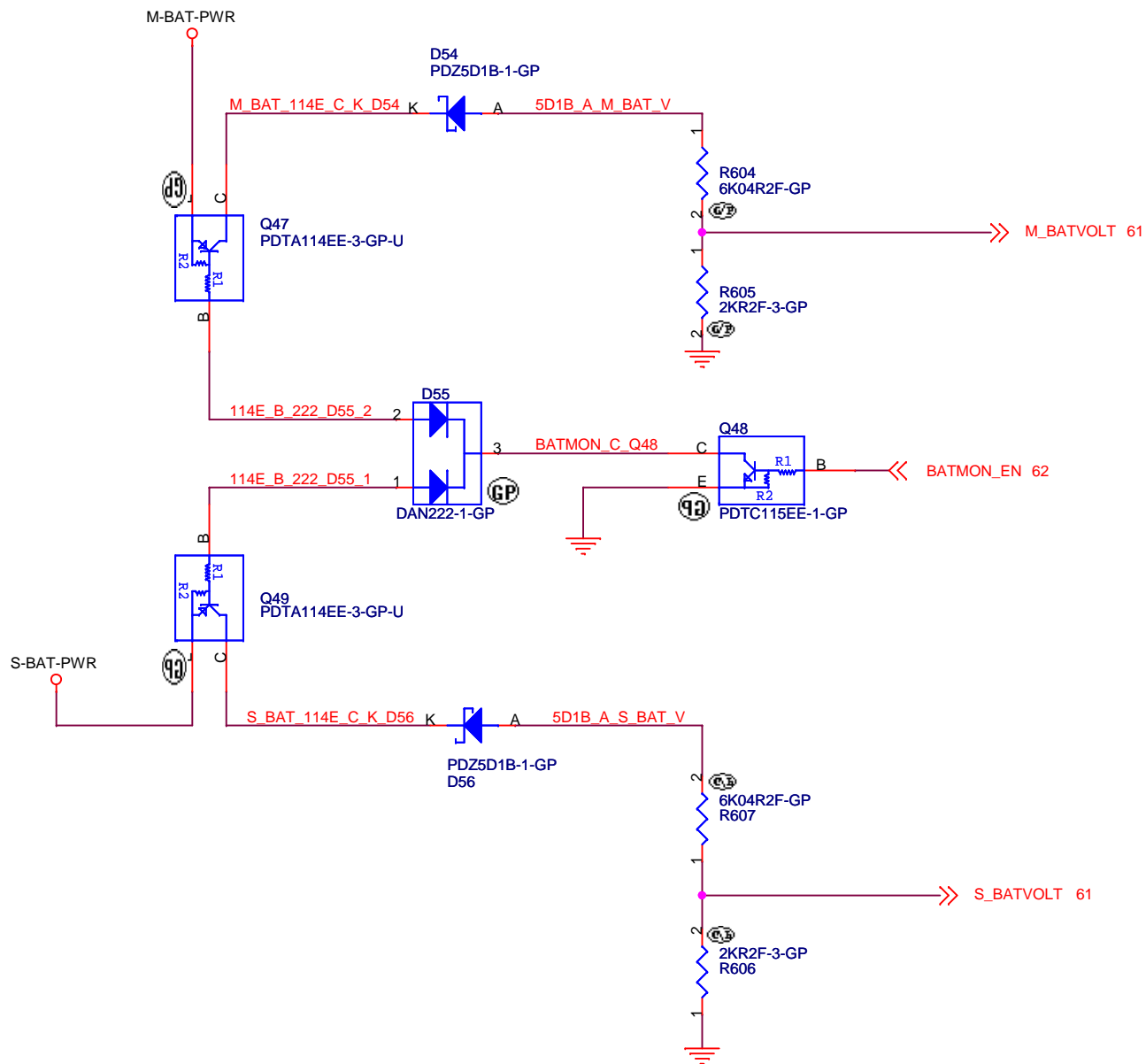
	-170W AC	-90W AC
170W(New)	L	L
135W	H	L
65W/90W	H	H

3-Cell program: Lo.  
4-Cell program: High.



<b>緯創資通 Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>CHARGER SELECT</b>		
Title Size A3	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
Date: Tuesday, December 07, 2010 Sheet 75 of 107		

$$V_{OUT} = 0.249 (V_{BAT} - 5)$$



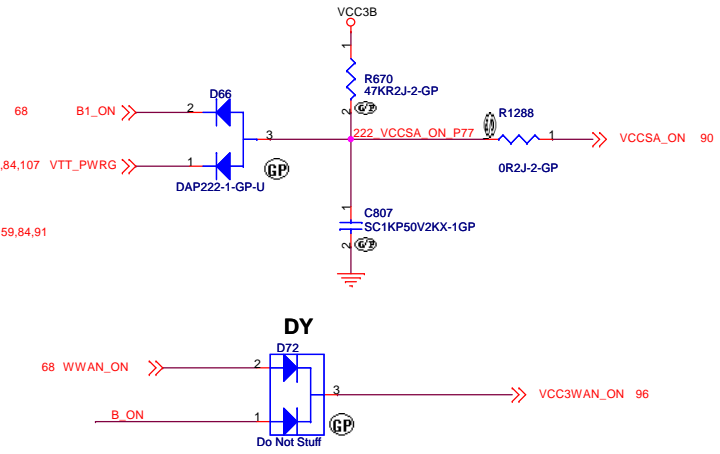
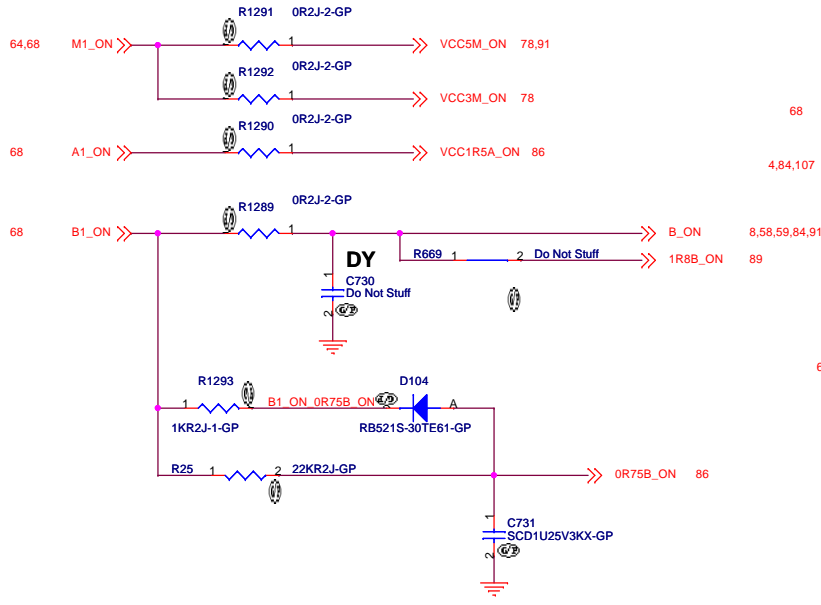
BOM

**緯創資通** **Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

Title  
**BATTERY MONITOR**

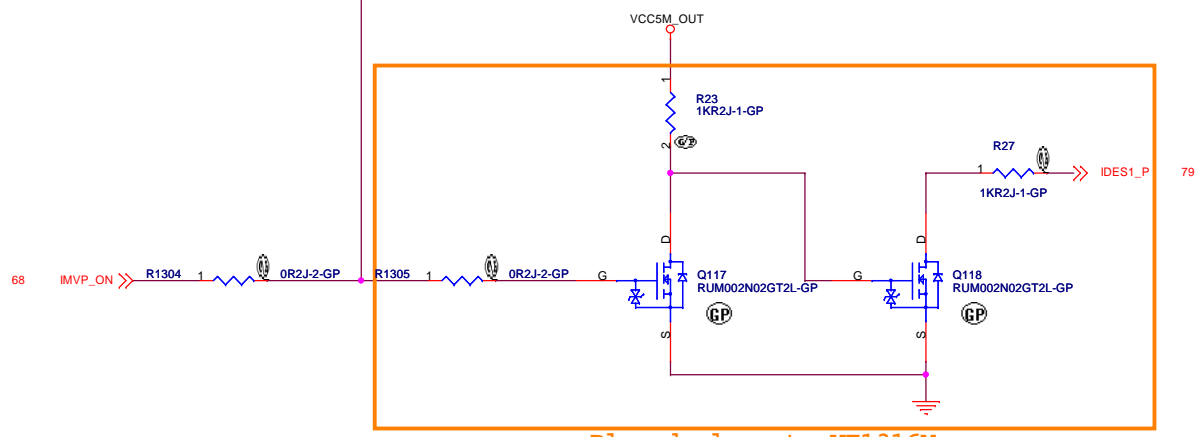
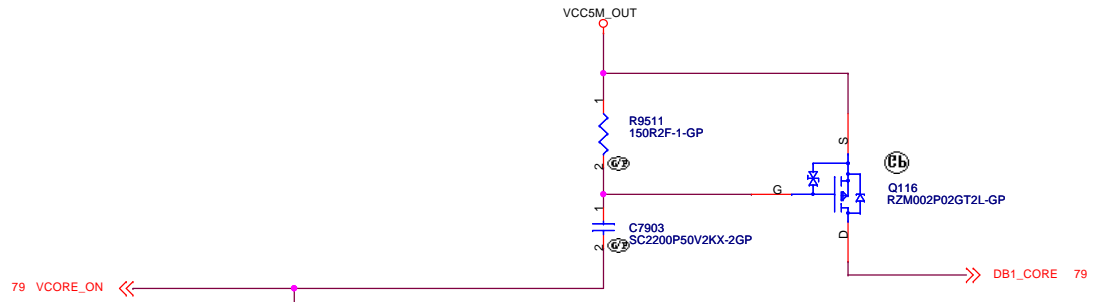
Size A4	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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**Table**

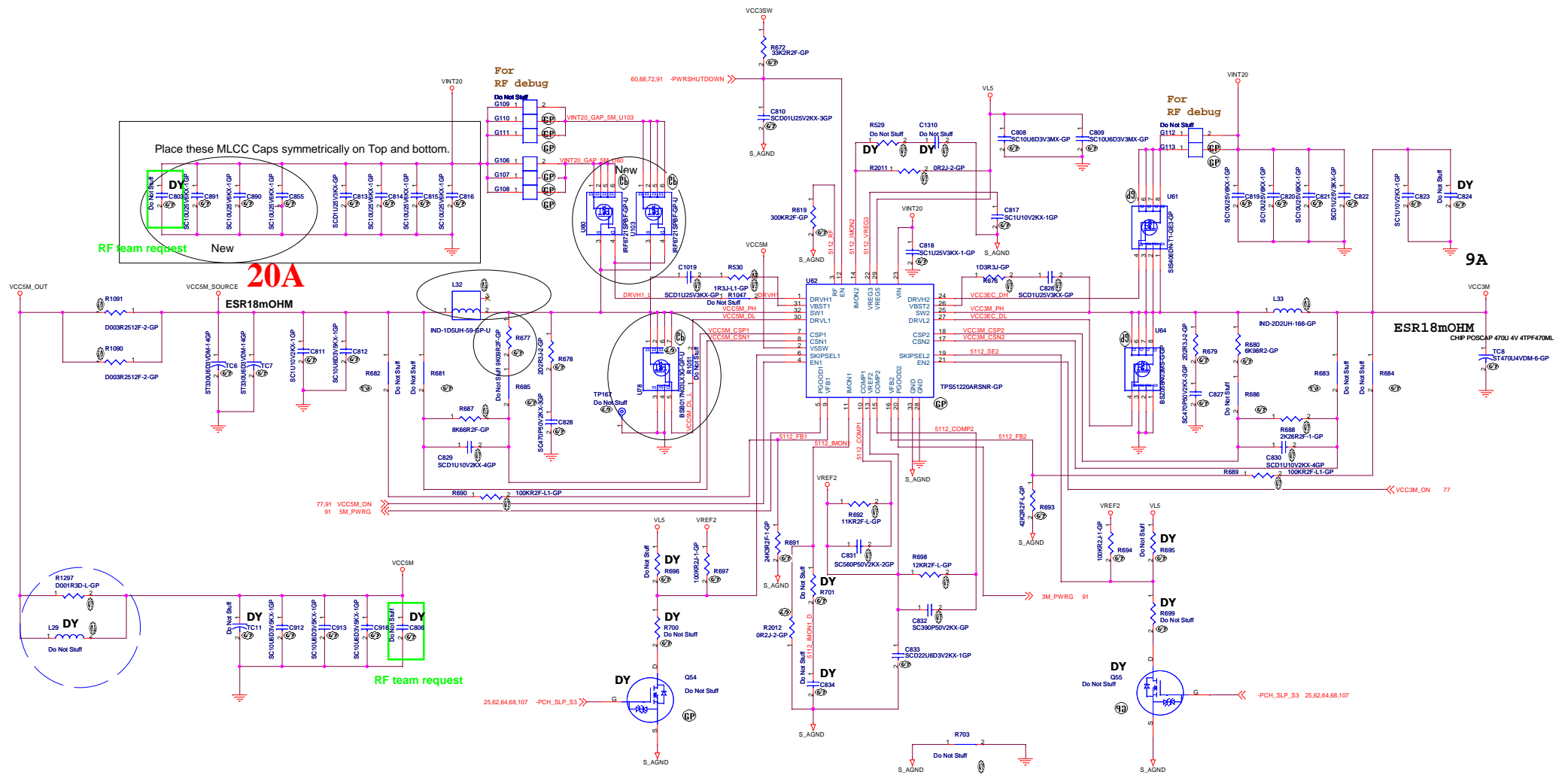
CONSTANT CONNECT	YES	NO
D72	ASM	NO_ASM



Placed close to VT1316M

BOM

<b>Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title: <b>POWER SEQUENCE</b>		
Size: A3	Document Number: <b>Kendo-3 WS</b>	Rev: SA
Date: Tuesday, December 07, 2010	Sheet: 77 of 107	





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BOM

<b>緯創資通</b>		<b>Wistron Corporation</b>	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title <b>BLANK</b>			
Size A4	Document Number <b>Kendo-3 WS</b>		Rev <b>SA</b>
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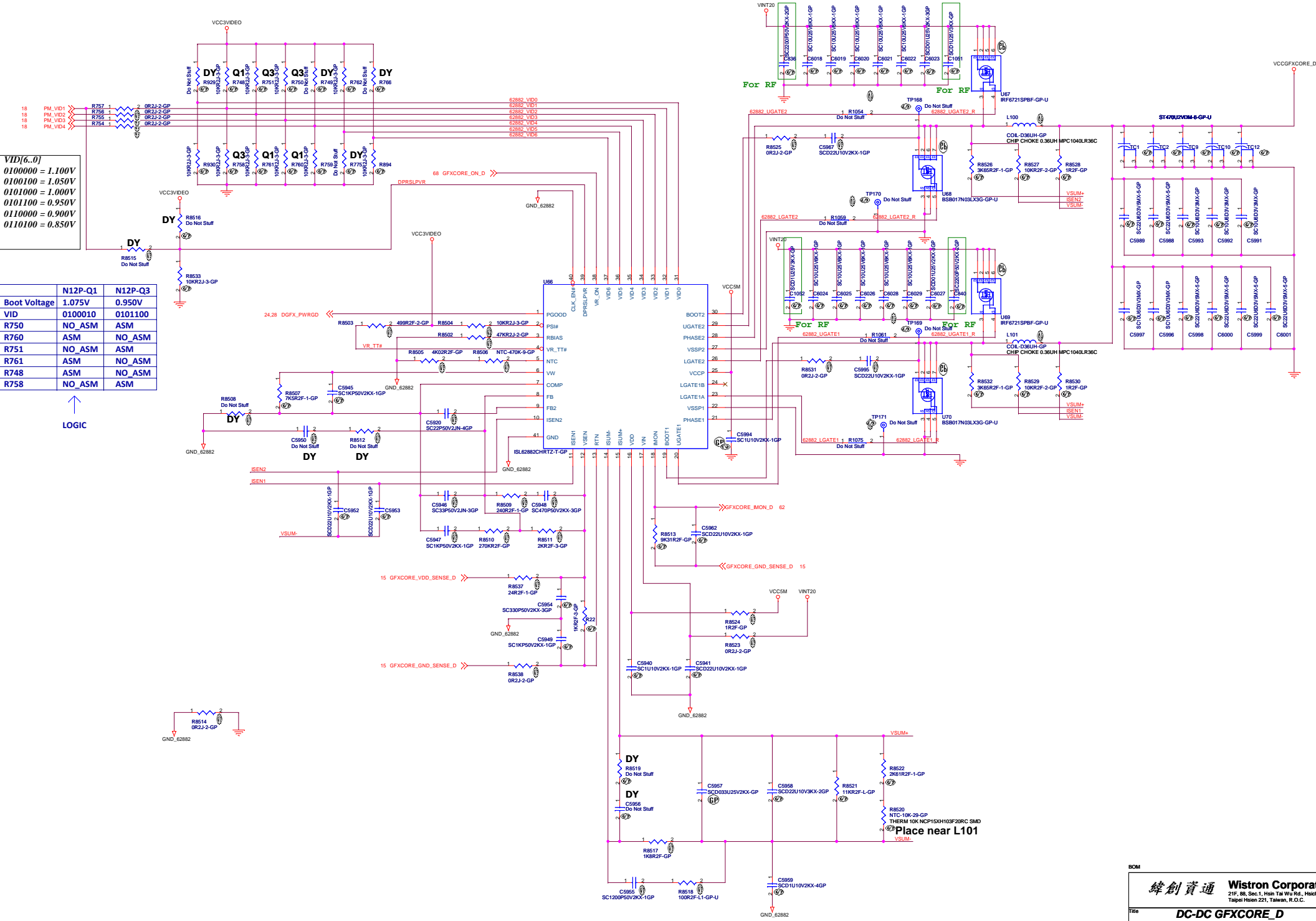
BOM

<b>緯創資通</b>		<b>Wistron Corporation</b>	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title <b>BLANK</b>			
Size A4	Document Number <b>Kendo-3 WS</b>		Rev <b>SA</b>
Date: Tuesday, December 07, 2010		Sheet 82	of 107

VID[6..0]  
 0100000 = 1.100V  
 0100100 = 1.050V  
 0101000 = 1.000V  
 0101100 = 0.950V  
 0110000 = 0.900V  
 0110100 = 0.850V

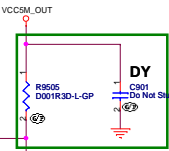
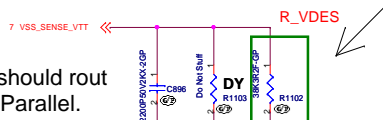
	N12P-Q1	N12P-Q3
Boot Voltage	1.075V	0.950V
VID	0100010	0101100
R750	NO_ASM	ASM
R760	ASM	NO_ASM
R751	NO_ASM	ASM
R761	ASM	NO_ASM
R748	ASM	NO_ASM
R758	NO_ASM	ASM

LOGIC



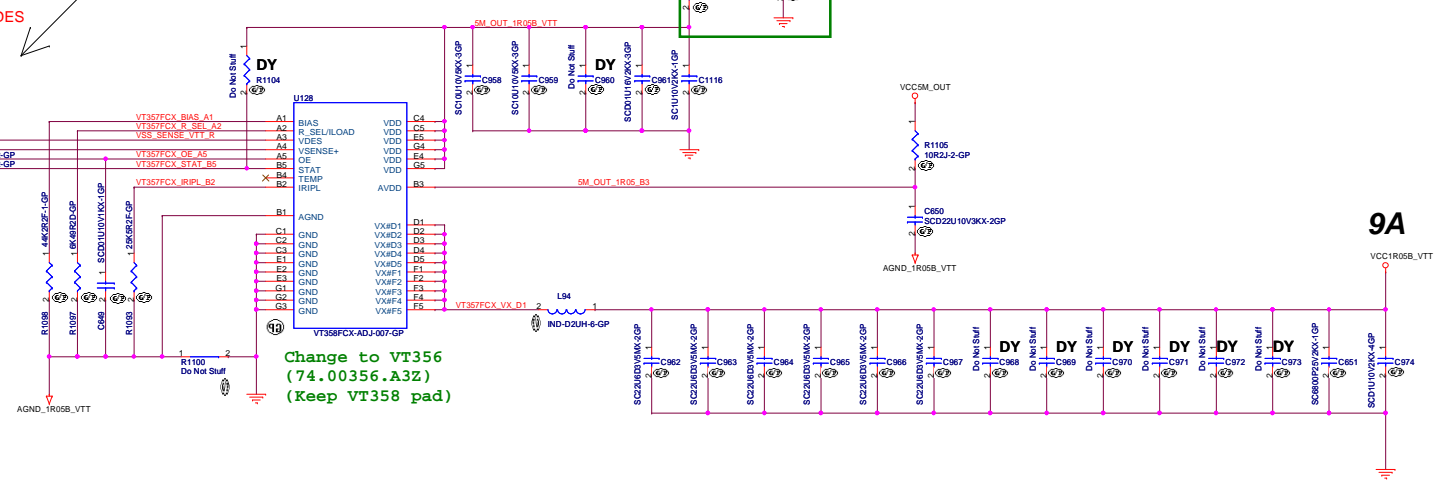
VOUT	Parameter
1.10V	R_VDES = 40.2K
1.05V	R_VDES = 38.3K
$VOUT = 1.212 \times R\_VDES / 44.2K$	

VCC\_SENSE Trace should rout to VSS\_VSENSE in Parallel.



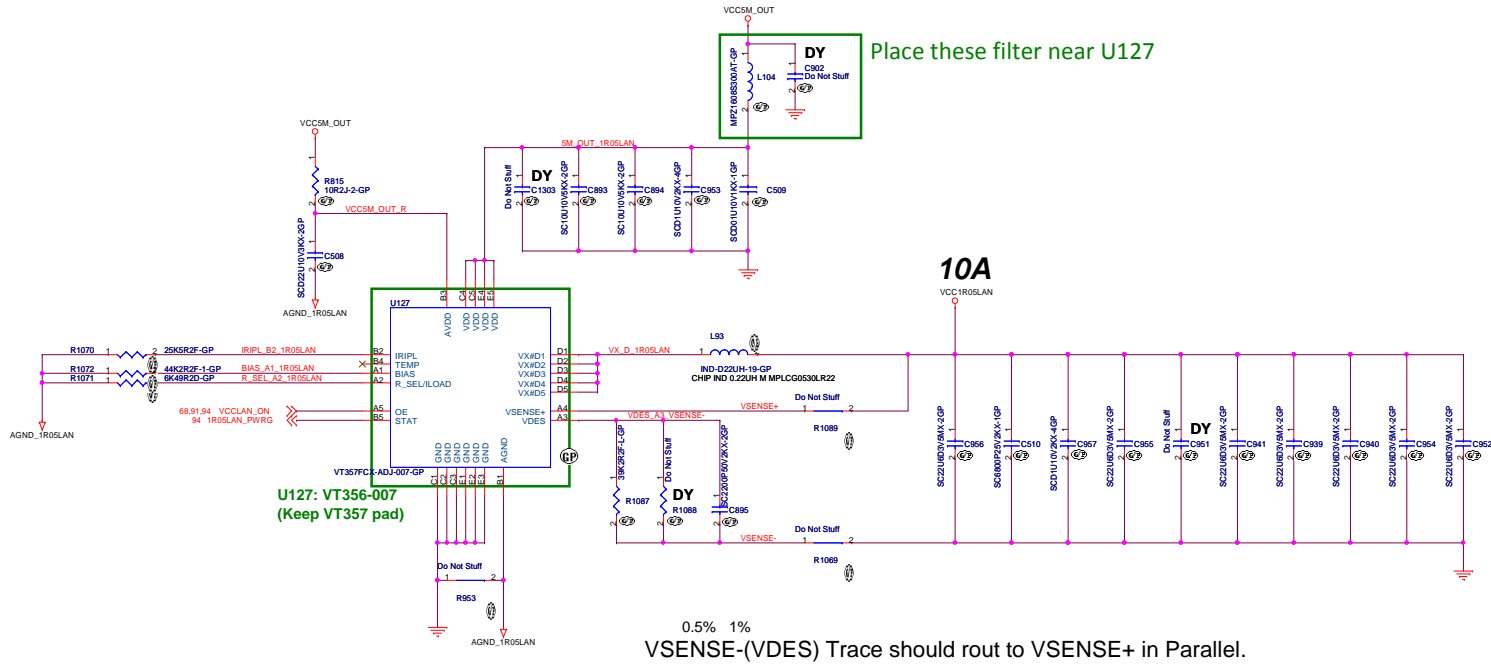
Place these filter near U128

7 VCC\_SENSE\_VTT  
8.54,59,77,81 @ CN  
4,7,10,7 VTT\_PWRG



Change to VT356  
(74.00356.A3Z)  
(Keep VT358 pad)

9A

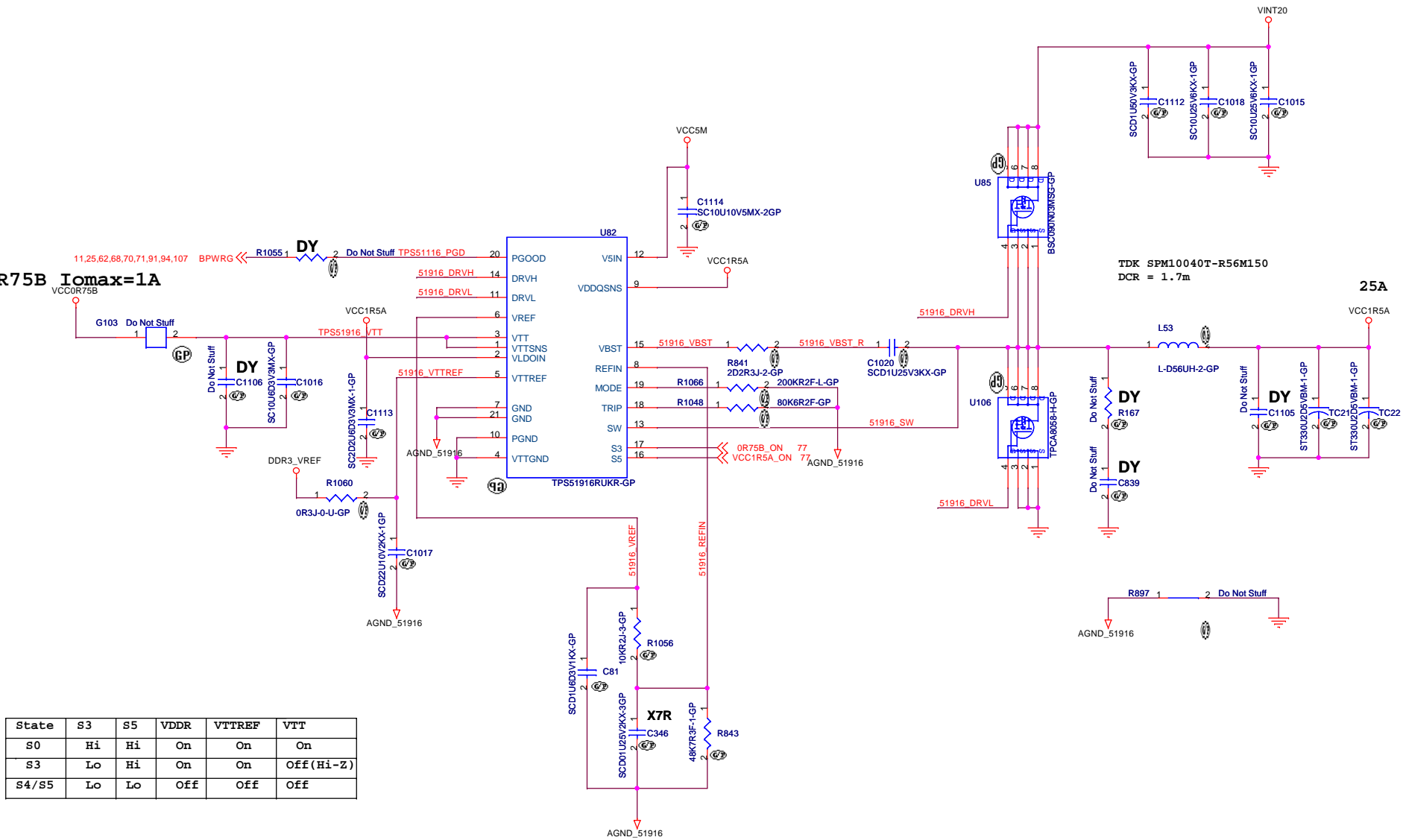


Place these filter near U127

0.5% 1%  
VSENSE-(VDES) Trace should rout to VSENSE+ in Parallel.

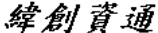
BOM			
緯創資通		Wistron Corporation	
21F, 8th, Sec.1, Hsin Tai Wu Rd., Hsichang, Taipei Hsien 221, Taiwan, R.O.C.			
Title VT357 VCC1R05LAN			
Size A2	Document Number	Kendo-3 WS	Rev SA
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VCC0R75B I<sub>omax</sub>=1A  
VCC0R75B



State	S3	S5	VDDR	VTTREF	VTT
S0	Hi	Hi	On	On	On
S3	Lo	Hi	On	On	Off (Hi-Z)
S4/S5	Lo	Lo	Off	Off	Off

BOM

 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>DC-DC VCC0R75B</b>		
File	Kendo-3 WS	
Size A3	Document Number	Rev SA
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BOM

 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>Title</b> <b>BLANK</b>	
<b>Size</b> A4	<b>Document Number</b> <b>Kendo-3 WS</b>
<b>Date:</b> Tuesday, December 07, 2010	<b>Rev</b> <b>SA</b>
<b>Date:</b> Tuesday, December 07, 2010	
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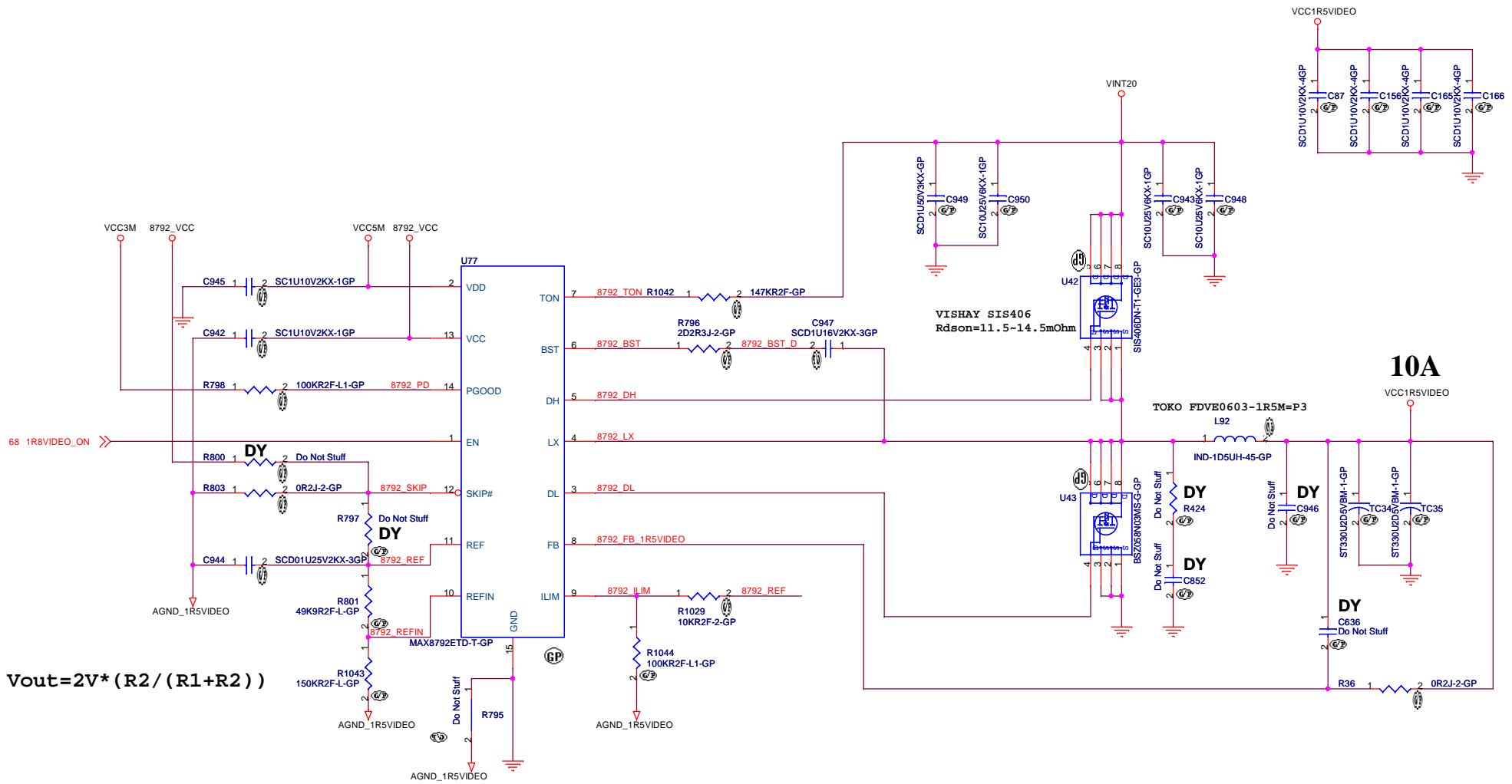
A

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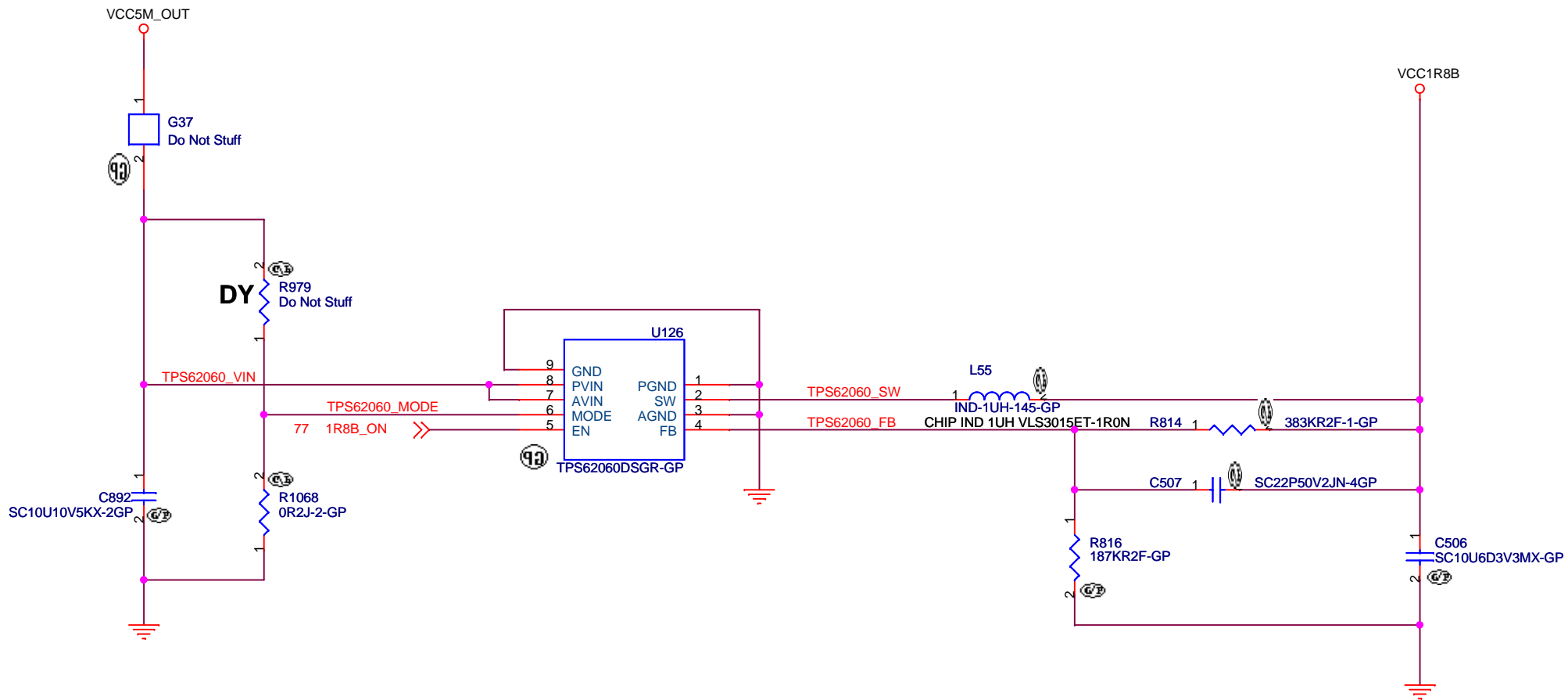
E



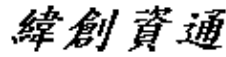
BOM

<p><b>緯創資通 Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.</p>		
<p><b>DC-DC VCC1R5VIDEO</b></p>		
Title		
Size	Document Number	Rev
A3	<b>Kendo-3 WS</b>	SA
Date:	Tuesday, December 07, 2010	Sheet 88 of 107



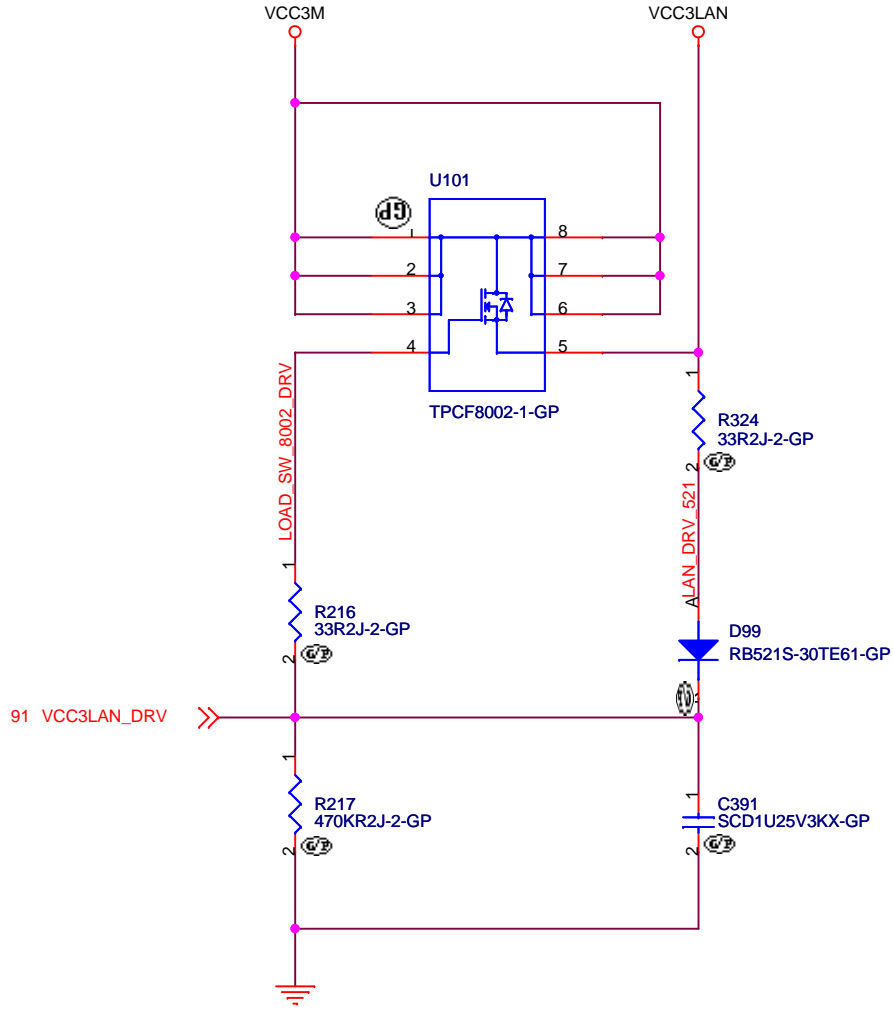


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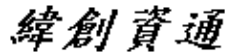
 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>DC-DC VCC1R8B</b>	
Size A4	Document Number <b>Kendo-3 WS</b>
Date: Tuesday, December 07, 2010	Rev <b>SA</b>
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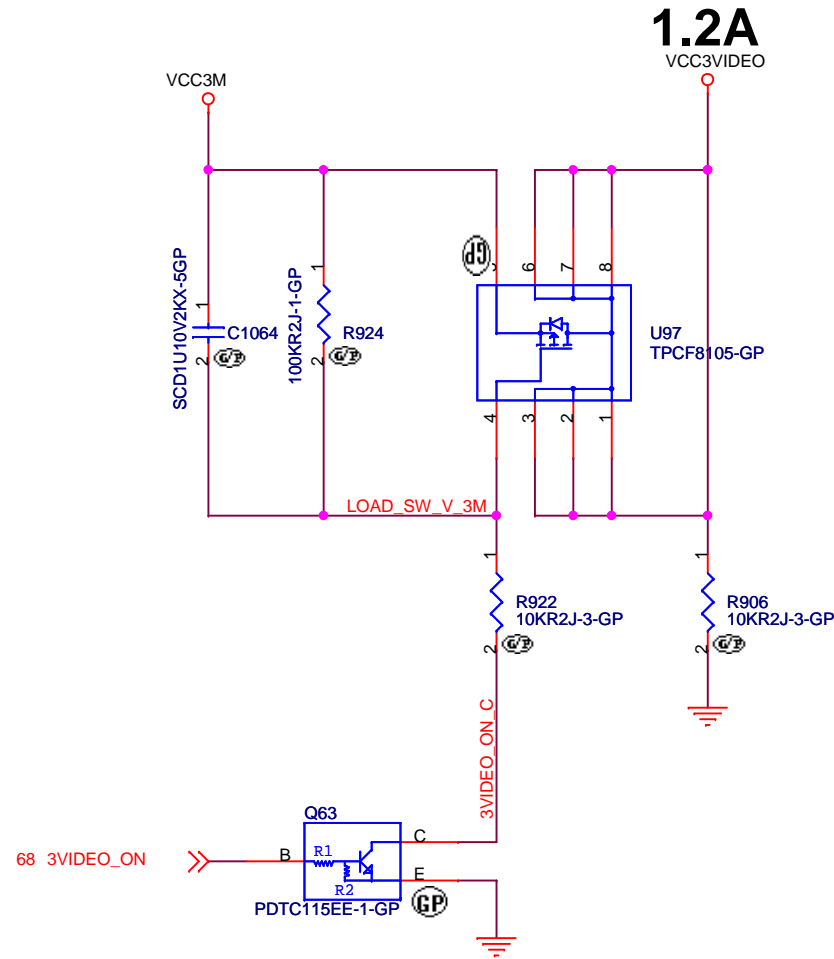




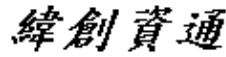


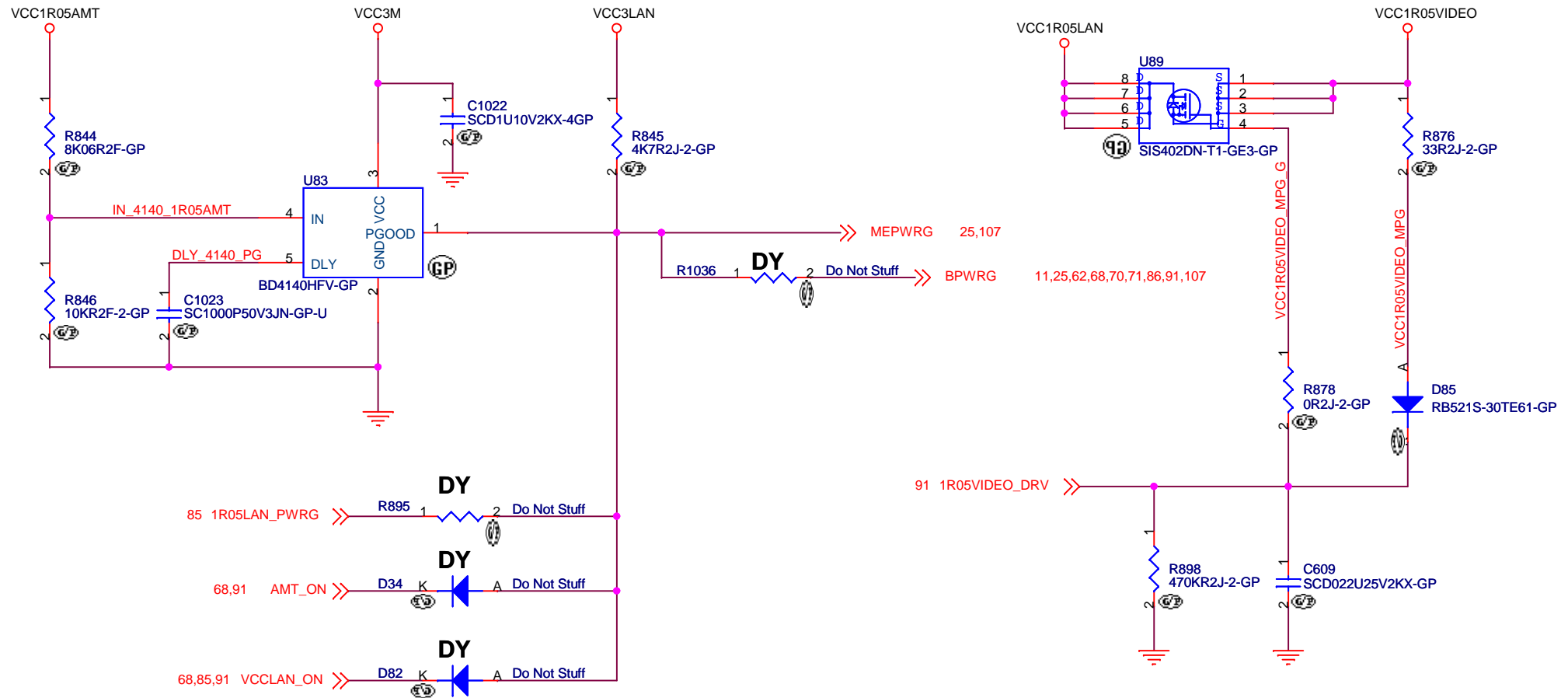
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 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>LOAD SW LAN &amp; LANPWRG</b>	
Size A4	Document Number <b>Kendo-3 WS</b>
Date: Tuesday, December 07, 2010	Rev <b>SA</b>
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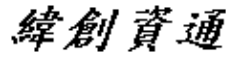


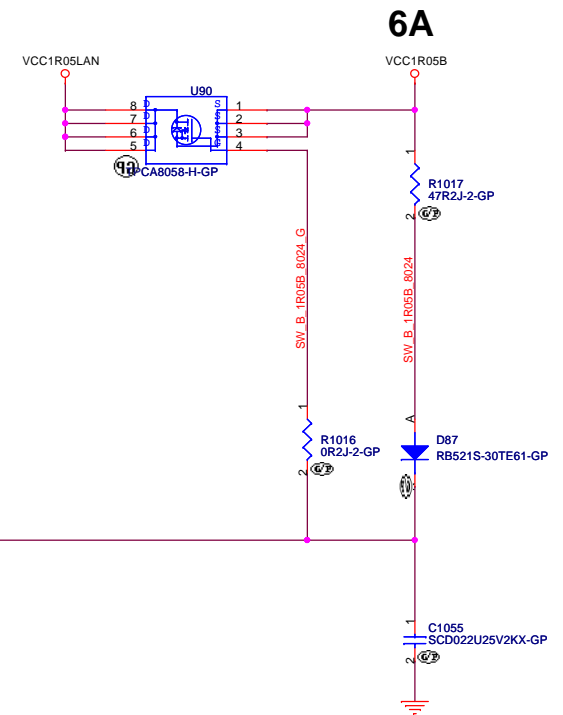
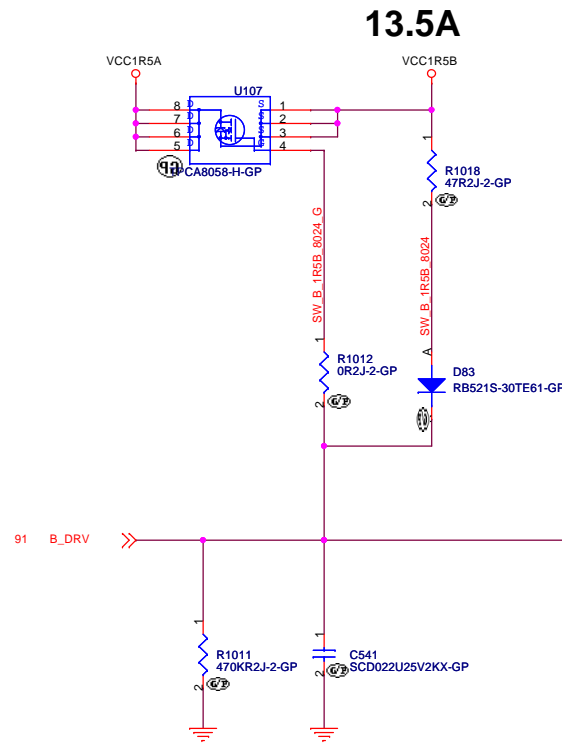
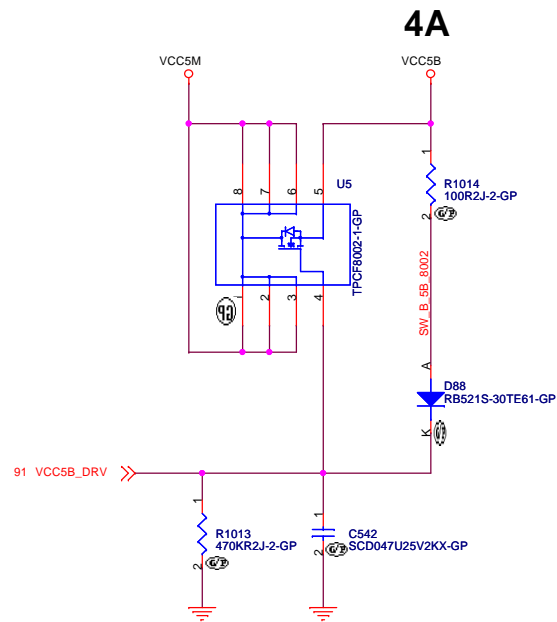
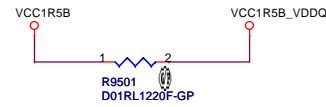
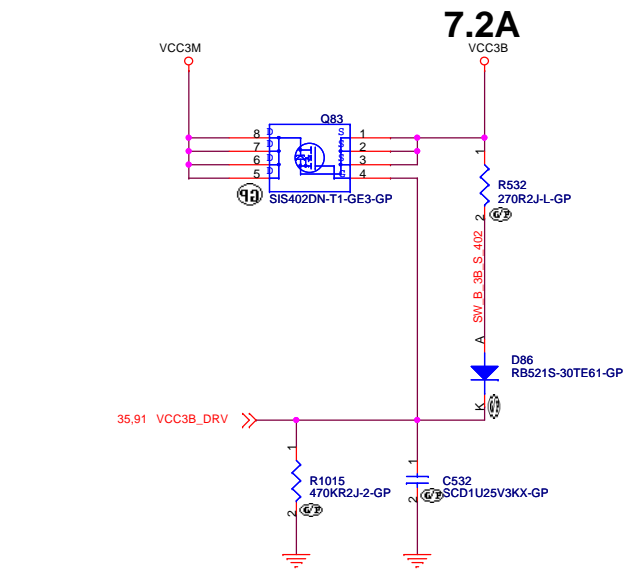
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 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>LOAD SW VIDEO</b>		
Size A4	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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BOM

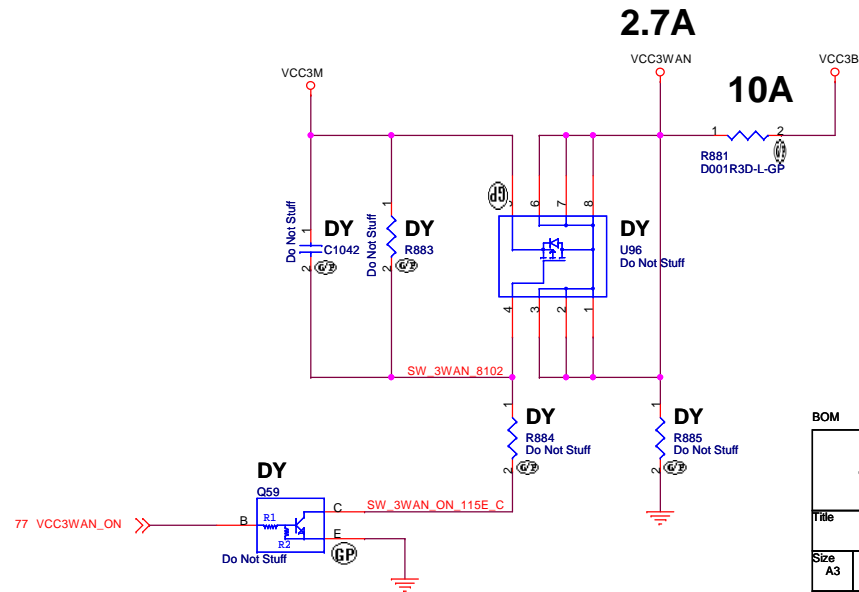
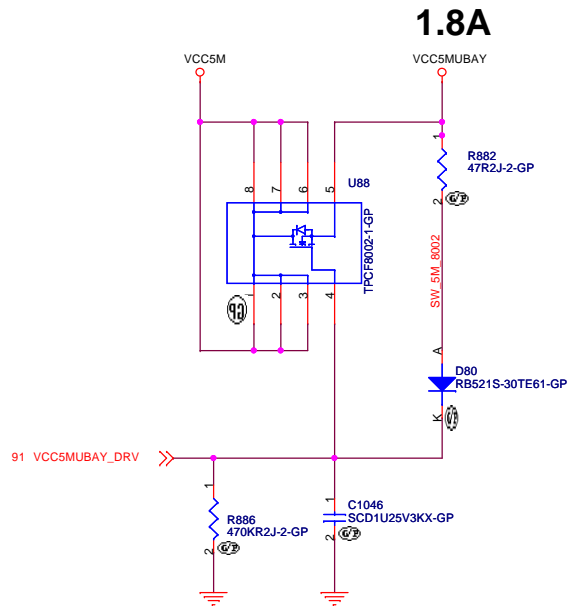
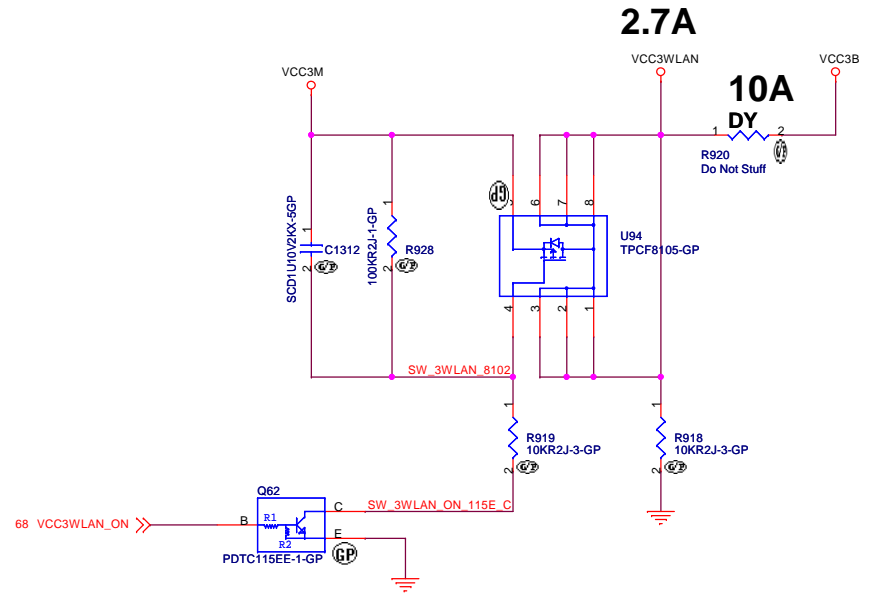
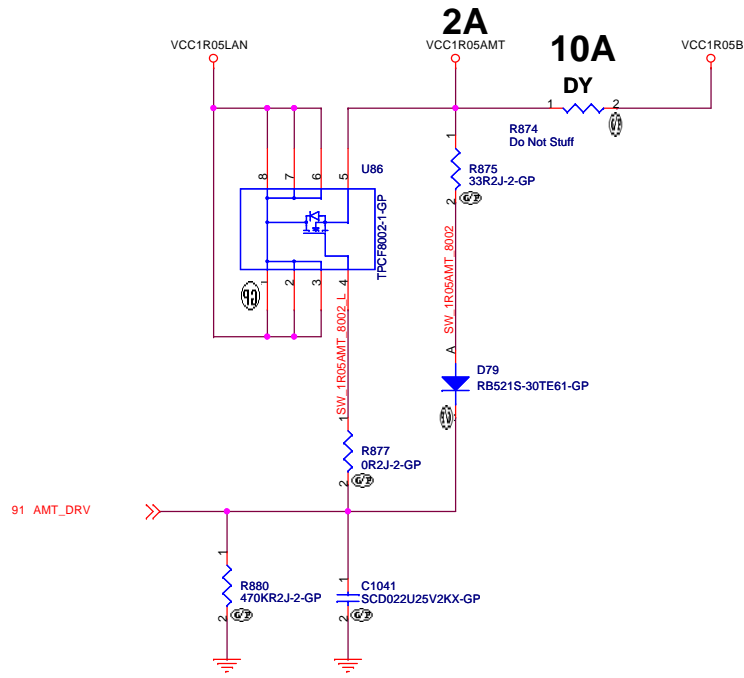
 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>SW AMT/MEPWRG</b>		
Size A4	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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BOM


**緯創資通** Wistron Corporation  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

Title			<b>LOAD SW B</b>
Size	Document Number	Rev	
A3		SA	
Date:	Tuesday, December 07, 2010	Sheet	95 of 107



	REG/LITE	BB/NO
R881	NO-ASM	ASM
U96	ASM	NO-ASM
R885	ASM	NO-ASM
R883	ASM	NO-ASM
C1042	ASM	NO-ASM
R884	ASM	NO-ASM
Q59	ASM	NO-ASM

BOM

 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>LOAD SW VCC5MBAY</b>		
File	Document Number	Rev
Size A3	<b>Kendo-3 WS</b>	<b>SA</b>
Date: Tuesday, December 07, 2010	Sheet 96 of 107	



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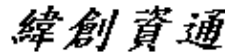
2

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Title <b>BLANK</b>	Document Number <b>Kendo-3 WS</b>
Size A4	Rev <b>SA</b>
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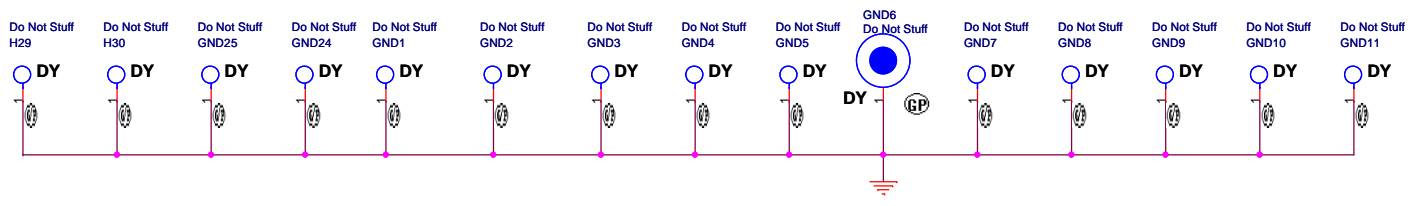
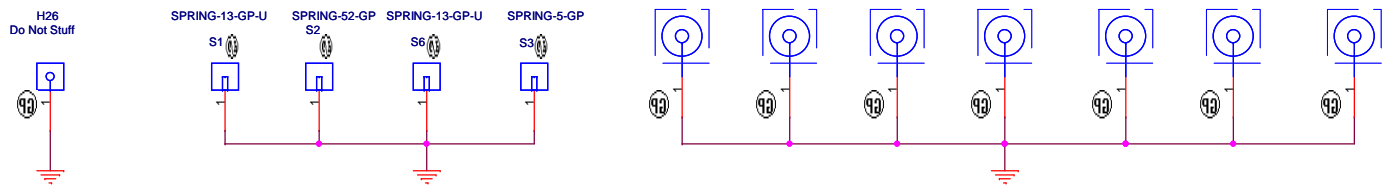
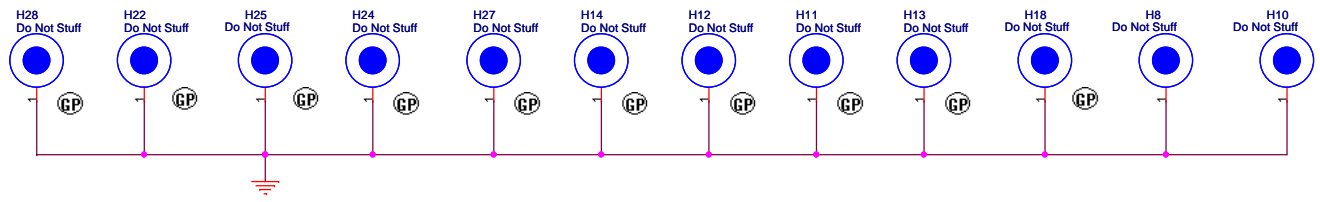
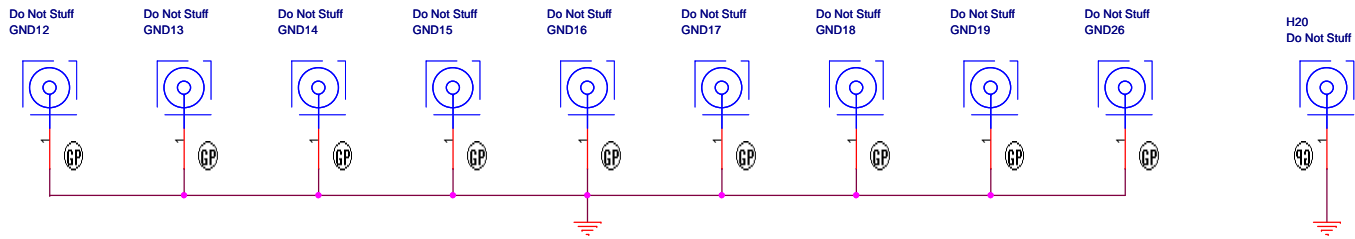
A

B

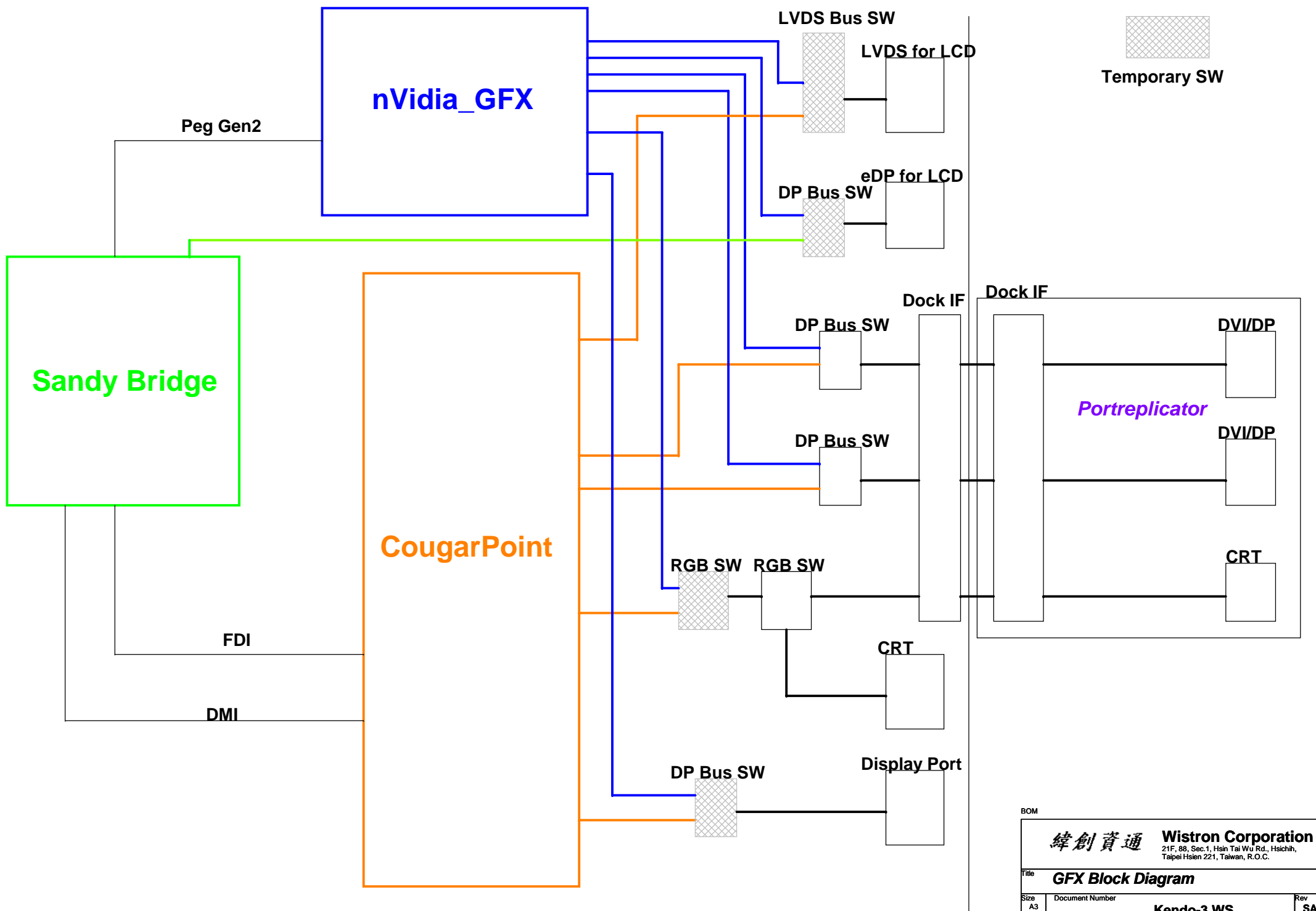
C

D

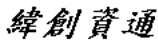
E

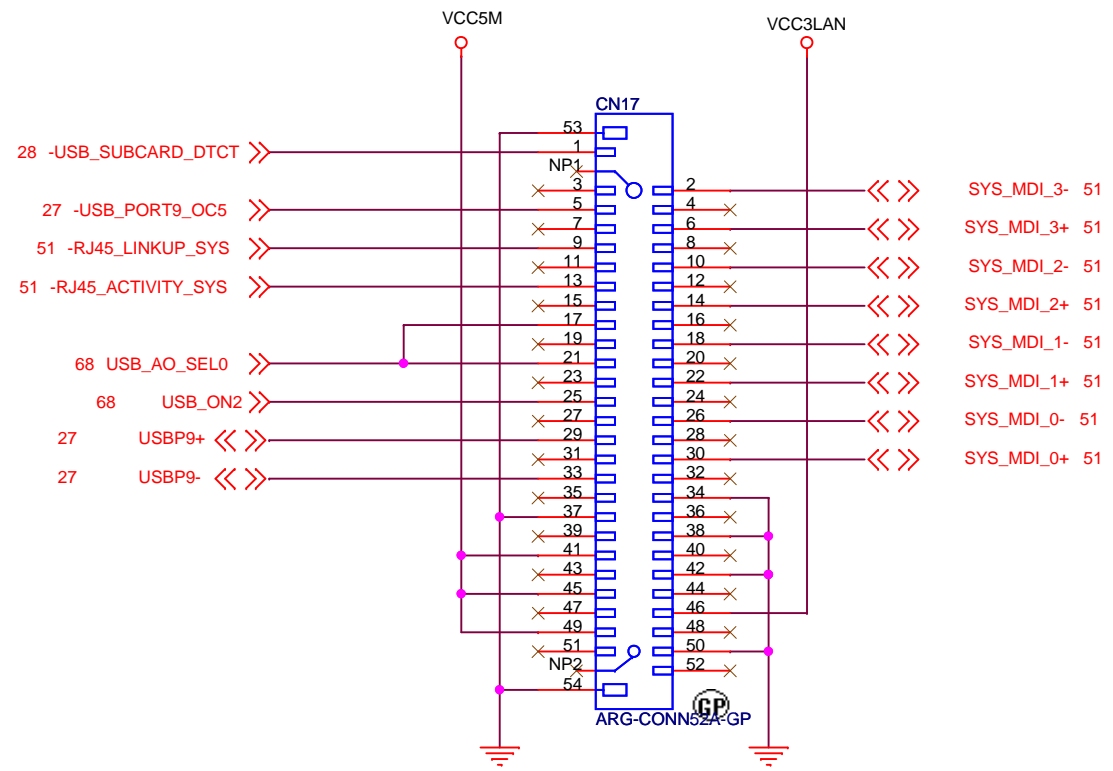


BOM		
<b>緯創資通 Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>PTH FOR SCREW HOLES</b>		
Size A3	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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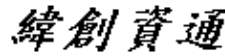


Temporary SW

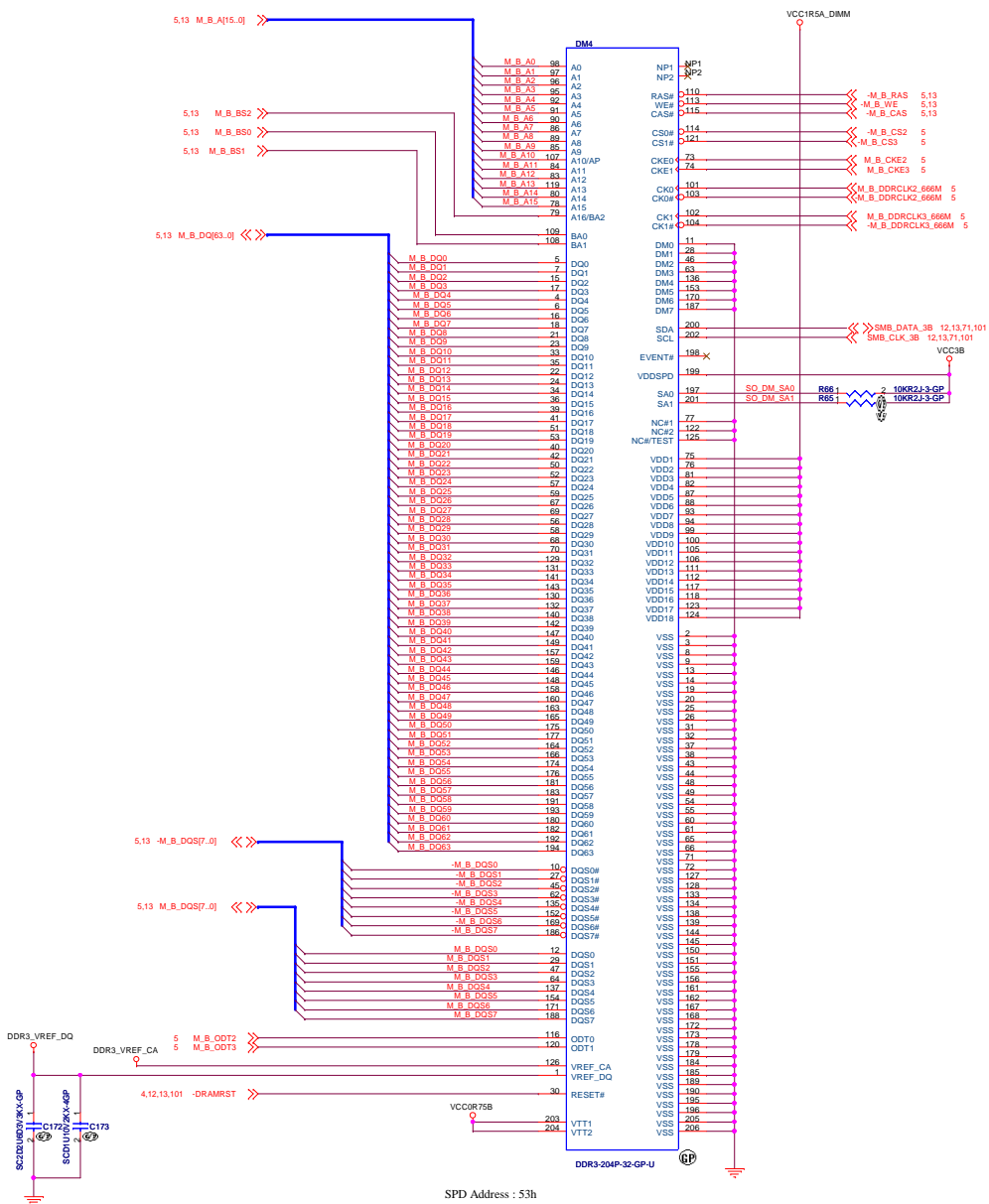
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 <b>Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		Rev
Title <b>GFX Block Diagram</b>		
Size A3	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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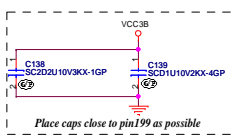
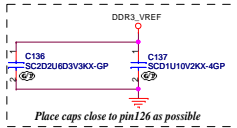
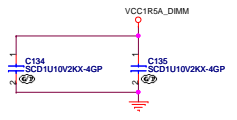
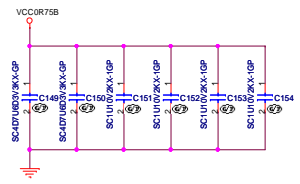
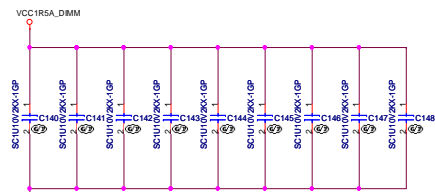
BOM

 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>USB BOARD CONN</b>		
Size A4	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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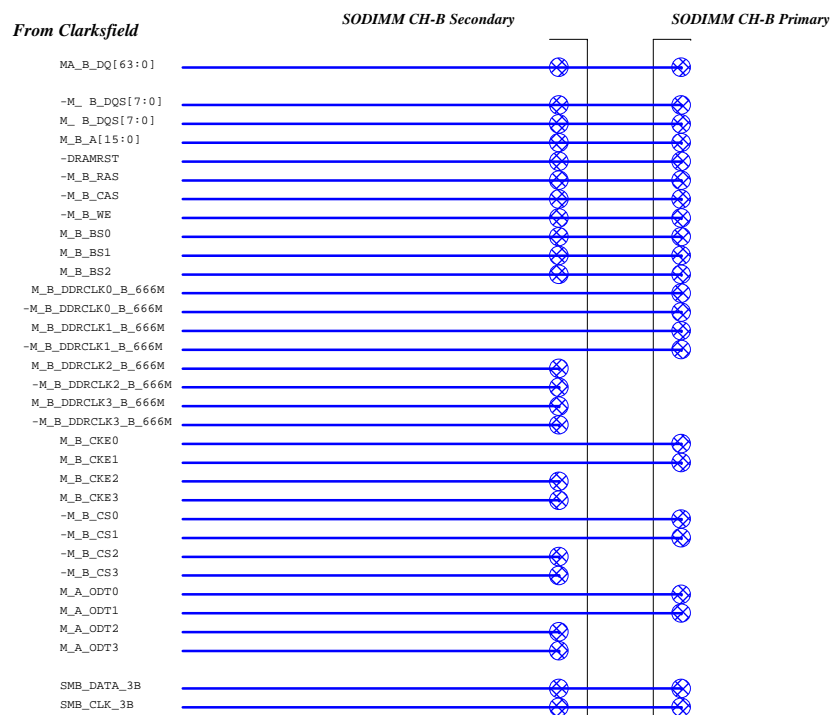
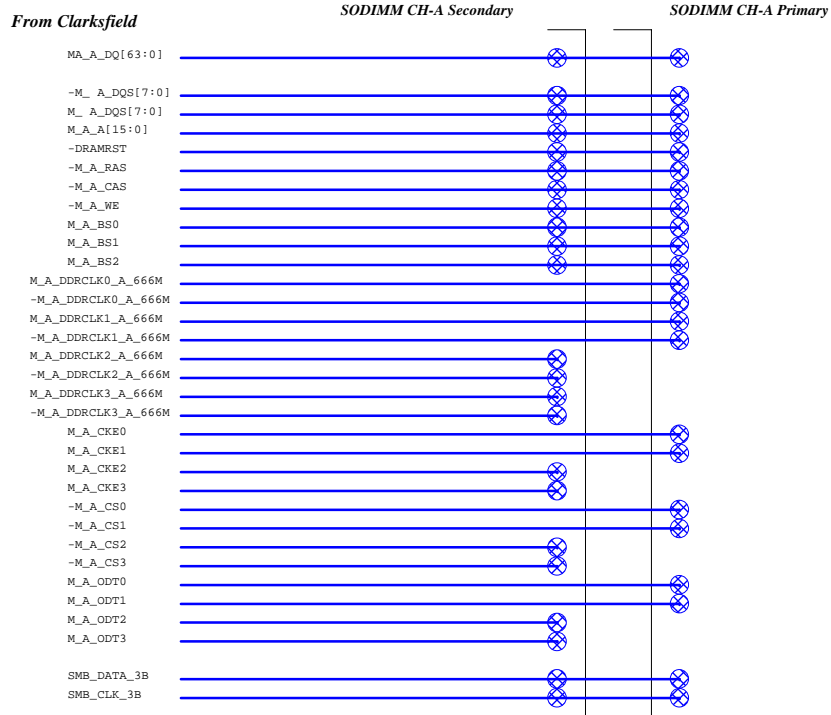




SPD Address : 53h  
 This connector should be placed on near side from CPU.

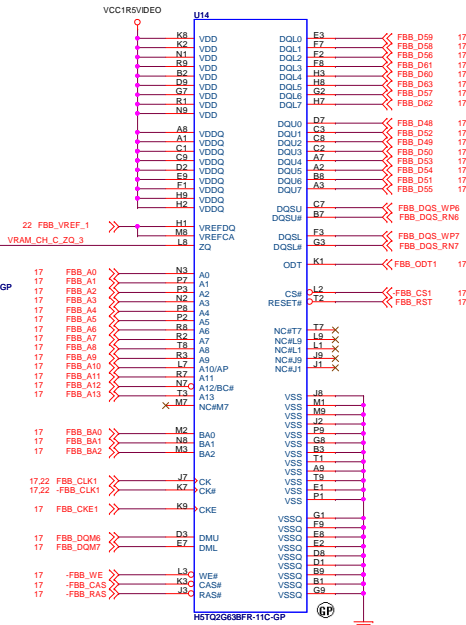
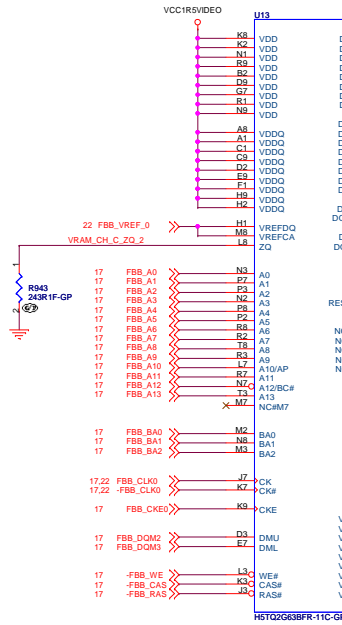
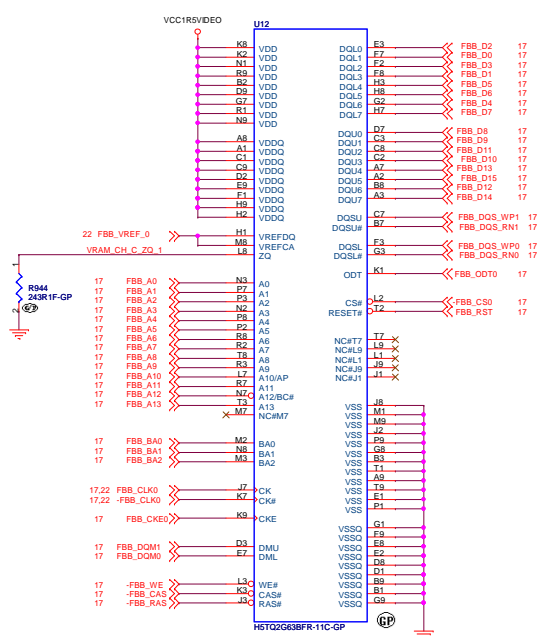


**SODIMM should be installed on CH0 Primary at first.**



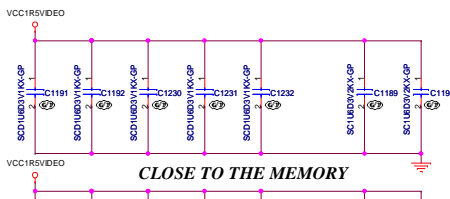
**SODIMM IIC Address :**  
**CH-A Primary : 50h**  
**CH-B Primary : 51h**  
**CH-A Secondary : 52h**  
**CH-B Secondary : 53h**

**Pin1 on SODIMM connector (VREF\_DQ) only connects to DDR Voltage divider.**  
**Clarksfield H17/J17 is left.**



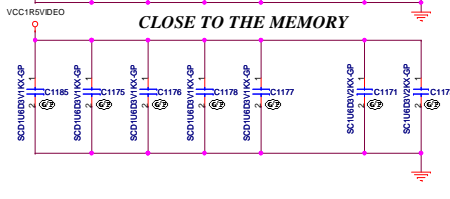
DG requires 4x0.1uF and 8x1.0uF per VRAM chip

FOR U12



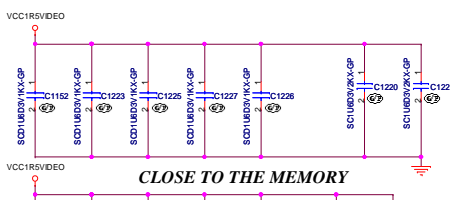
CLOSE TO THE MEMORY

FOR U13



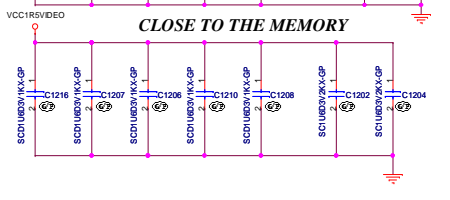
CLOSE TO THE MEMORY

FOR U14

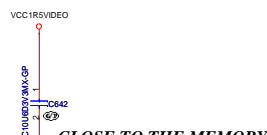


CLOSE TO THE MEMORY

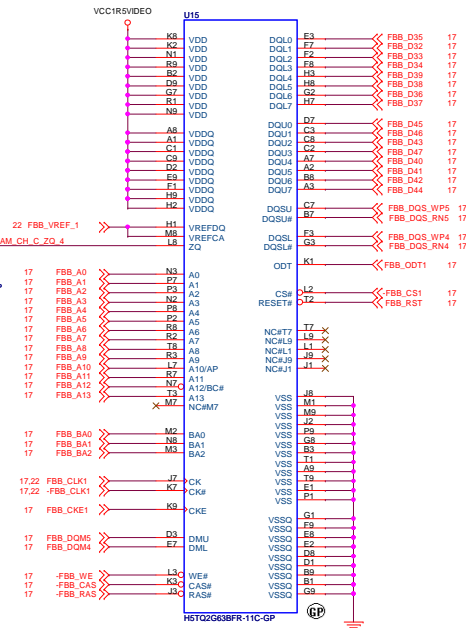
FOR U15



CLOSE TO THE MEMORY



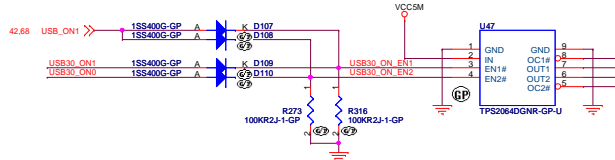
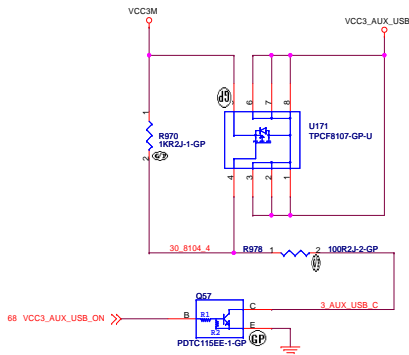
CLOSE TO THE MEMORY



VIDEO FRAME BUFFER PORT C

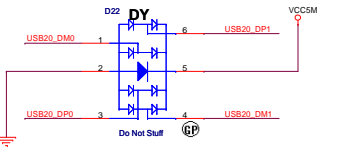


0.6A

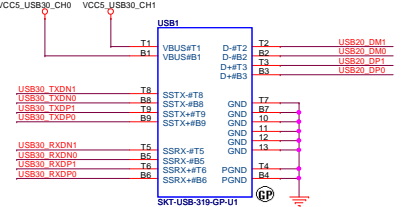


**2CH USB Power Switch w/o Output Discharge Function**

U47	Supplier	Vendo P/N	WISTRON P/N
	TI	TPS2064GNGR-GP	41R0511BA



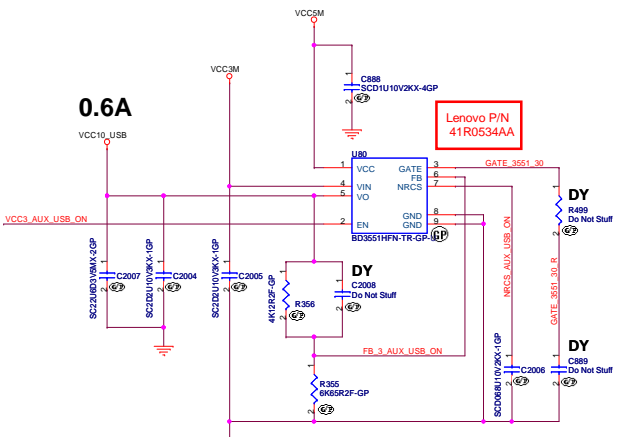
**USB3.0 CONNECTOR**



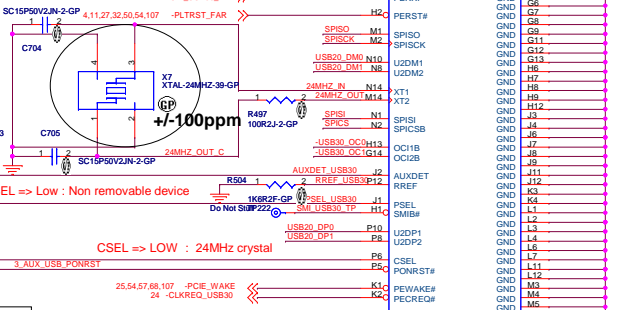
Supplier	Vendo P/N	WISTRON P/N
1	AMIC A25L512V-F TSSOP 8P	72.25512.00Q
2	MXIC MX25L512V1E0C-20G TSSOP 8P	72.25512.F09
3	CHINGIS Pm25LD512C-2CE TSSOP 8P	72.25512.E09

USE 6AK EEPROM

0.6A



If Wakeup function from D3 cold is required, VCC3\_AUX should be applied from system.



CSEL => LOW : 24MHz crystal

ball#	uPD720200	→ uPD720200A
H1	SMIB (Hi-active)	SMI (Hi- active)
P4	GND	SMIB (Low-active)

Supplier	Vendo P/N	WISTRON P/N
1	HARMONY XTAL 24M 30PPM12P HSX321S SMD	82.30023.721
2	HOSONIC XTAL 24M 12P20PPM HCX-3SB SMD	82.30004.551

HARMONY: R497=56 R

NOT MANDATORY TO PLACE.

HELE Recommended Conditions:  
 Normal Frequency: 24MHz.  
 Frequency Tolerance: +/- 30ppm.  
 Load Frequency: 12pF.  
 Effective Series Resistance: 50-ohm.  
 Effective Shunt Capacitance: 2pF.

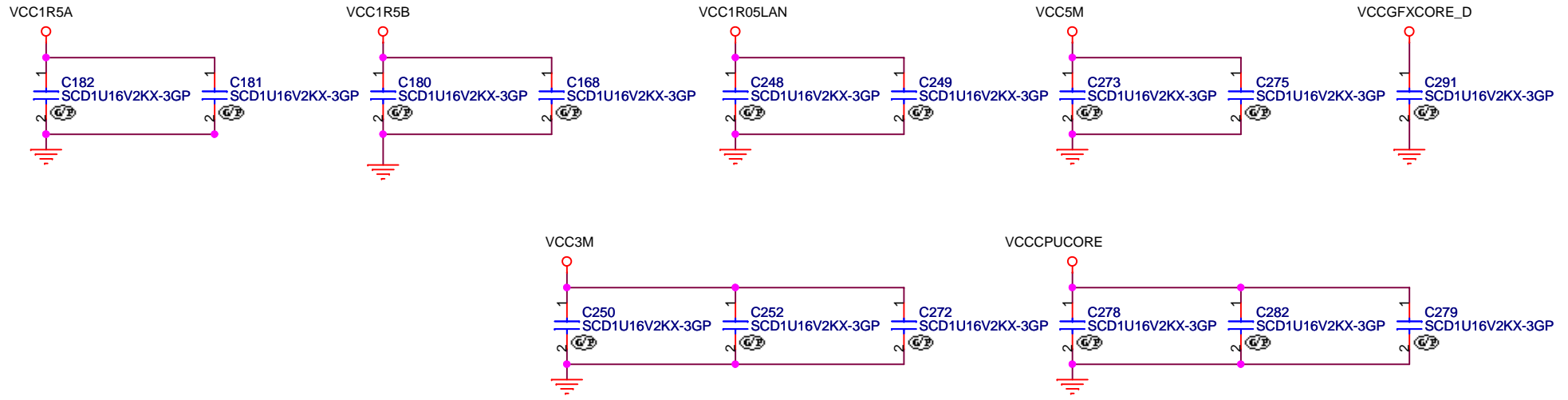
BOM

**緯創資通 Wistron Corporation**  
 21F, 8F, Sec 1, Hsin Tai Wu Rd., Hsichia, Taipei Hsien 221, Taiwan, R.O.C.

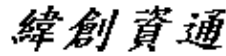
**File**  
**USB 3.0**

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# Long power trace EMI decoupling caps



BOM

 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>EMI DECOUPLING</b>		
Size A4	Document Number <b>Kendo-3 WS</b>	Rev <b>SA</b>
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